SIEMENS

SIMATIC

**S7-300 Programmable Controller
CPU Specifications,
CPUs 31xC and CPU 31x**

Reference Manual

Safety Guidelines

This manual contains notices intended to ensure personal safety, as well as to protect the products and connected equipment against damage. These notices are highlighted by the symbols shown below and graded according to severity by the following texts:

⚠ **Danger**
indicates that death, severe personal injury or substantial property damage will result if proper precautions are not taken.

⚠ **Warning**
indicates that death, severe personal injury or substantial property damage can result if proper precautions are not taken.

⚠ **Caution**
indicates that minor personal injury can result if proper precautions are not taken.

Caution
indicates that property damage can result if proper precautions are not taken.

Note
draws your attention to particularly important information on the product, handling the product, or to a particular part of the documentation.

Qualified Personnel

Only **qualified personnel** should be allowed to install and work on this equipment. Qualified persons are defined as persons who are authorized to commission, to ground and to tag circuits, equipment, and systems in accordance with established safety practices and standards.

Correct Usage

Note the following:

⚠ **Warning**
This device and its components may only be used for the applications described in the catalog or the technical description, and only in connection with devices or components from other manufacturers which have been approved or recommended by Siemens.

This product can only function correctly and safely if it is transported, stored, set up, and installed correctly, and operated and maintained as recommended.

Trademarks

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Excellence in Automation & Drives: Siemens

Contents

Figures

Tables

Purpose of this manual

1

Purpose of this manual

This manual contains all the information you will need concerning the structure, communication functions, memory concept, cycle, response times and the technical data for the CPUs. You will then learn the points to consider when upgrading to one of the CPUs discussed in this manual.

Basic knowledge required

To understand this manual, you will need a general knowledge of automation control engineering. backed up by a knowledge of the STEP 7 basic software. You may find it useful to read the *Programming with STEP 7 V5.1* manual first.

Applicability of this manual

This manual applies to the following CPUs with the following hardware and software versions:

CPU	Convention: In this manual, the CPUs are designated as follows:	Order No.	As of version	
			Firmware	Hardware
CPU 312C	CPU 31xC	6ES7312-5BD01-0AB0	V2.0.0	01
CPU 313C		6ES7313-5BE01-0AB0	V2.0.0	01
CPU 313C-2 PtP		6ES7313-6BE01-0AB0	V2.0.0	01
CPU 313C-2 DP		6ES7313-6CE01-0AB0	V2.0.0	01
CPU 314C-2 PtP		6ES7314-6BF01-0AB0	V2.0.0	01
CPU 314C-2 DP		6ES7314-6CF01-0AB0	V2.0.0	01
CPU 312	CPU 31x	6ES7312-1AD10-0AB0	V2.0.0	01
CPU 314		6ES7314-1AF10-0AB0	V2.0.0	01
CPU 315-2 DP		6ES7315-2AG10-0AB0	V2.0.0	01

Note

This manual contains a description of all the modules available at the time of publishing.

We reserve the right to enclose product information for new modules or modules with more recent versions that contains the latest information about those modules.

Approvals

The SIMATIC S7-300 product series has the following approvals:

- Underwriters Laboratories, Inc.: UL 508 (Industrial Control Equipment)
- Canadian Standards Association: CSA C22.2 No. 142, (Process Control Equipment)
- Factory Mutual Research: Approval Standard Class Number 3611

CE label

The SIMATIC S7-300 product series conforms to the requirements and safety specifications of the following EU Directives:

- EU Directive 73/23/EWE "Low-voltage directive"
- EU Directive 89/336/EEC "EMC directive"

C tick mark

The SIMATIC S7-300 product series is compliant with AS/NZS 2064 (Australia and New Zealand).

Standards

The SIMATIC S7-300 product series conforms to IEC 61131-2.

Its place in the world of documentation

This manual is part of the documentation package for the S7-300.

Read this manual		
Reference Manual ☐ "CPU Data CPU 312 IFM to 318-2 DP" →☐ "CPU Data CPU 31xC and CPU 31x"		Description of the functions, structure and technical data of a CPU
Manual ☐ "CPU 31xC" Technological Functions" ◉ CD-Rom: "Examples"		Description of the individual technological functions: - Positioning - Count - Point-to-point connection - Control The CD contains examples on the technological functions.
Installation Manual ☐ Automation Systeem S7-300: "Installation"		Description of the configuration, installation, wiring and commissioning of a S7-300
Referenzhandbuch ☐ Automation Systems S7-300, M7-300: "Module Data"		Functions descriptions and technical data of signal modules, power supply modules and interface modules.
Instruction lists ☐ "CPU 312 IFM to 318-2 DP" ☐ "CPUs 31xC and CPU 31x"		List of stored instructions of the CPUs and their execution times. List of executable blocks (OBs/SFCs/SFBs) and their execution times.
Getting Started ☐ "CPU 31xC: Positioning with analog output" ☐ "CPU 31xC: Positioning with digital outputs" ☐ "CPU 31xC: Count" ☐ "CPU 31xC: Point-to-point connectioon" ☐ "CPU 31xC: Control" ☐ "CPU 31xC: Commissioning" ☐ "CPU 31x: Commissioning"		Getting Starteds take you through each commissioning step up to a functioning application by using a concrete example.

Figure 1-1   Information environment of the S7-300

You will also require the following manual, in addition to this documentation package:

Reference manual "system software for S7-300/400 system and standard functions"	
☐ Reference manual part of the STEP 7 documentation package with the order the number 6ES7 810-4CA05-8XR0	Description of the SFCs, SFBs and OBs and CPUs. You can also find the description in the STEP 7 Online Help

Figure 1-2 Additional documentation

Recycling and Disposal

The CPU 31xC/ CPU 31x is recycleable due to its non-toxic materials. Please contact a company certified in the disposal of electronic scrap for environmentally safe recycling and disposal of your old device.

Further Support

If you have any technical questions, please get in touch with your Siemens representative or agent responsible.

http://www.siemens.com/automation/partner

Training Centers

Siemens offers a number of training courses to familiarize you with the SIMATIC S7 automation system. Please contact your regional training center or our central training center in D 90327 Nuremberg, Germany for details:

Telephone: +49 (911) 895-3200.

Internet: http://www.sitrain.com

A&D Technical Support

Worldwide, available 24 hours a day:

Figure 1-3   A&D Technical Support

Worldwide (Nuernberg) **Technical Support** 24 hours a day, 365 days a year Phone: +49 (0) 180 5050-222 Fax: +49 (0) 180 5050-223 E-Mail: adsupport@ siemens.com GMT: +1:00		

Europe / Africa (Nuernberg)
Authorization
 	
Local time: Mon.-Fri. 8:00 to 17:00
Phone: +49 (0) 180 5050-222
Fax: +49 (0) 180 5050-223
E-Mail: adsupport@
                  siemens.com
GMT: +1:00
	United States (Johnson City)
	Technical Support and
	Authorization
	
	Local time: Mon.-Fri. 8:00 to 17:00
	Phone: +1 (0) 770 740 3505
	Fax: +1 (0) 770 740 3699
	E-Mail: isd-callcenter@
	                  sea.siemens.com
	GMT: -5:00
		Asia / Australia (Beijing)
		Technical Support and
		Authorization
		
		Local time: Mon.-Fri. 8:30 to 17:30
		Phone: +86 10 64 75 75 75
		Fax: +86 10 64 74 74 74
		E-Mail: adsupport.asia@
		                  siemens.com
		GMT: +8:00

The languages of the SIMATIC Hotlines and the authorization hotline are generally German and English.		

Service & Support on the Internet

In addition to our documentation, we offer our Know-how online on the internet at:

http://www.siemens.com/automation/service&support

where you will find the following:

- The newsletter, which constantly provides you with up-to-date information on your products.

- The right documents via our Search function in Service & Support.

- A forum, where users and experts from all over the world exchange their experiences.

- Your local representative for Automation & Drives via our representatives database.

- Information on field service, repairs, spare parts and more under "Services".

Guide to the S7-300 documentation

2

In this chapter

you will find a guide to the documentation for the S7-300.

Selecting and configuring

Table 2-1 Influence of the ambient conditions on the automation system (AS)

Information on ...	is available in ...
What provisions do I have to make for PLC installation space?	Chapter *Configuring; Mounting dimensions of modules,* and *Mounting; mounting the rail*, in the *Installation Manual*
How do environmental conditions influence the PLC?	*Appendix of the Installation Manual*

Table 2-2 Electrical isolation

Information on ...	is available in ...
Which modules can I use if electrical isolation is required between sensors/actuators?	Chapter *Configuring; Electrical assembly, protective measures and grounding,* in the *Installation Manual*
	Reference Manual *Module Data*
When do I need to isolate the potential of individual components? How do I wire that?	Chapter *Configuring; Electrical assembly, protective measures and grounding,* in the *Installation Manual*
	Chapter *Wiring, in the Installation manual*
When do I need to isolate the potential of specific stations? How do I wire that?	Chapter *Configuring; Configuring a subnet, in the Installation Manual*
	Chapter *Wiring, in the Installation Manual*

Table 2-3   Communication between sensors/actuators and the automation system

Information on ...	is available in ...
Which module is suitable for my sensor/actuator?	for CPU: *CPU Data* Reference Manual for signal modules: *Module Data* Reference Manual
How many sensors/actuators can I connect to the module?	for CPU: *CPU Data* Reference Manual for signal modules: *Module Data* Reference Manual
To connect my sensors/actuators to the PLC, how do I wire the front connector ?	Chapter *Wiring; Wiring front connectors, in the Installation Manual*
When do I require expansion modules (EM), and how are they connected?	Chapter *Configuring, optional expansions and networking, in the Installation Manual*
How do I mount modules in racks / on rails?	Chapter *Mounting; Mounting modules on a rail, in the Installation Manual*

Table 2-4   Use of centralized and decentralized peripherals

Information on ...	is available in ...
Which range of modules do I want to use?	for local I/Os / expansion modules (EMs): *Module Data* Reference Manual for distributed I/Os / PROFIBUS DP: manual of the relevant I/O device, e.g. *Manual ET 200B*

Table 2-5   Configuration consisting of the central processing unit (CPU) and expansion modules (EMs)

Information on ...	is available in ...
Which rack / rail is best suited to my application?	Chapter *Configuring, in the Installation Manual*
Which Interface modules (IM) do I need to connect EMs to the CPU?	Chapter *Configuring, Arranging modules on multiple racks, in the Installation Manual*
What is the right power supply (PS) for my application?	Chapter *Configuring, in the Installation Manual*

Table 2-6   CPU performance

Information on ...	is available in ...
Which memory concept is best suited to my application?	*CPU Data* Reference Manual
How do I insert and remove Micro Memory Cards?	Chapter *Commissioning; Removing/Installing Micro Memory Cards, in the Installation Manual*
Which CPU meets my requirements on performance ?	*Instruction list*, *CPU Data* Reference Manual
How fast is the response / processing time of the CPU?	*CPU Data* Reference Manual
Which technological functions are implemented?	*Technological functions* Manual
How can I use these technological functions?	*Technological functions* Manual

Table 2-7   Communication

Information on ...	is available in ...
Which principles do I have to take into account?	*Communication with SIMATIC* manual
Which options and resources are available on the CPU ?	*CPU Data* Reference Manual
How do I optimize communication with the help of communication processors (CPs)?	the relevant manual
Which type of communication network is best suited to my application?	Chapter *Configuring; Configuring a subnet, in the Installation Manual* *Communication with SIMATIC* Manual
How do I network the individual components?	Chapter *Configuring* and *wiring, in the Installation Manual*

Table 2-8   Software

Information on ...	is available in ...
Which software do I require for my S7-300 system?	Chapter *Technical Data*; *CPU Data* Reference Manual

Table 2-9   Supplementary features

Information on ...	is available in ...
How do I implement operator control and monitoring? (Human Machine Interface)	for text-based display units: the relevant device manual for OPs: the relevant device manual for WinCC: the relevant device manual
How can I integrate process control modules?	for PCS 7: the relevant device manual
What options are offered by redundant and fail-safe systems?	*S7-400H - Redundant Systems* manual; Manual *Fail-safe Systems*

Structure and communication functions

3

3.1   Operator control and display elements

CPU elements

The figure below shows the operator control and display elements of a CPU. Arrangement and number of elements may be different for some CPUs.

For example, the CPUs 312, 314 and 315-2 DP do not have integrated I/Os.

Card slot for

Displays status and error

Micro Memory Card (MMC)

Ejector for MMC

Mode selector

2 Interface
(PtP or DP interface)

Multipoint MPI interface

Power supply port

Outputs and inputs connector terminals (only CPU 31xC)

SF
BF
DC5V
FRCE
RUN
STOP

RUN
STOP
MRES

SIEMENS
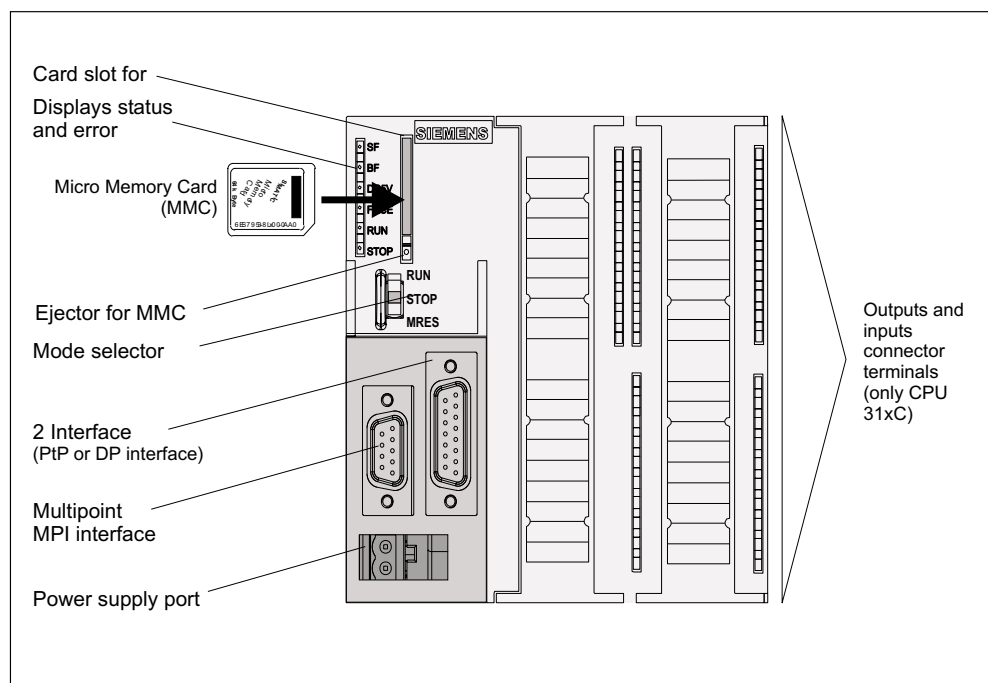
Figure 3-1   Elements and structure of a CPU (e.g. a CPU 314C-2 PtP)

The following picture illustrates the integrated digital and analog I/Os on a CPU 31xC with the front panels open. X1 and X2 are the front connectors on your CPU.
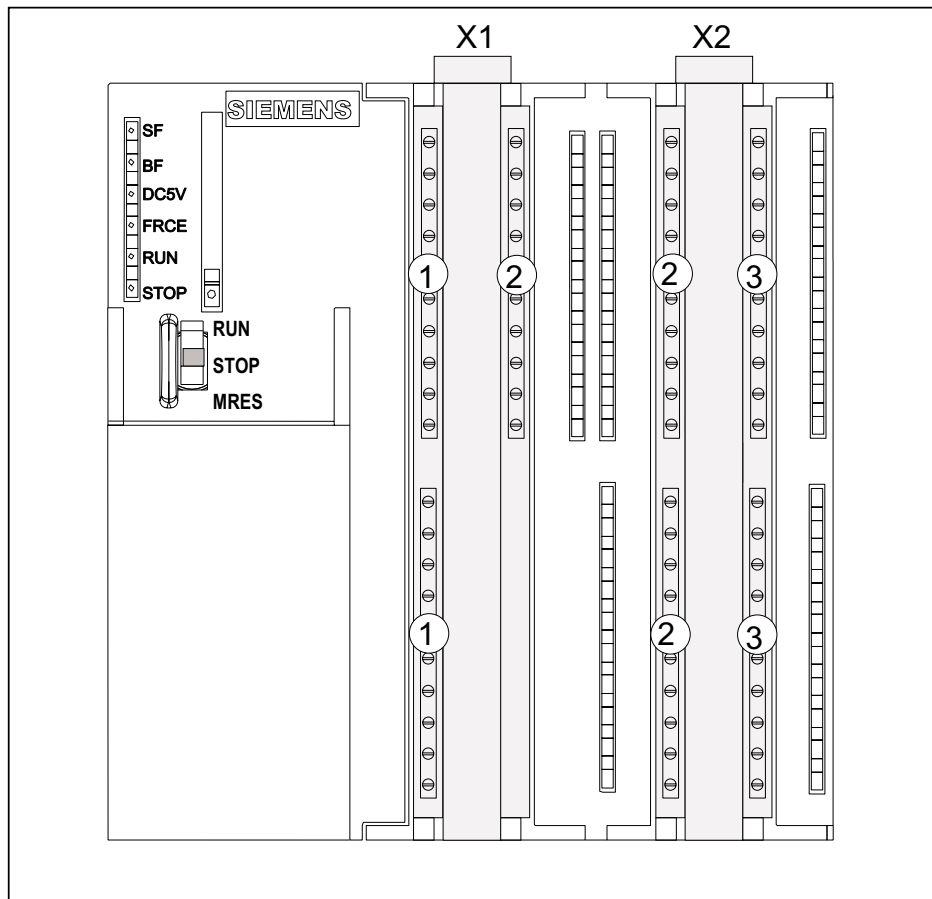
Figure 3-2   Integrated I/Os on the CPU 31xC (e.g. a CPU 314C-2 PtP)

The diagram illustrates under number	The following integrated I/Os
1	Analog inputs and analog outputs
2	8 digital inputs
3	8 digital outputs

Differences between the CPUs

Table 3-1   Differences between the CPUs 31xC and 31x

Element	CPU 312	CPU 312C	CPU 313C	CPU 313C-2 DP	CPU 313C-2 PtP	CPU 314	CPU 314C-2 DP	CPU 314C-2 PtP	CPU 315-2 DP
SIMATIC Micro Memory Card (always required for operation)	X	x	x	x	x	x	x	x	x
9-pin MPI interface	X	x	x	x	x	x	x	x	x
9-pin DP interface	–	–	–	x	–	–	x	–	x
15-pin PtP interface	–	–	–	–	x	–	–	x	–
Digital inputs	–	10	24	16	16	–	24	24	–
Digital outputs	–	6	16	16	16	–	16	16	–
Analog inputs	–	–	4 + 1	–	–	–	4 + 1	4 + 1	–
Analog outputs	–	–	2	–	–	–	2	2	–
Technological functions	–	2 counters	3 counters	3 counters	3 counters	–	4 counters 1 channel for positioning	4 counters 1 channel for positioning	–

Status and error displays

The CPU is equipped with following LED displays:

CPU LEDs:

SF   (red)   Hardware or software error
BF   (red)   Bus error (only CPUs with DP interface)
DC5V (green)   The 5 V power supply for the CPU and S7-300 bus is ok.
FRCE (yellow) Force job is active.
RUN   (green)   CPU in RUN; LED flashes during startup with with 2 Hz; in HOLD with 0.5 Hz.
STOP (yellow)   CPU is in STOP or HOLD or startup;
                         LED flashes during memory reset with 0.5 Hz, during memory reset with 2 Hz.

Figure 3-3   Status and error displays

Diagnostics

How you can use the LED displays for diagnostics is explained in the, *Testing functions, Diagnostics and fault elimination* chapter of the Installation Manual.

Slot for the SIMATIC Micro Memory Card (MMC)

A SIMATIC micro memory card (MMC) is used as the memory module. The MMC can be used as load memory and as portable storage medium.

Note

These CPUs do not have an integrated load memory, so an MMC MUST be inserted in order to use the CPU.

Mode selector switch

You can use the mode selector switch to set the current CPU operating mode.

The mode selector switch is a 3-position toggle switch.

Positions of the mode selector switch

The positions of the mode selector are explained in the order in which they appear on the CPU.

Table 3-2   Positions of the mode selector switch

Position	Meaning	Description
RUN	RUN mode	The CPU executes the user program.
STOP	STOP mode	The CPU does not execute a user program.
MRES	Memory reset	Mode selector switch position with momentary pushbutton function for CPU memory reset. Memory reset requires a specific sequence of operation (refer to the Installation Manual, Chapter *Commissioning*).

Power supply connector

CPU 31xC and CPU 31x series are equipped with a 2-pin power supply socket. When the CPU is supplied, the connector with screw terminals is already plugged into this socket.

Further information

Further information on CPU operating modes is found in the *STEP 7 Online Help*. For information on how to reset CPU memory using the mode selector switch, please refer to the Installation manual, Chapter *Commissioning*. Details on how to evaluate the LED display in the event of errors/diagnostics are found in your Installation Manual, Chapter *Testing functions, Diagnostics and fault elimination*.

The *Memory concept* chapter contains information on using the MMCs and about the memory concept

3.2   SIMATIC Micro Memory Card (MMC)

Memory module

These CPUs have a SIMATIC micro memory card (MMC) as their memory module. You can use MMCs as load memory or as a portable storage medium.

Note

An MMC must be plugged in before you can use the CPU.

Following data is stored on the MMC:

- User programs (all blocks)

- Archives and recipes

- Configuration data (STEP 7 projects)

- Data for an operating system update and backup

Note

On **one** MMC you can **either** store user and configuration data **or** the operating system.

Cross-reference

Your MMC has an internal serial number that provides copy protection for the MMC at the user level. You can read this serial number via the SZL partial list 011C$_H$ index 8 using SFC 51 "RDSYSST".

You can then program a STOP command, for example, in a copy-protected block if the expected and actual serial numbers of your MCC do not tally.

Further information can be found in the *SZL partial list in the list of operations* or the *System and Standard Functions* manual.

Properties

SIMATIC Micro Memory Cards ensure maintenance-free and retentive operation of these CPUs. Details are found in Chapter *Memory concept*.

> **Caution**
>
> Data on a SIMATIC Micro Memory Card can be corrupted if you remove the card while the it is being accessed by a write operation. In this case, you may have to delete the MMC on your PG or format the card in the CPU.
>
> Never remove an MMC in RUN mode. Always remove when power is off or when the CPU is in STOP state and when the PG is not writing to the card. When the CPU is in STOP mode and you cannot determine whether or not a PG is writing to a card (e.g. load/delete block), disconnect the communication lines.

Useful life of an MMC

The useful life of an MMC depends mainly on following criteria:

1. The number of delete or programming operations,

2. External influences, e.g ambient temperature.

The useful life of an MMC is 10 years, at an ambient temperature of up to 60 degC and a maximum of 100,000 delete/write operations.

> **Caution**
>
> As a precaution against data loss, always make sure that the maximum number of delete/write operations is not exceeded.

Plug-in SIMATIC Micro Memory Cards

The following memory modules are available:

Table 3-3   Available MMCs

Type	Order numbers	Required for a firmware update with ...
MMC 64k	6ES7 953–8LF00–0AA0	–
MMC 128k	6ES7 953–8LG00–0AA0	–
MMC 512k	6ES7 953–8LJ00–0AA0	–
MMC 2M	6ES7 953–8LL00–0AA0	CPUs without a DP interface
MMC 4M	6ES7 953–8LM00–0AA0	CPUs with a DP interface
MMC 8M	6ES7 953–8LP10–0AA0	–

Formatting MMC when resetting memory

You must format the MMC in the following special situations:

- The MMC module type is not a user module
- The MMC has not yet been formatted
- The MMC is defective
- The content of the MMC is invalid

The content of the MMC is marked invalid

- The *Load user program* operation was interrupted as a result of Power Off.
- The *Write RAM to ROM* operation was interrupted as a result of Power Off.
- Module memory evaluation error during memory reset.
- Formatting error or formatting could not be carried out.

If one of these errors has occurred, the CPU prompts you to repeat memory reset, regardless of a previous memory reset. The card's content is retained until the MMC is formatted unless the Load user program/Write RAM to ROM operation was interrupted as a result of Power Off.

Follow the steps below to format your MMC:

If the CPU is requesting a memory reset (STOP LED flashing slowly), you can format the MMC by setting the selector switch as follows:

1. Toggle the switch to the MRES position and hold it there until the STOP LED lights up and remains on (after approx. 9 seconds).

2. Within the next three seconds, release the switch and toggle it once again to MRES position. The STOP LED flashes to indicate that formatting is in progress.

Always perform this sequence of operation within the specified time. Otherwise, the MMC will not be not formatted, but rather returns to memory reset status.

Do not format the MMC unless you have specific reasons to do so (see above); for instance, do not format the card if the CPU requests memory reset after you have replaced a module, because switching to MRES merely initiates a normal memory reset, while existing module data is retained.

Further details on MMCs ...

are found in the Installation Manual.

3.3   Interfaces

MPI interface

Availability: In all the CPUs described in this document.

MPI (Multipoint Interface) represents the interface between the CPU and a PG/OP or for communication in an MPI Subnet.

The typical (default) transmission rate is 187.5 Kbps. You can also specify 19.2 Kbps for communication with an S7-200. Other transmission rates are not possible. The CPU automatically broadcasts its bus parameter configuration (e.g. transmission rate) via MPI interface. A programming device, for example, can then automatically retrieve the correct parameters and connect to an MPI Subnet.

Note

In RUN mode, you may only connect PGs to the MPI Subnet.
Other stations (e.g. OP, TP, ...) should not be connected to the MPI subnet while the PLC is in RUN mode. Otherwise, transferred data might be corrupted due to interference or global data packages may be lost.

PROFIBUS DP interface

Availability: CPU types with the identifier "DP" (used as a DP master)

The PROFIBUS DP interface is mainly used to connect distributed I/Os. PROFIBUS DP allows you to create large, extended subnets, for example. The PROFIBUS DP interface can be configured as either master or slave, and offers a transmission speed of up to 12 Mbps. The CPU sends its bus parameters (e.g. the baud rate) to the PROFIBUS DP interface (if it is used as the master). A programming device, for example, can then automatically retrieve the correct parameters and connect to a PROFIBUS subnet. In your configuration, you can disable this bus parameter broadcast.

Note

(For the DP interface in slave mode).

If you have disabled the Commissioning / Test mode check box in the DP interface properties in STEP 7, the baud rate you have set will be ignored, and the master's baud rate will be used automatically,

---

Cross-reference

For information on the new DPV1 functionality, see the section with the same name in the *CPU Data Reference Manual, CPU 31xC and CPU 31x*.

PtP interface

Availability: CPU types with the identifier "PtP".

You can use the PtP (Point to Point) interface on your CPU to connect external devices such as a barcode reader, printer, etc. to a serial port. Baud rates of up to 19.2 Kbps for full duplex (RS 422) and up to 38.4 Kbps for half duplex (RS 485) are possible. The following PtP communication drivers are installed in the CPUs:

- ASCII driver
- 3964 (R) protocol
- RK512 (only CPU 314C-2 PtP)

Which devices can I connect to which interface?

Table 3-4   The following devices may be connected

MPI	PROFIBUS DP	PtP
- PG/PC - OP/TP - S7-300/400 with MPI interface - S7-200 (19.2 Kbps only)	- PG/PC - OP/TP - DP slaves - DP master - Actuators/Sensors - S7-300/400 with PROFIBUS DP interface	Devices equipped with a serial port, e.g. barcode readers, printers, etc.

Further Information

Further information on specific connections can be found in the *Communication with SIMATIC* manual.

Details on PtP communication are also found in the *Technological Functions* manual.

3.4 What do we mean by DPV1?

New automation and process engineering tasks require the range of functions performed by the existing DP protocol to be extended. In addition to cyclical communication functions, acyclical access to non-S7 field devices is another important requirement of our customers, and was implemented in the standard EN 50170. In the past, acyclical access was only possible with S7 slaves.

Definition

The designation DPV1 means extension of the functionality of the acyclical services (to include new interrupts, for example) provided by the DP protocol.

The distributed I/O standard EN 50170 has been further developed. All the changes concerning new DPV1 functions are included in IEC 61158/ EN 50170, volume 2, PROFIBUS.

Extended functions of DPV1

- Use of any DP1 slaves from external vendors (in addition to the existing DPV0 and S7 slaves, of course).

- Selective handling of DPV1-specific interrupt events by new interrupt blocks.

- Reading/writing SFBs that conform to standards to the dataset (although this can only be used for centralized modules).

- User-friendly SFB for reading diagnostics.

DP master/slave with DPV1 functionality

Table 3-5   CPUs (as the DP master) with new DPV1 functionality

CPU	Order No.	As of version	
		Firmware	**Hardware**
CPU 313C-2 DP	6ES7313-6CE01-0AB0	V2.0.0 or later	01
CPU 314C-2 DP	6ES7314-6CF01-0AB0	V2.0.0 or later	01
CPU 315-2 DP	6ES7315-2AG10-0AB0	V2.0.0 or later	01

Note

If you want to use the CPU as an intelligent slave, remember that it does not have DPV1 functionality.

Requirement for using the DPV1 functionality with DP slaves

For DPV1 slaves from other vendors, you will need a GSD file conforming to EN 50170, revision 3 or later.

Interrupt blocks that support the DPV1 functionality.

Table 3-6   Interrupt blocks with DPV1 functionality

OB	Functionality
OB 82	Diagnostic interrupt
OB 40	Process interrupt
OB 55	Status interrupt
OB 56	Update interrupt
OB 57	Vendor-specific interrupt

Note

You can now also use organizational blocks OB82 and OB40 for DPV1 interrupts.

System function blocks that support the DPV1 functionality.

Table 3-7   System function blocks with DPV1 functionality

SFB	Functionality
SFB 52	Read dataset from DP slave or centralized module
SFB 53	Write dataset to DP slave or centralized module
SFB 54	Read additional alarm information from a DP slave or a centralized module in the relevant OB.
SFB 75	Set any interrupts for intelligent slaves

Note

You can also use SFB 52 to SFB 54 for centralized I/O modules.

Further information on the DPV1 functionality

In this context, you should also note the *Information on upgrading to a CPU 31xC, 312, 314, 315-2 DP.* Read the chapter with the same title in the *CPU Data Reference Manual, 31xC and 31x.*

Cross-reference

You will find further information on the blocks mentioned above in the *System software for S7-300/400* Reference Manual*: System and Standard Software,* or directly in the *STEP7 Online Help.*

3.5   Realtime clock

Properties and functions

The table below shows the properties and functions of the real-time clock.

Table 3-8   Properties and functions of the real-time clock

Characteristics	CPU 312C, CPU 312	CPU 313C / CPU 313C-2 / CPU 314C-2, 314, 315-2
Type	Software clock	Hardware clock
Factory setting	DT#1994-01-01-00:00:00	DT#1994-01-01-00:00:00
Buffering	No	with integrated capacitor
Buffered period	–	Typically 6 weeks (at an ambient temperature of 40 degC)
Behavior of the realtime clock after POWER ON	The clock keeps running, continuing with the time it had when the power was switched off.	The clock continues running after the POWER OFF.
Behavior of the clock on expiration of the buffered period	–	The clock keeps running, continuing at the time-of-day it had when power was switched off.

Information on ...

- Synchronization and correction factor: When you configure the CPU parameters in *STEP 7*, you can also configure functions such as synchronization via MPI interface and the correction factor. Refer to the *STEP 7 Online Help.*

- Setting, reading and programming the real-time clock: You can read and set the real-time clock with your PG (refer to the *Programming with STEP 7* manual). You can program the real-time clock with respective SFCs in your user program (refer to the *System and Standard Functions*) Reference Manual.

3.6 S7 Connections

Introduction

An S7 connection is established when S7 modules communicate with one another. This represents the communication path.

Note

Global data communications and PtP communications do not require an S7 connection.

Every communication link requires S7 connection resources on the CPU for the entire duration of each link.

Thus, every S7 CPU provides a specific number of S7 connection resources. These are used by various communication services (PG/OP communication, S7 communication or S7 basic communication).

What are S7 connection points?

An S7 connection between modules with communication capability is established between connection points. The S7 connection always has two connection points: the active and the passive connection point:

- The active connection point is assigned to the module that establishes the S7 connection.

- The passive connection point is assigned to the module that accepts the S7 connection.

Any module that is capable of communication can thus act as an S7 connection point. At the connection point, the established communication link always uses **one** S7 connection of the module concerned.

Transition point of an S7 connection

If you use the routing functionality, the S7 connection between two modules capable of communication is established across a number of subnets. These subnets are interconnected via a network transition. The module that implements this network transition is known as a router. The router is thus the point through which an S7 connection passes.

Any CPU 31xC-2 DP and CPU 315-2 DP can be the router for an S7 connection. It can establish up to four routed connections, without restricting the equipment required for the S7 connections.

Allocating S7 connections

There are several ways to allocate S7 connections on a communication-capable module:

Reservation when programming

- On a CPU inserted during hardware configuration, *STEP 7* automatically reserves one S7 connection per PG and OP communication.

- In *STEP 7* you can reserve S7 connections for PG / OP / S7-based communication.

Allocating connections via programming

S7-based communication is established by the user program. The CPU's operating system initiates the connection and allocates the respective S7 connection.

Allocating connections during commissioning, testing and diagnostics routines

An online function of the engineering station (PG/PC with *STEP 7*) allocates S7 connection resources for PG communication:

- An S7 connection resource for PG communication which was reserved in your CPU hardware configuration is assigned to the engineering station, that is, it only needs to be allocated.

- If all reserved S7 connection resources for PG communication are occupied, the operating system assigns a free S7 connection resource which has not yet been reserved. If no more connection resources are available, the engineering station cannot go online to the CPU.

Allocating connection resources to O&M services

An online function of the O&M station (OP/TP/... with *ProTool*) allocates S7 connection resources for OP communication:

- An S7 connection resource for OP communication you have reserved in your CPU hardware configuration is therefore assigned to the O&M station engineering station, that is, it only needs to be allocated.

- If all reserved S7 connection resources for OP communication have been allocated, the operating system assigns a free S7 connection resource. If no more connection resources are available, the O&M station cannot go online to the CPU.

Time sequence for the allocation of S7 connection resources

Parameter assignment blocks are generated during configuration in *STEP 7*. They are called on start-up of the module. Here, the module's operating system reserves or allocates the respective S7 connection resources. This means, for instance, that OPs cannot access a reserved S7 connection resource for PG communication.

The module's S7 connection resources which were not reserved (CPU) can be used freely. These S7 connection resources are allocated in the order they are requested.

Example:

If there is only one free S7 connection left on the CPU, you can still connect a PG to the bus. The PG can then communicate with the CPU. The S7 connection is only used, however, when the PG is communicating with the CPU.

If you attach an OP to the bus while the PG is not communicating, the OP can establish a connection to the CPU. Since an OP maintains its communication link at all times, in contrast to the PG, you cannot then establish another connection via the PG.

Distribution of S7 connection resources

The following table illustrates how the S7 connection resources of CPUs are distributed:

Table 3-9   Distribution of S7 connection resources

Communication service	Distribution
PG communication OP communication S7-based communication	In order to avoid allocation of connection resources being dependent only on the chronological sequence in which various communication services are requested, S7 connection resources can be reserved for these services. For PD and OP communication respectively, at least one S7 connection resource is reserved by default. In the table below, and in the technical data of the CPUs, you can find the configurable S7 connection resources and the default configuration for each CPU. You can "redistribute" the S7 connection resources in *STEP 7*, when you configure the CPU parameters.
S7 communication Other communication resources (e.g. via CP 343-1, with a data length of > 240 bytes)	Here you allocate S7 connection resources which are still available and not reserved for a specific service (PG/OP communication, S7-based communication.
Routing PG functions (CPU 31xC-2 DP and CPU 315-2 DP only)	The CPUs provide four connection resources for the routing of PG functions. These connection resources are available in addition to S7 connection resources.
Global data communication PtP communication	These communication services do **not** use S7 connection resources.

Availability of S7 connection resources

The table below shows S7 connection resources available on specific CPUs.

Table 3-10   Availability of S7 connection resources

Parameters	CPU 312C	CPU 313C CPU 313C-2 DP/PtP	CPU 314C-2 DP/PtP	CPU 312	CPU 314	CPU 315-2 DP
Total number of S7 connection resources	6	8	12	6	12	16
• reserved for PG communication	1 to 5 Default: 1	1 to 7 Default: 1	1 to 11 Default: 1	1 to 5 Default: 1	1 to 11 Default: 1	1 to 15 Default: 1
• reserved for OP communication	1 to 5 Default: 1	1 to 7 Default: 1	1 to 11 Default: 1	1 to 5 Default: 1	1 to 11 Default: 1	1 to 15 Default: 1
• reserved for S7-based communication	0 to 2 Default: 2	0 to 4 Default: 4	0 to 8 Default: 8	0 to 2 Default: 2	0 to 8 Default: 8	0 to 12 Default: 12
• Free S7 connection resources	Displays S7 connection resources which are not reserved as free connection resources.					

Example of a CPU 314C-2 DP

The CPU 314C-2 DP provides 12 S7 connection resources:

- Reserve two S7 connection resources for PG communication.

- Reserve three S7 connection resources for OP communication.

- Reserve one S7 connection resource for S7-based communication.

This leaves six S7 connection resources available for any communication service, e.g. S7 communication, OP communication etc.

Details ...

- on SFCs are found in the *Instruction list*, for more details refer to the *STEP 7 Online Help* or to the *System and Standard Functions* Reference Manual.

- on communication are found in the Manual *Communication with SIMATIC.*

- on routing can be found in the Routing chapter and in the *STEP 7 Online Help.*

3.7   Communications

Communication services of the CPUs

Which communication service you select will depend on the functionality you want to use in your particular circumstances.

Your choice of communication service will have no effect on

- the functionality to be provided,
- whether an S7 connection is required, or
- when the connection is established.

The user interface can vary considerably (SFC, SFB, ...), and also depends on the hardware used (SIMATIC CPU, PC, ...).

The following table summarizes the communication services provided by the CPUs.

Table 3-11   Communication services provided by CPUs

Communication service	Functionality	Time at which the S7 connection is established ...	via MPI	via DP	via PtP
PG communication	Start-up, test, diagnostics	via PG when the service is being used	x	x	–
OP communication	Operator control and monitoring	via OP at POWER ON	x	x	–
S7-based communication	Data exchange	is programmed via blocks (SFC parameters)	x	–	–
S7 communication	Data exchange	Only as a server; the connection is established by the communication partner	x	x	–
Global data communication	Cyclic data exchange (e.g. flag bits)	does not require an S7 connection	x	–	–
Routing PG functions (CPU 31xC-2 DP and CPU 315-2 DP only)	e.g. testing, diagnostics extending over network limits	via PG when the service is being used	x	x	–
PtP communication	Data exchange via serial interface	does not require an S7 connection	–	–	x

PG communication

PG communication is used to exchange data between engineering stations (e.g. PG, PC) and SIMATIC modules that are capable of communication. This service is possible via MPI / PROFIBUS / industrial Ethernet subnets. Transition between subnets is also supported.

PG communication provides the functions needed to download/upload programs and configuration data, and to run tests and evaluate diagnostic information. These functions are integrated in the operating system of SIMATIC S7 modules.

A CPU can maintain several simultaneous online connections to one or multiple PGs.

OP communication

OP communication is used to exchange data between operator stations (e.g. OP, TP) and communication-capable SIMATIC modules. This service is possible via MPI / PROFIBUS / industrial Ethernet subnets.

OP communication provides functions required for operator control and monitoring. These functions are integrated in the operating system of SIMATIC S7 modules.

A CPU can maintain several simultaneous connections to one or several OPs.

S7-based communication

S7-based communication is used to exchange data between S7 CPUs and the communication-capable SIMATIC modules within an S7 station (acknowledged data exchange). Data exchange takes place via non-configured S7 connections. The service is available via MPI subnet, or in the station to function modules (FM).

S7-based communication provides functions required for data exchange. These functions are integrated into the CPU operating system.

The user can utilize this service via "System function" (SFC) user interface.

S7 Communication

The CPUs as the server in S7 communication. A connection is always established by the communication partner. This service is possible via MPI / PROFIBUS / industrial Ethernet subnets.

The operating system processes these services without explicit user interface.

Note

S7 communication as a client can be implemented using CPs and loadable FBs.

Global data communication

Global data communication is used for cyclic exchange of global data (e.g. I, Q, M) between SIMATIC S7 CPUs (data exchange with no acknowledgement). One CPU broadcasts the data to all other CPUs on the MPI subnet. This function is integrated in the CPU operating system.

Conditions for sending and receiving

For GD circuit communication, the following conditions should always be fulfilled:

- For the station sending a GD packet:
  $\text{Scan rate}_{\text{Sending station}}$ x $\text{Cycle time}_{\text{Sending station}} \geq 60$ ms

- For the station receiving a GD packet:
  $\text{Scan rate}_{\text{Receiving station}}$ x $\text{Cycle time}_{\text{Receiving station}}$
  $< \text{Scan rate}_{\text{Sending station}}$ x $\text{Cycle time}_{\text{Sending station}}$

A GD packet may be lost if you do not maintain these conditions. The reasons being:

- the performance of the "smallest" CPU in the GD circuit

- the sending/receiving stations exchange global data asynchronously

if you specify in *STEP 7*: "Send data after every CPU cycle", and if the CPU has a short cycle time (< 60 ms), the operating system might overwrite the CPU's GD packet before it is sent. Loss of global data is indicated in the status field of the GD circuit, provided you have configured this feature in *STEP 7.*

Scan rate

The scan rate specifies the cycle intervals for GD communication. You can customize this scan rate when you configure global data communication in *STEP 7*. For example, if you select a scan rate of 7, global data is transferred only after every 7th cycle. This reduces CPU load.

GD resources

The table below shows the GD resources of CPUs.

Table 3-12   GD resources of CPUs

Parameters	CPU 31xC, 312, 314	CPU 315-2 DP
Number of GD circuits per CPU	max. 4	max. 8
Number of send GD packets per GD circuit	max. 1	max. 1
Number of send GD packets of all GD circuits	max. 4	max. 8
Number of receive GD packets per GD circuit	max. 1	max. 1
Number of receive GD packets of all GD circuits	max. 4	max. 8
Data length per GD packet	max. 22 bytes	max. 22 bytes
Consistency	max. 22 bytes	max. 22 bytes
Min. scan rate (default)	1 (8)	1 (8)

Routing

With the CPU 313C-2 DP, 314C-2 DP or 315-2 DP configured as the master and *STEP 7* V 5.1 + Service Pack 4 or later, you can use a PG/PC to access S7 stations via various subnets (MPI interface / PROFIBUS DP interface).

You can download user programs or a hardware configuration, or run testing and commissioning functions, for example.

Note

If you use your CPU as an intelligent slave, the routing function can only be used with an actively-configured DP interface.

In the properties of the DP interface in STEP 7, tick the Commissioning / Test mode check box.

You will find further information in the *Programming with STEP 7manual* or in the STEP 7 Online Help.

PtP communication

PtP communication enables data exchange via serial interface. PtP communication can be used to interconnect automation devices, computers or other communication-capable non-Siemens systems. Adaptation to the communication partner's protocol is also possible.

Details ...

- on SFCs are found in the *Instruction list*, for more details refer to the *STEP 7 Online Help* or to the *System and Standard Functions* Reference Manual.

- on communication are found in the Manual *Communication with SIMATIC*.

3.8   Routing

PG/PC access to stations on another subnet

As of *STEP 7* V5.1 + SP 4, PGs/PCs can access S7 stations across subnets boundaries, e.g. to download/upload user programs or hardware configurations, or to perform testing and diagnostics routines.

The Routing function allows you to connect a PG at any point on the network, and to establish a connection to all stations that can be accessed via network transitions.

The CPUs with DP interface provide four connection resources for routing PG functions. These connection resources are available in addition to S7 connection resources.

Note

If you use your CPU as an intelligent slave, the routing function can only be used with an actively configured DP interface.

In the properties of the DP interface in STEP 7, tick the Commissioning / Test mode check box.

You will find further information in the *Programming with STEP 7manual* or in the STEP 7 Online Help.

Network node

Transitions between subnets are routed in a SIMATIC station that is equipped with interfaces for access to the respective subnets. In the illustration below, the CPU 31xC-2 DP acts as the router between subnet 1 and subnet 2.
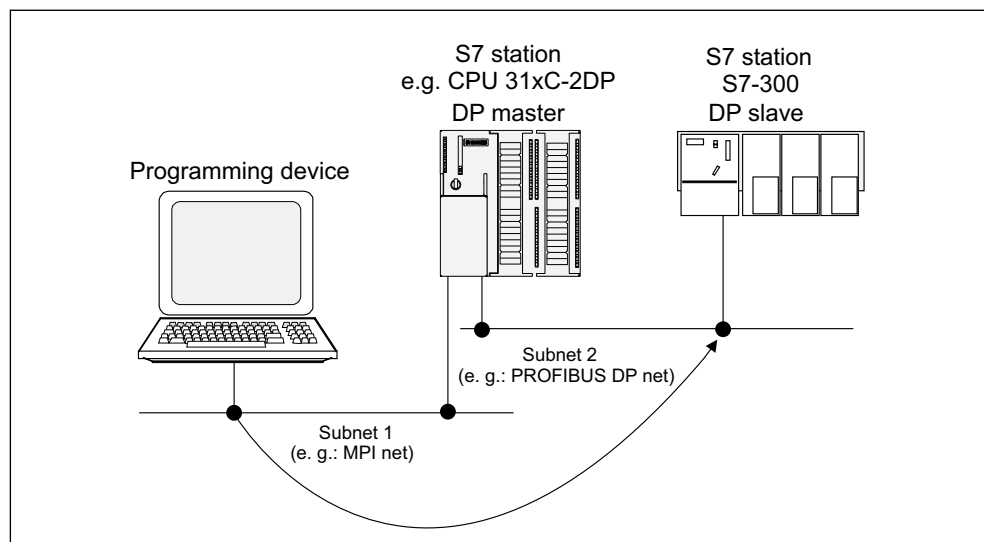
Figure 3-4   Routing - Network node

Requirements

- The station modules must be "routing-compatible" (CPUs or CPs).

- The network configuration does not exceed project limits.

- The modules must have downloaded the configuration data containing the latest "knowledge" of the entire project network configuration.

  Reason: All modules accessing the network node must receive information on available subnets and network paths (= routing information).

- In your network configuration, the PG/PC you want to use to establish a connection via network node must be assigned to the network it is physically connected to.

- The CPUs must either be configured as the master or

- If the CPU is configured as the slave, then the Commissioning / Test mode functionality must be activated under the properties of the DP interface for DP slaves in STEP 7.

Sample application: TeleService

The picture below contains a sample application: remote maintenance of an S7 station by a PG. The connection is established across subnet boundaries and requires a modem.

The lower part of the figure shows you how easy it is to configure this feature in *STEP 7*.
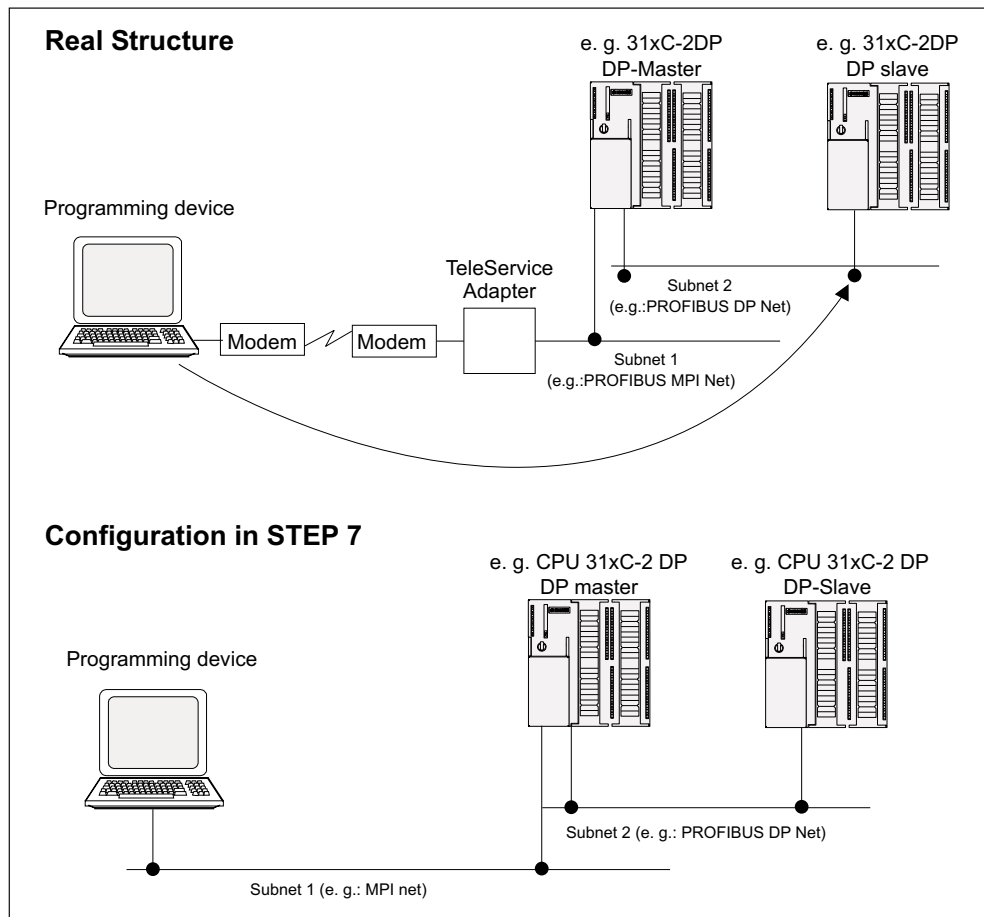
Figure 3-5   Routing - Sample application TeleService

Further information ...

*   on configuration with *STEP 7* is found in the *Configuring Hardware and Connections with STEP 7* Manual.

*   of a basic nature is contained in the *Communication with SIMATIC* Manual.

*   on the TeleService adapter can be found on the Internet at . In The Document Search area you can enter the search term A5E00078070 to download the documentation.

3.9   Data consistency

A data area is considered consistent, if the operating system can read/write access the data area in a continuous block. Data exchanged collectively between the stations should belong together and originate from a single processing cycle, that is, be consistent.

If the user program contains a programmed communication function, e.g. access to shared data with XSEND/ XRCV, access to that data area can be co-ordinated by means of the "BUSY" parameter itself.

With PUT/GET functions

With S7 communication functions, such as PUT/GET or write / read via OP communication that do not require a block in the user program on the CPU (acting as the server), then the extent of the data consistency must have been considered at the programming stage.

The PUT/GET functions for S7 communication or for reading/writing variables via OP communication are executed at the CPU's scan cycle checkpoint.

To ensure a defined process interrupt response time, communication variables are copied consistently to/from user memory, in blocks with a maximum size of 64 bytes, during the scan cycle checkpoint of the operating system. Data consistency is not guaranteed for any larger data areas.

If a defined level of data consistency is required, the length of communication variables in the user program must therefore not exceed 64 bytes.

Memory concept

<div style="text-align: right; font-size: 3em; font-weight: bold;">4</div>

4.1 Memory areas

4.1.1 Distribution of the memory

Introduction

The CPU memory can be divided into three areas:
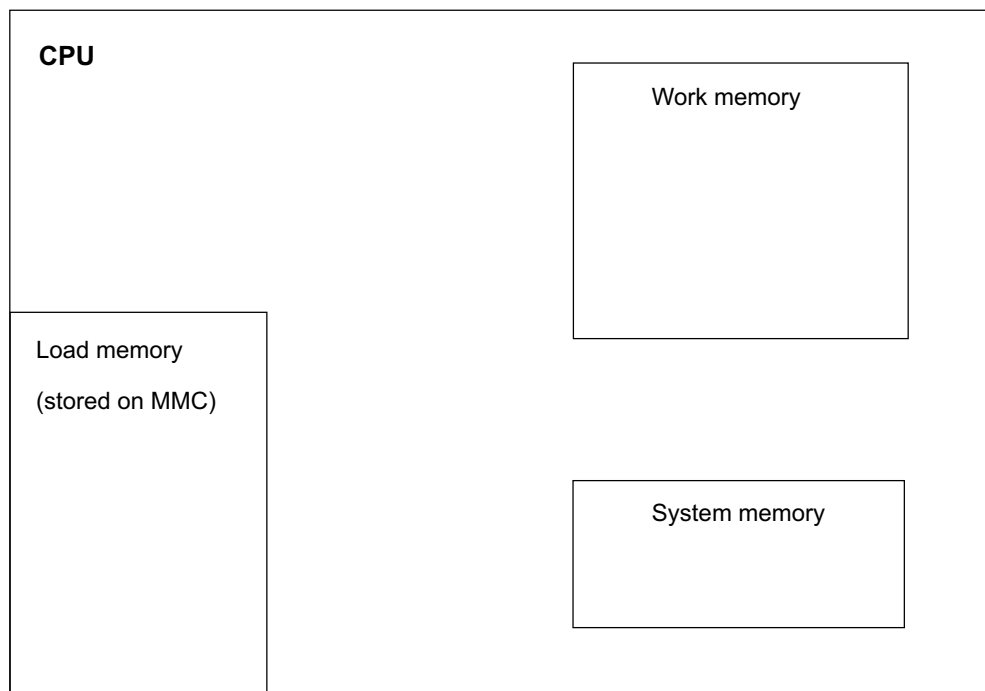
Figure 4-1   CPU memory areas

Load memory

The load memory is located on a SIMATIC Micro Memory Card (MMC). The size of the load memory corresponds exactly to the size of the MMC. It is used to store code blocks, data blocks and system data (configuration, connections, module parameters, etc.).

Blocks that are identified as non runtime-related are stored exclusively in load memory.

You can also store all the configuration data for your project on the MMC.

Note

User programs can only be downloaded and thus the CPU can only be used **if the MMC is inserted**.

RAM (working memory)

The RAM is integrated in the CPU and cannot be extended.It is used to run the code and process user program data. Programs only run in RAM and system memory.

The CPU's RAM is always retentive.

System memory

The RAM system memory is integrated in the CPU and cannot be expanded.

It contains

- the address areas for address area memory bits, timers and counters
- the process image of the I/Os
- local data

4.1.2 Retentive memory

Introduction

Your CPU is equipped with retentive memory . Retentive memory is implemented on MMC and in the CPU.

Data is kept in retentive memory across POWER OFF and restart (warm start).

Load memory

Your program in load memory (MMC) is always retentive. Program data is written to the MMC when they are downloaded, and are thus protected against power loss and memory reset.

RAM

In the event of POWER OFF, your RAM data is backed up on the MMC. Therefore, the content of data blocks is always retentive.

System memory

In your configuration (CPU properties, Retentive memory tab), specify which part of flag bits, timers and counters should be kept retentive and which of them are to be initialized with "0" on restart (warm restart).

The diagnostic buffer, MPI address (and transmission rate) and operating hour counter data are generally written to the retentive memory area on the CPU. Retentivity of the MPI address and baud rate ensures that your CPU can continue to communicate, even after a power loss, memory reset or loss of communication parameters (e.g. due to removal of the MMC or deletion of communication parameters).

Retentive behavior of memory objects

The table below shows the retentive behavior of memory objects during specific operating state transitions.

Table 4-1   Retentive behavior of memory objects

Memory object	Operating state transition		
	POWER ON / POWER OFF	RUN → STOP	Memory reset
User program/data (load memory)	x	x	x
Actual value of the DBs	x	x	–
Flag bits, timers and counters configured as retentive data	x	x	–
Diagnostics buffer, operating hour counter	x	x	x
MPI address, transmission rate	x	x	x

x = retentive; - = not retentive

4.2   Memory functions

Introduction

Memory functions are used to generate, modify or delete entire user programs or specific blocks. You can also ensure that your data is retained by archiving your own project data.

Basics of downloading a user program via PG/ PC

All user program data is downloaded **from your PG/PC to the CPU via MMC**.

Blocks use the load memory area as specified under "Load memory requirements" in "General block properties".
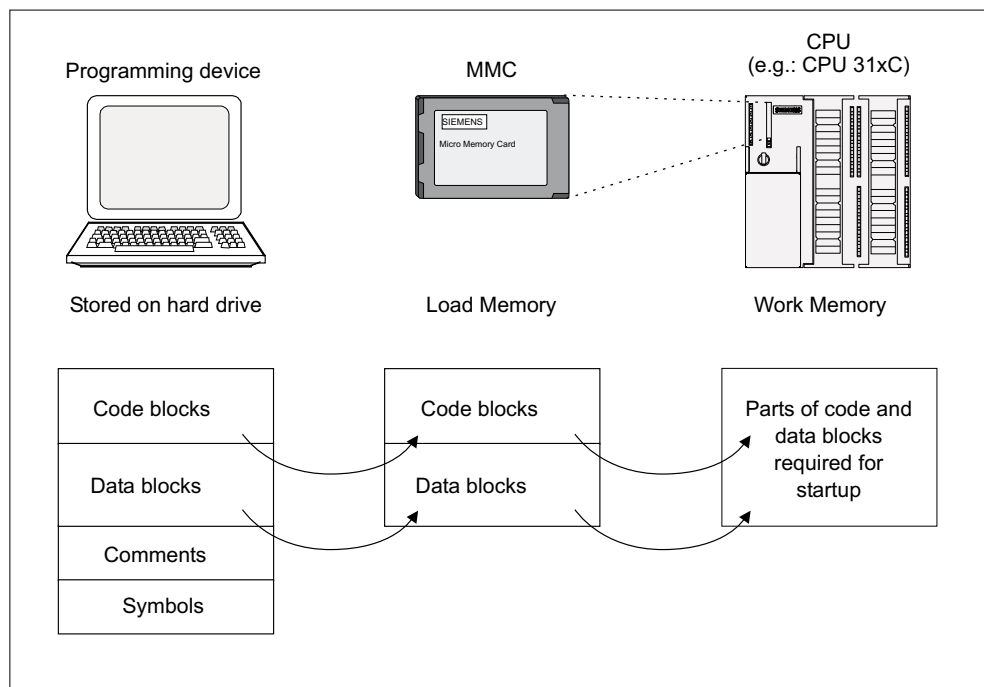
Figure 4-2   Load memory and RAM

You cannot run the program until all the blocks have downloaded.

Note

This function is only permitted when the CPU is in STOP mode.
Load memory is empty if this load operation could not be interrupted due to power loss or illegal block data.

Downloading a user program from the PG/ PC to the MMC

Case A: Download of a new user program

You have created a new user program. Download the complete program from your PG/PC to the MMC.

Case B: Download of additional blocks

You have already created a user program and downloaded it to the MMC (Case A). You then want to expand the program with additional blocks. In this case, you do not need to reload the entire user program to the MMC. Rather, you can download only the new blocks to the MMC (this procedure reduces the time required to download highly complex programs).

Case C: Overwriting with downloaded data

In this case, you modify blocks in your user program. In the next step, you download and overwrite the user program or only the modified blocks to the MMC, using the PG/PC.

Warning

When you download and overwrite blocks/a user program, all data stored under the same name on the MMC are lost.

Data of blocks linked to runtime are transferred to RAM and activated after the block is loaded.

Deleting blocks

When you delete a block, it is deleted from load memory. In *STEP 7* you can also delete a block via the user program (DBs also with SFC 23 "DEL_DB").

RAM used by this block is released.

Upload

Contrary to download operations, upload is referred to as the upload of specific blocks or of a complete user program **from the CPU to the PG/PC**. In this case, the blocks contain the data they had when they were downloaded the last time to the MMC. DBs linked to runtime form the exception, as their actual values are transferred.

In *STEP 7*, an upload of blocks or of the user program from the CPU does not influence the CPU's memory allocation.

Compression

When data is compressed, gaps which have developed between memory objects in load memory/RAM as a result of load/delete operations will be eliminated. This makes free memory available in a continuous block.

Data can be compressed while the CPU is in STOP or RUN mode.

Copying RAM to ROM

When copying the RAM content to ROM, the actual values of the DBs are transferred from RAM to load memory to form the start values for the DBs.

Note

This function is only permitted when the CPU is in STOP mode.

Subsequently, there will be no data in load memory if this operation is could not be interrupted by power loss.

Removing/inserting the MMC

You cannot run the CPU without an MMC inserted (no load memory). Appropriate operation is only possible after you have inserted an MMC and performed a CPU memory reset.

The CPU recognizes removal and insertion of an MMC in any operating state.

Removal procedure:

1. The CPU must be switched to STOP mode.

2. All PG write access functions must be disabled (e.g. download of blocks)

3. After the MMC is removed, the CPU requests memory reset.

⚠ **Warning**

Data on a SIMATIC Micro Memory Card can be corrupted if you remove the card while it is being accessed by a write operation. In this case, you may have to delete the MMC via PG or format the card in the CPU.

Never remove an MMC in RUN mode. Always remove when power is off or when the CPU is in STOP state and when the PG is not writing to the card. When the CPU is in STOP mode and you cannot determine whether or not a PG is writing to the card (e.g. load/delete block), disconnect the communication lines.

Insertion procedure:

Insert an MMC containing the corresponding user program as follows:

1. Insert the MMC

2. The CPU requests a memory reset

3. Acknowledge memory reset

   For information on corresponding procedures in case of repeated CPU requests for memory reset as a result of the insertion of a wrong MMC, or of an MMC with firmware update, refer to Chapter *Structure and Communication Connections of CPU 31xC, Special Handling*.

4. Start the CPU

⚠️ **Warning**

Make sure that the MMC contains a user program that matches your CPU (system). The wrong user program may have fatal processing effects.

Memory reset

After the insertion/removal of a Micro Memory Card, a CPU memory reset establishes defined conditions for CPU restart (warm start).

Memory reset rebuilds the CPU's memory management. Blocks in load memory are retentive. All runtime-related blocks are transferred again from load memory to RAM. The effect of this operation, in particular, is to initialize the data blocks in RAM (i.e. resets them to their initial values).

Memory reset and the corresponding peculiarities are described in the S7-300 Installation Manual, Chapter *CPU Memory Reset*.

Restart (warm start)

- The actual values of all DB are retained.

- The values of all retentive M, C, T are maintained.

- All non-retentive user data is initialized:

  – M, C, T, I, O with "0"

- All runtime levels are initialized.

- The process images are deleted.

4.3   Address areas

Overview

S7 CPU system memory is split into address areas (refer to the table below). Using corresponding operations, address data in the user program directly in the respective address area.

Table 4-2   Address areas of system memory

Address areas	Description
Process image of the inputs	At the start of every OB 1 cycle, the CPU reads the values at the input of the input modules and saves them the process image of the inputs.
Process image of the outputs	During its cycle, the program calculates the values for the outputs and writes them to the process image of the outputs. At the end of the OB1 cycle, the CPU writes the calculated output values to the output modules.
Flag bits	This area provides memory for saving the intermediate results of a program calculation.
Timers	Timers are available in this area.
Counters	Counters are available in this area.
Local data	Temporary data in a code block (OB, FB, FC) is saved to this memory area while the block is being edited.
Data blocks	Refer to Chapter *Handling of DB data*

Cross-reference

The address areas that are available on your CPU are listed in the *Instruction list for CPUs 31xCand 31x*.

I/O process image

When the user program addresses the Input (I) and Output (O) address areas, it does not query the signal states of digital signal modules. Instead, it rather accesses a memory area in CPU system memory. This memory area is referred to as process image.

The process image is split into two sections: Process image of the inputs and the process image of the outputs.

Advantages of the process image

Process image access, compared to direct I/O access, offers the advantage that a consistent image of process signals is made available to the CPU during cyclic program execution. When the signal status at an input module changes during program execution, the signal status in the process image is maintained until the image is updated in the next cycle. Moreover, since the process image is stored in CPU system memory, access is significantly faster than direct access to the signal modules.

Process image update

The operating system updates the process image periodically. The figure below shows the sequence of this operation within a cycle.
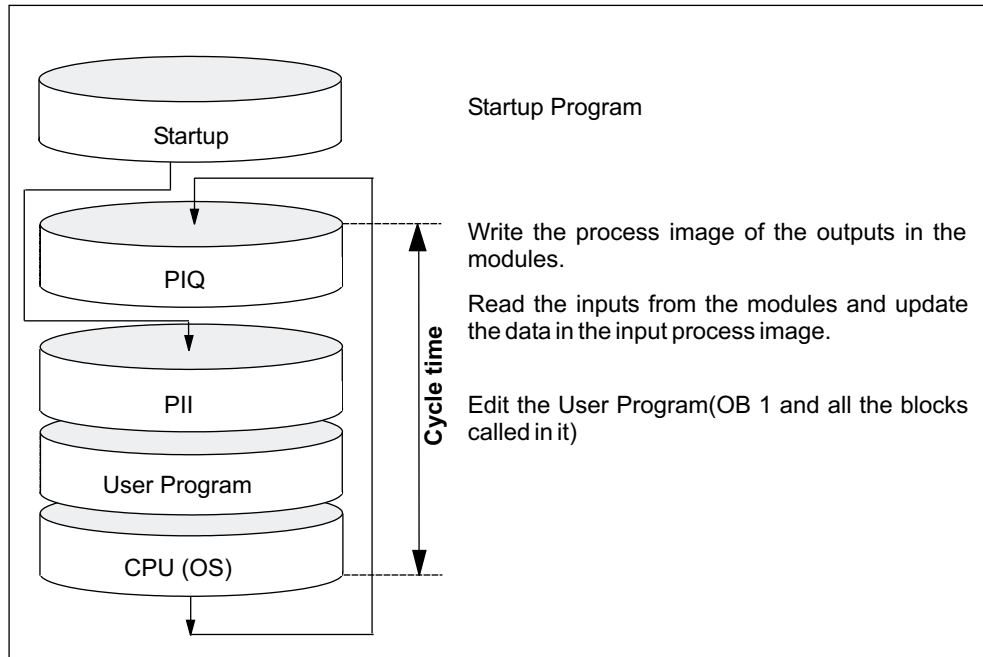
Figure 4-3   Sequence of operation within a cycle

Local data

Local data contains:

- the temporary variables of code blocks

- the start information of the OBs

- transfer parameters

- intermediate results

Temporary Variables

When you create blocks, you can declare temporary variables (TEMP) which are only available during block execution and then overwritten again. These local data have a fixed length per OB. Local data must be initialized prior to the first read access. Each OB also requires 20 bytes of local data for its start information. Local data access is faster than access to the data in DBs.

The CPU is equipped with memory for storing temporary variables (local data) of currently executed blocks. The size of this memory area depends on the CPU. It is distributed in partitions of equal size to the priority classes. Each priority class has its own local data area.

> **Caution**
>
> ⚠ All temporary variables (TEMP) of an OB and its subordinate blocks are stored in local data. If you use multiple nesting levels for block processing, you may cause an overflow in the local data area.
> The CPUs will change to STOP mode if you exceed the permitted length of local data for a priority class.
> Take local data volume required for synchronous error OBs into account; this is assigned to the respective priority class.

4.4 Handling of DB data

4.4.1 Recipes

Introduction

A recipe represents a collection of user data.

You can implement a simple recipe concept using DBs which are not linked to runtime. In this case, the recipes should have the same structure (length). One DB should exist per recipe.

Processing sequence

Recipes should be stored in load memory:

- in *STEP 7*, the specific records of recipes are generated as non-runtime DBs, and are then downloaded to the CPU. Therefore, recipes utilize load memory, rather than RAM.

Working with recipe data:

- SFC 83 "READ_DBL" is called from the user program to copy the record for the current recipe from the DB in load memory to a runtime-related DB in RAM. As a result, the RAM only has to accommodate the data of one record.

The user program can now access data of the current recipe.
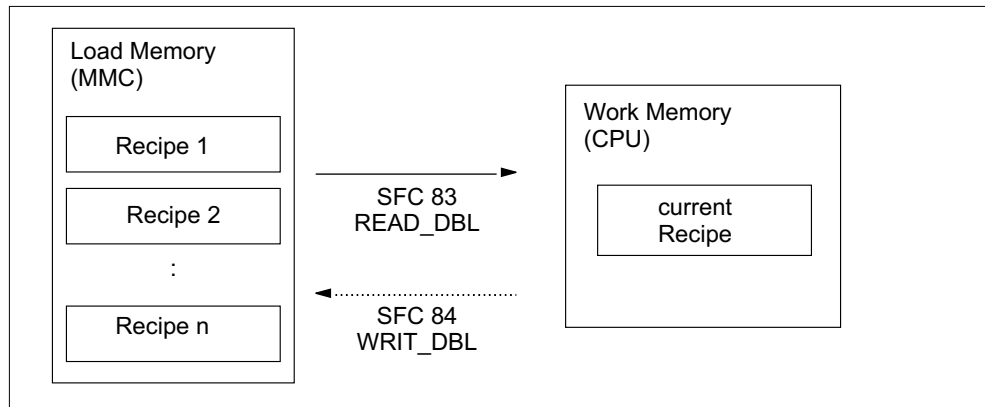
Figure 4-4   Handling of recipe data

Saving a changed recipe:

- New or changed recipe records generated during program processing can be transferred to load memory. To do this, call SFC 84 "WRIT_DBL" in the user program.

  These data which were written to load memory are portable, and are also retentive on memory reset.

  If you want to backup modified records (recipes) on a PG/PC, you can upload and save them in a single block.

Note

The active system functions SFC82 to 84 (current accesses to the MMC) have a distinct influence on PG functions (e.g. block status, variable status, load block, upload, open). They typically reduce performance (compared to inactive system functions) by the factor 10.

Note

As a precaution against data loss, always make sure that the maximum number of delete/write operations is not exceeded. Also refer to the SIMATIC Micro Memory Card (MMC) section in the "Structure and Communication Connections of a CPU" chapter.

Caution

Data on a SIMATIC Micro Memory Card can be corrupted if you remove the card while it is being accessed by a write operation. In this case, you may have to delete the MMC via PG or format the card in the CPU. Never remove an MMC in RUN mode. Always remove when power is off or when the CPU is in STOP state and the PG is not writing to the card. When the CPU is in STOP mode and you cannot determine whether or not a PG is writing to the card (e.g. load/delete block), disconnect the communication lines.

4.4.2 Measurement value archives

Introduction

Measurement values are generated when the CPU executes the user program. These values are to be evaluated and archived.

Processing sequence

Acquisition of measurement values:

- The CPU writes measured values to a DB (for alternating backup mode in several DBs) which is located in RAM.

Archiving measurement values:

- Before the data volume can exceed RAM capacity, you should call SFC 84 "WRIT_DBL" in the user program to swap measured values from the DB to load memory.
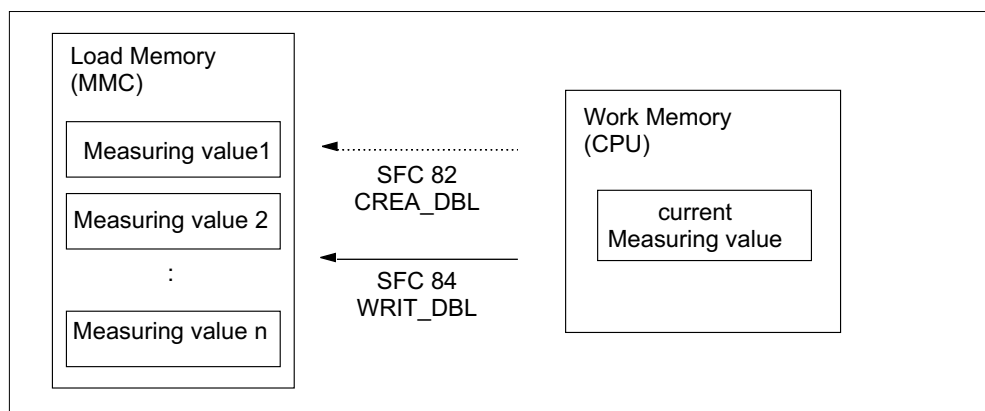
Figure 4-5   Handling of measurement value archives

- You can call SFC 82 "CREA_DBL" in the user program to generate new (additional) DBs in load memory which are not linked to runtime and do not require RAM space.

Cross-reference

The *System Software for S7-300/400* Reference Manual*, System and Standard Functions* or the STEP 7 Online Help all contain further information about the SFC 82 block.

Note

SFC 82 is terminated and an error message is generated if a DB already exists under the same number in load memory and/or RAM.

These data which were written to load memory are portable, and are also retentive on memory reset.

Evaluation of measurement values:

- Measurement value DBs saved to load memory can be uploaded and evaluated by other communication partners (e.g. PG, PC, ...).

Note

The active system functions SFC82 to 84 (current accesses to the MMC) have a distinct influence on PG functions (e.g. block status, variable status, load block, upload, open).

They typically reduce performance (compared to inactive system functions) by the factor 10.

To prevent loss of data, always make sure that you do not exceed the maximum number of delete/write cycles. See also the SIMATIC Micro Memory Card (MMC) section in the "Structure and Communication Functions of a CPUs 31xC" chapter.

Caution

Data on a SIMATIC Micro Memory Card can be corrupted if you remove the card when it is being accessed by a write operation. In this case, you may have to delete the MMC via PG or format the card in the CPU.

Never remove an MMC in RUN mode. Always remove when power is off or when the CPU is in STOP state and when the PG is not writing to the card. When the CPU is in STOP mode and you cannot determin whether or not a PG is writing to the card (e.g. load/delete block), disconnect the communication lines.

4.5 Saving/retrieving complete projects to/from Micro Memory Card

Function mode of operation

Using the **Save project to Memory Card** and **Retrieve project from Memory Card** functions, you can save all project data to a SIMATIC Micro Memory Card for future retrieval. For this operation, the SIMATIC Micro Memory Card can be located in a CPU or in the MMC programming device of a PG or PC.

Project data is compressed before they are saved to a SIMATIC Micro Memory Card, and uncompressed on retrieval.

Note

You may also have to store your user data on the micro memory card, in addition to just the project data. You should therefore check in advance whether your chosen MMC has sufficient memory.

A message will indicate if your MMC is running out of memory.

The volume of project data to be saved corresponds with the size of the project's archive file.

Note

For technical reasons, you can only transfer the entire contents (user program and project data) using the **Save project to memory card** action.

Handling the functions

How you use the **Save project to memory card** / **Retrieve project from memory card** functions depends on the location of the SIMATIC micro memory card:

- If the micro memory card is inserted in the MMC slot, select a project level that is uniquely assigned to the CPU from the SIMATIC Manager project window (e.g. CPU, program, source or blocks). Select the **Target system > Save project to memory card** or **Target system > Retrieve project from memory card** menu command. All project data is written to the MMC, or retrieved from the card.

- If project data is not available on the currently used programming device (PG/PC), you can select the source CPU via "Available nodes" window. Select menu command **PLC > Show available nodes** to open the "Available nodes" window. Select the connection/CPU that contains your project data on Micro Memory Card. Now select menu command **Retrieve project from Memory Card**.

- If the micro memory card is located in the MMC programming device of a PG or PC, open the "S7 memory card window" using the **File > S7 Memory Card > Open** menu command. Select the **Target system > Save project to memory card** or **Target system > Retrieve project from memory card** menu command. to open a dialog in which you can select the source or target project.

Note

Project data may generate a high volume of data. Especially in RUN mode and during read/write access to the CPU, this can lead to waiting periods of several minutes.

Sample application

When you assign more than one member of your service and maintenance department to perform maintenance tasks on a SIMATIC PLC, it may prove difficult to provide quick access to current configuration data to each staff member.

However, CPU configuration data available locally on any CPU that is to be serviced can be accessed by any member of the service department. They can edit these data and then release the updated version to all other personnel.

Cycle and response times

5

5.1　Introduction

In this Chapter ...

we are going to show you which factors determine the cycle and response times of S7-300 CPUs.

You can use the PG to read the cycle time of your user program on the relevant CPU (see *STEP 7 Online Help* or the *Configuring Hardware and Connections with STEP 7 V5.1* manual).

The following examples show you how to calculate the cycle time.

The response time represents an important factor when looking at a process. In this chapter we shall show you in detail how to calculate this time.

Chapter overview

- Cycle time
- Communication load
- Response time
- Examples of how to calculate cycle / response time
- Interrupt response time
- Example of how to calculate the interrupt response time
- Reproducibility of delay interrupts and watchdog interrupts

Further information on processing times ...

can be found in the *S7-300 Instruction List for CPUs 31xC* and 31x, which is a spreadsheet containing the run times for all

- *STEP 7* instructions the respective CPU can process,
- SFCs/SFBs integrated in the CPUs,
- IEC functions which can be called in *STEP 7*.

5.2 Cycle time

5.2.1 Overview

Introduction

This section explains what we mean by the term "cycle time", what this consists of and how you can calculate it.

What do we mean by "cycle time"?

The cycle time represents the time that an operating system needs for a single pass through a program, i.e. one OB 1 cycle - and all program sections and system activities that interrupt this cycle.

This time is monitored.

Time sharing model

Cyclic program processing, and therefore user program execution, is carried out in time shares. To clarify these processes, let us assume that every time share has a length of precisely 1 ms.

Process image

During cyclic program processing, the CPU requires a consistent image of the process signals. To ensure this, the process signals are read/written prior to program execution. Subsequently, during program execution and when addressing input (I) and output (Q) address areas, the CPU does not directly access the signal modules, but rather accesses the system memory area which contains the I/O process image.

Sequence of cyclic program processing

The table and figure below show the phases of cyclic program processing.

Table 5-1   Cyclical program processing

Step	Sequence
1	The operating system initiates cycle time monitoring.
2	The CPU copies the values of the process image of the outputs to the output modules.
3	The CPU reads the status at the inputs of the input modules and then updates the process image of the inputs.
4	The CPU processes the user program in time shares and executes program instructions.
5	At the end of a cycle the operating system executes queued tasks, e.g. it loads and deletes blocks.
6	The CPU then returns to the start of the cycle and restarts cycle time monitoring.

PIO: Process image Outputs
PII: Process image of Inputs
CCP: Cycle Checkpoint
 OS: Operating system
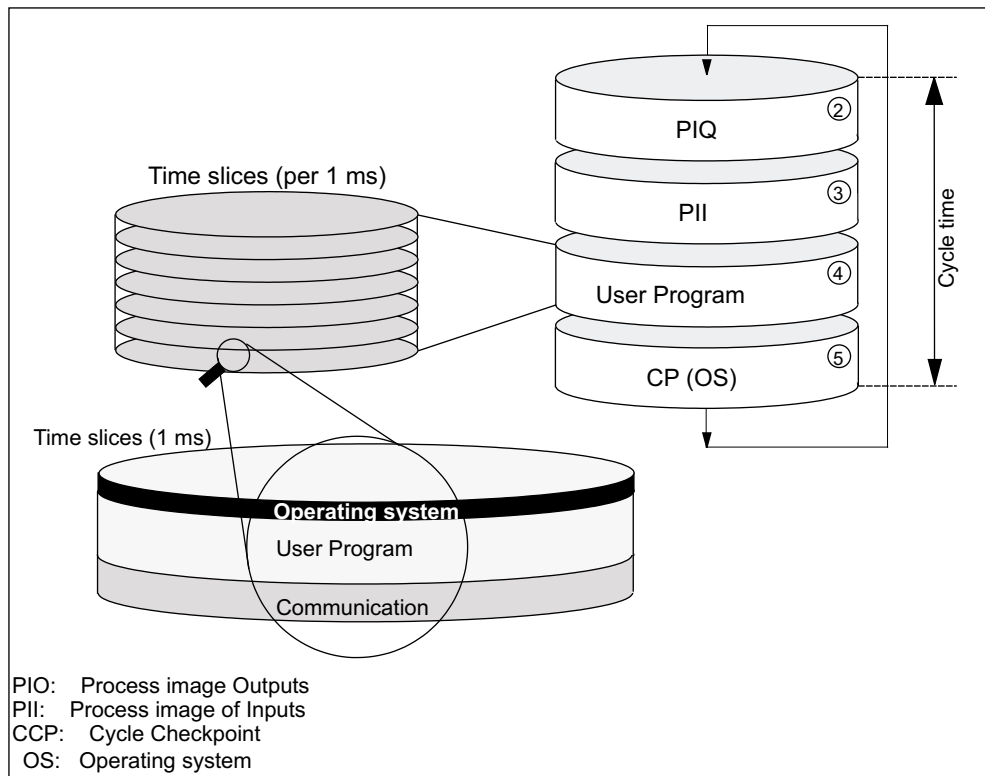
Figure 5-1   Time-sharing model

In contrast to the S7-400 CPUs (and the CPU 318-2 DP), with the S7-300 CPUs the data is accessed with an OP/TP (control and monitoring functions) only at the scan cycle checkpoint (see the technical data chapter for data consistency). Processing of the user program is not interrupted by the control and monitoring functions.

Extension of the cycle time

Always take into consideration that the cycle time of a user program is extended by:

- Time-controlled interrupt handling

- Process interrupt handling (also refer to Chapter *Interrupt response time*)

- Diagnostics and error handling

- Communication with programming devices (PGs), operator panels (OPs) and via connected CPs (e.g. Ethernet, PROFIBUS-DP)

- Testing and commissioning routines, e.g. status/controlling of variables or block status functions.

- Transfer and deletion of blocks, compressing user program memory

- Write/read access to the MMC, using SFC82 to 84 in the user program

5.2.2 Calculating the cycle time

Introduction

The cycle time is made up of following influencing factors.

Process image update

The table below shows the times a CPU requires to update the process image (process image transfer time). The times specified might be prolonged as a result of interrupts or CPU communication.

The process image transfer time is calculated as follows:

BaseLoad (K) **+ number of bytes in the PI in the module 0 x (A)**
+ number of bytes in the PI in the module 1 to 3 x
+ number of bytes in the PI via DP x (D)

= transfer time for the process image

Figure 5-2   Formula for calculating the process image (PI) transfer time

Table 5-2   Data for calculating the process image transfer time

Const.	Compo-nents	CPU 312C	CPU 313C	CPU 313C -2 DP	CPU 313C -2 PtP	CPU 314C -2 DP	CPU 314C-2 PtP	CPU 312	CPU 314	CPU 315-2 DP
K	Base load	150 µs	100 µs	100 µs		100 µs		150 µs	100 µs	100 µs
A	per byte in rack 0	37 µs	35 µs	37 µs		37 µs		37 µs	35 µs	37 µs
B	per byte in racks 1 to 3*	-	43 µs	47 µs		47 µs		-	43 µs	47 µs
D (DP only)	per WORD in the DP area for the integrated DP interface	-	-	1 µs	-	1 µs	-	-	-	1 µs

* + 60 µs per rack

Extending the user program processing time

In addition to actually working through the user program, your CPU's operating system also runs a number of processes in parallel, such as timer management for the core operating system. These processes extend the processing time of the user program.

The table below lists the multiplication factors required to calculate your user program processing time.

Table 5-3   Extending the user program processing time

Process CPU	312C	313C	313C-2 DP	313C-2 PtP	314C-2 DP	314C-2 PtP	312	314	315-2 DP
Factor	1.06	1.10	1.10	1.06	1.10	1.09	1.06	1.10	1.10

Operating system processing time at the scan cycle checkpoint

The table below shows the operating system processing time at the scan cycle checkpoint of the CPUs. These times are calculated without taking into consideration times for:

- Testing and commissioning routines, e.g. status/controlling of variables or block status functions
- Transfer and deletion of blocks, compressing user program memory
- Communications
- Read/write access to the MMC, using SFC82 to 84

Table 5-4   Operating system processing time at the scan cycle checkpoint

Sequence	CPU 312C	CPU 313C	CPU 313C-2	CPU 314C-2	CPU 312	CPU 314	CPU 315-2
Cycle control at the SCC	500 µs	500 µs	500 µs	500 µs	500 µs	500 µs	500 µs

Extended cycle times as a result of errors and nested interrupts

Enabled interrupts also extend cycle time. Details are found in the table below.

Table 5-5   Extended cycle time due to nested interrupts

Interrupt type	CPU 312C	CPU 313C	CPU 313C-2	CPU 314C-2	CPU 312	CPU 314	CPU 315-2 DP
Process interrupt	700 µs	500 µs	500 µs	500 µs	700 µs	500 µs	500 µs
Diagnostic interrupt	700 µs	600 µs	600 µs	600 µs	700 µs	600 µs	600 µs
Timeofday interrupt	600 µs	400 µs	400 µs	400 µs	600 µs	400 µs	400 µs
Delay interrupt	400 µs	300 µs	300 µs	300 µs	400 µs	300 µs	300 µs
Watchdog interrupt	250 µs	150 µs	150 µs	150 µs	250 µs	150 µs	150 µs

The program runtime at interrupt level must be added to this time extension.

Table 5-6   Cycle time extension as a result of errors

Type of error	CPU 312C	CPU 313C	CPU 313C-2	CPU 314C-2	CPU 312	CPU 314	CPU 315-2 DP
Programming errors	600 µs	400 µs	400 µs	400 µs	600 µs	400 µs	400 µs
I/O access errors	600 µs	400 µs	400 µs	400 µs	600 µs	400 µs	400 µs

The interrupt OB processing time must be added to this extended time. The times required for multiple nested interrupt/error OBs are added accordingly.

see also

Calculating method for calculating the cycle/response time *[→ Page 5-16]*

5.2.3 Different cycle times

Overview

The length of the cycle time (T_{cyc}) is not the same in every cycle. The figure below shows different cycle times T_{cyc1} and T_{cyc2}. T_{cyc2} is longer than T_{cyc1}, because the cyclically executed OB1 is interrupted by a time-of-day interrupt OB (here: OB10).
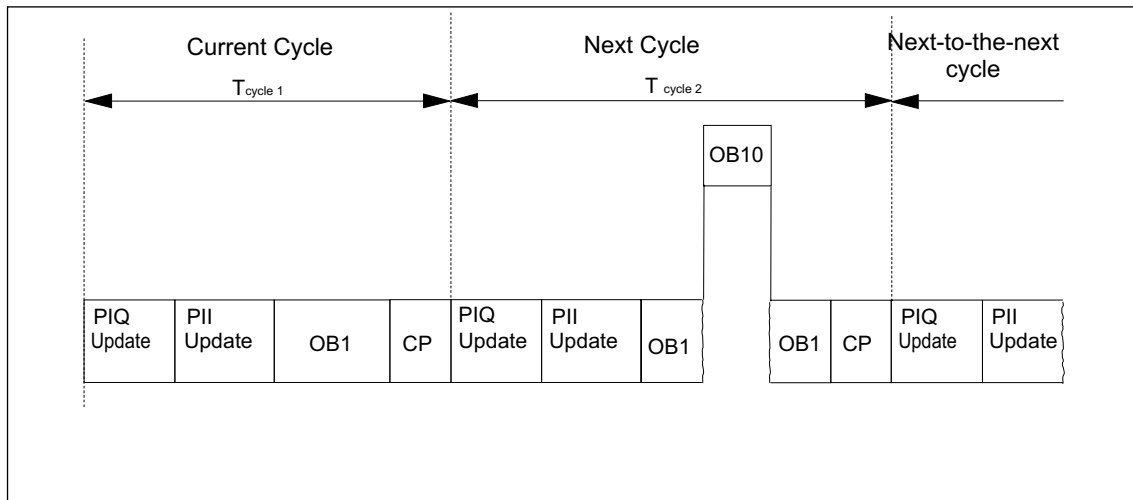
Figure 5-3   Different cycle times

Block processing times may fluctuate

Fluctuation of the block processing time (e.g. OB 1) may also be a factor causing cycle time fluctuation, due to:

- conditional instructions,
- conditional block calls,
- different program paths,
- loops etc.

Maximum cycle time

In *STEP 7* you can modify the default maximum cycle time. OB80 is called on when this time expires. In this block you can specify the CPU's response to this timeout error.

The CPU switches to STOP mode if OB80 does not exist in its memory.

5.2.4 Communication load

Configured communication load (PG/OP communication)

The CPU operating system continuously provides a specified percentage of total CPU processing performance (Time-sharing technology) for communication tasks. Processing performance not required for communication is made available to other processes. In HW Config, you can specify a communication load value between 5% and 50%. Default value is 20%. You can use the following formula for calculating the cycle time extension factor:

$$\frac{100}{100 - \text{"projected Communication load in \%"}}$$

Figure 5-4   Formula for calculating communication load
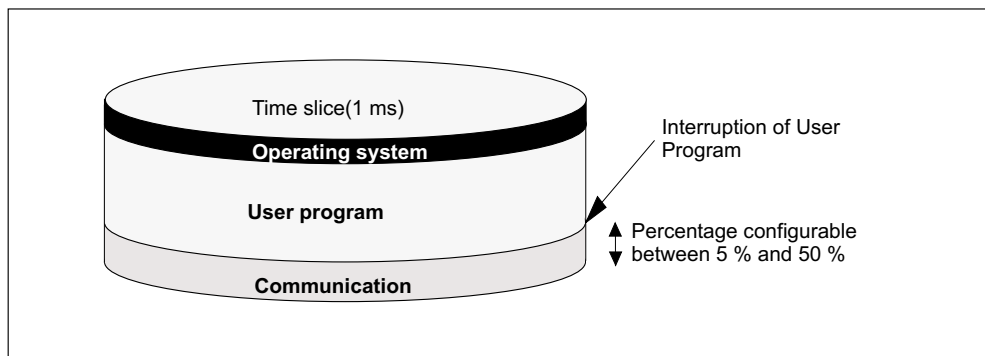
Figure 5-5   Splitting a time share

Example: 20% communication load

In your hardware configuration, you have specified a communication load of 20%.

The calculated cycle time is 10 ms.

Using the above formula, the cycle time is extended by the factor 1.25.

Example: 50% communication load

In your hardware configuration, you have specified a communication load of 50%.

The calculated cycle time is 10 ms.

Using the above formula, the cycle time is extended by the factor 2.

Physical cycle time depending on communication load

The figure below describes the non-linear dependency of the physical cycle time on communication load. In our sample we have chosen a cycle time of 10 ms.
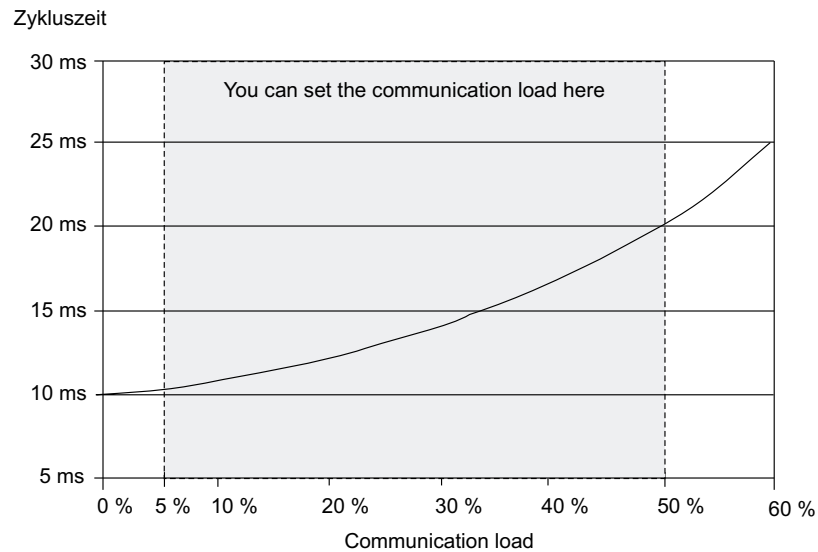
Figure 5-6   Cycle time depending on communication load

Influence on the physical cycle time

From the statistical viewpoint, asynchronous events - such as interrupts - occur more frequently within the OB1 cycle when the cycle time is extended as a result of communication load. This further extends the OB1 cycle. This extension depends on the number of events that occur per OB1 cycle and the time required to process these events.

Note

Change the value of the "communication load" parameter to check the effects on the cycle time at system runtime. You must consider the communication load when you set the maximum cycle time, otherwise timing errors can occur.

Tips

- Use the default setting wherever possible.

- Increase this value only if the CPU is used primarily for communications and if the user program is not time critical.

- In all other situations you should only reduce this value.

5.2.5 Cycle time extension as a result of testing and commissioning functions

Runtimes

The runtimes of the testing and commissioning functions are operating system runtimes, so they are the same for every CPU. Initially, there is no difference between process mode and testing mode.

How the cycle time is extended as a result of active testing and commissioning functions is shown in the table below.

Table 5-7   Cycle time extension as a result of testing and commissioning functions

Function	CPU 31xC/ CPU 31x
Status variable	50 µs for each variable
Control variable	50 µs for each variable
Status block	200 µs for each monitored line

Configuration during parameter assignment

In **process mode**, the maximum permitted communication load by is not only set in "Communication load". It is also determined by "Process mode: maximum permitted cycle time extension due to testing functions". Thus, the configured time is monitored absolutely in process mode and data acquisition is stopped if a timeout occurs. This is how *STEP 7* stops data requests in loops before a loop ends, for example.

When running in **Testing mode**, the complete loop is executed in every cycle. This can significantly increase cycle time.

5.3 Response time

5.3.1 Overview

Definition of response time

The response time is the time between the detection of an input signal and the change of a linked output signal.

Fluctuation width

The physical response time lies between the shortest and the longest response time. You must always reckon with the longest response time when configuring your system.

The shortest and longest response times are shown below, to give you an idea of the fluctuation width of the response time.

Factors

The response time depends on the cycle time and following factors:

- Delay of the inputs and outputs of signal modules or integrated I/O.

- Additional DP cycle times in a PROFIBUS-DP network
  (only with CPUs 31xC-2 DP)

- Execution in the user program

You can find the delay times ...

- in the technical data of the signal modules (Reference Manual *Module data*)

- for integrated I/Os in *Technical data of integrated I/O*

DP cycle times in a PROFIBUS-DP network

if you have configured your PROFIBUS-DP network in *STEP 7* , *STEP 7* calculates the typical DP cycle time to be expected. You can then view the DP cycle time of your configuration on the PG.

The figure below gives you an overview of the DP cycle time. In this example, let us assume that the data of each DP slave has an average length of 4 bytes.
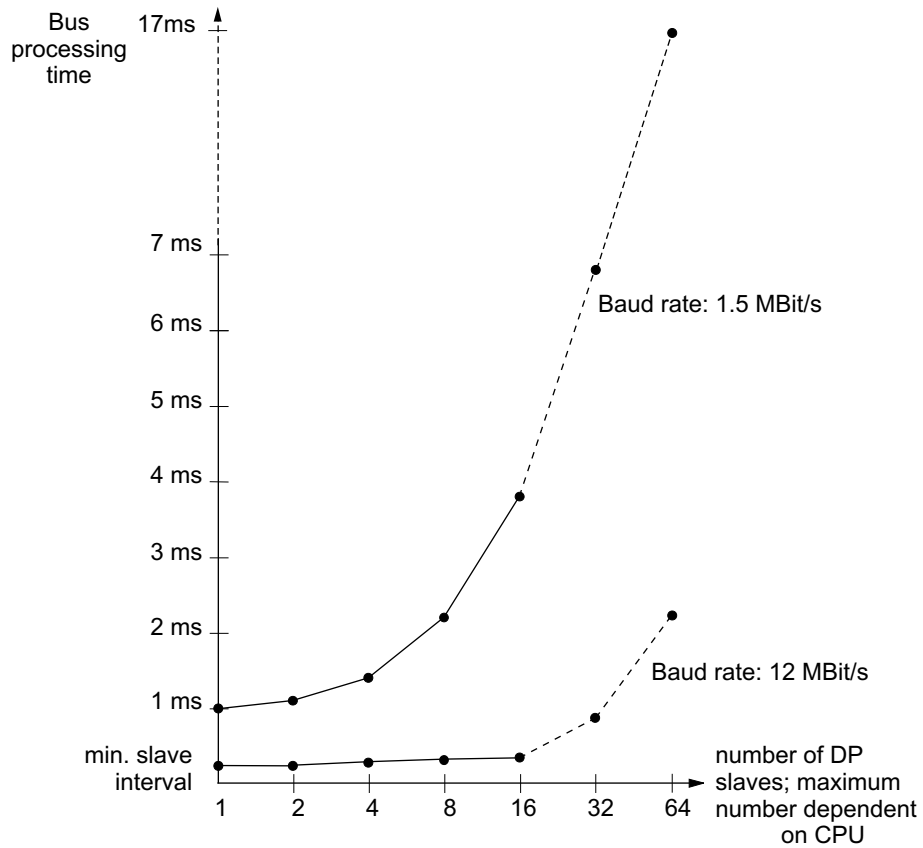
Figure 5-7   DP cycle times in a PROFIBUS-DP network

With multi-master operation on a PROFIBUS-DP network, you must consider the DP cycle time for each individual master. That is, you will have to calculate the times for each master separately and then add up the results.

see also

Longest response time *[→ Page 5-14]*

Shortest response time *[→ Page 5-13]*

5.3.2 Shortest response time

Conditions for shortest response time

The figure below shows you the conditions under which the shortest response time is reached.
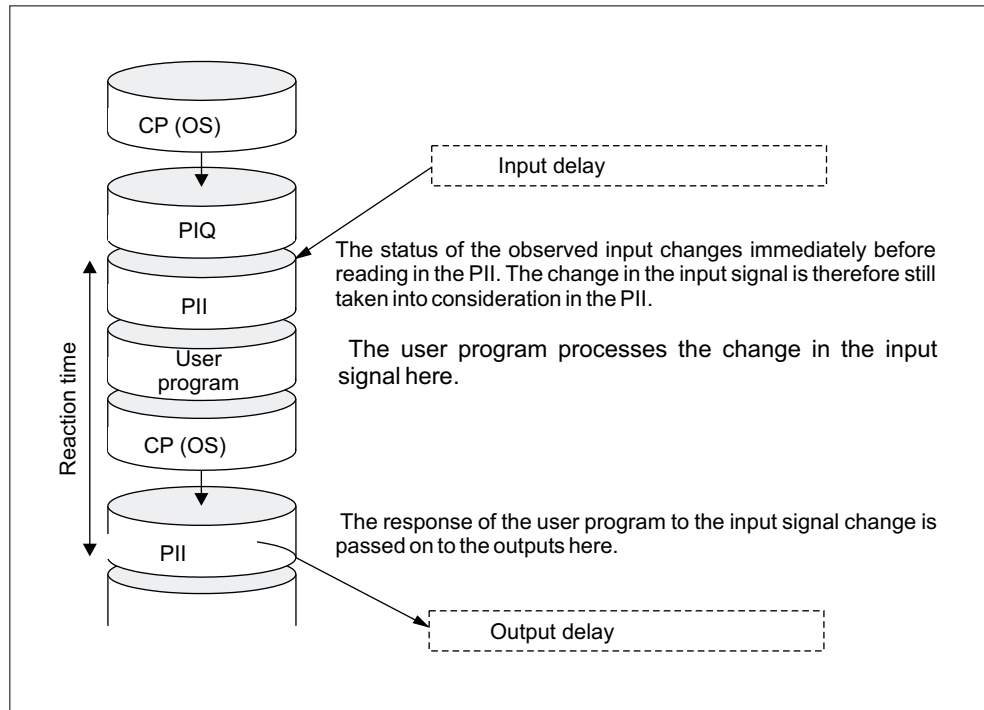
Figure 5-8 Shortest response time

Calculation

The (shortest) response time is the sum of:

- 1 x process image transfer time for the inputs +
- 1 x process image transfer time for the outputs +
- 1 x program processing time +
- 1 x operating system processing time at the SCC +
- I/O delay

The result is equivalent to the sum of the cycle time plus the I/O delay times.

see also

Calculating method for calculating the cycle/response time *[→ Page 5-16]*

Reducing the response time with direct I/O access *[→ Page 5-15]*

5.3.3 Longest response time

Conditions for the longest response time

The figure below shows the conditions under which the longest response time is reached.
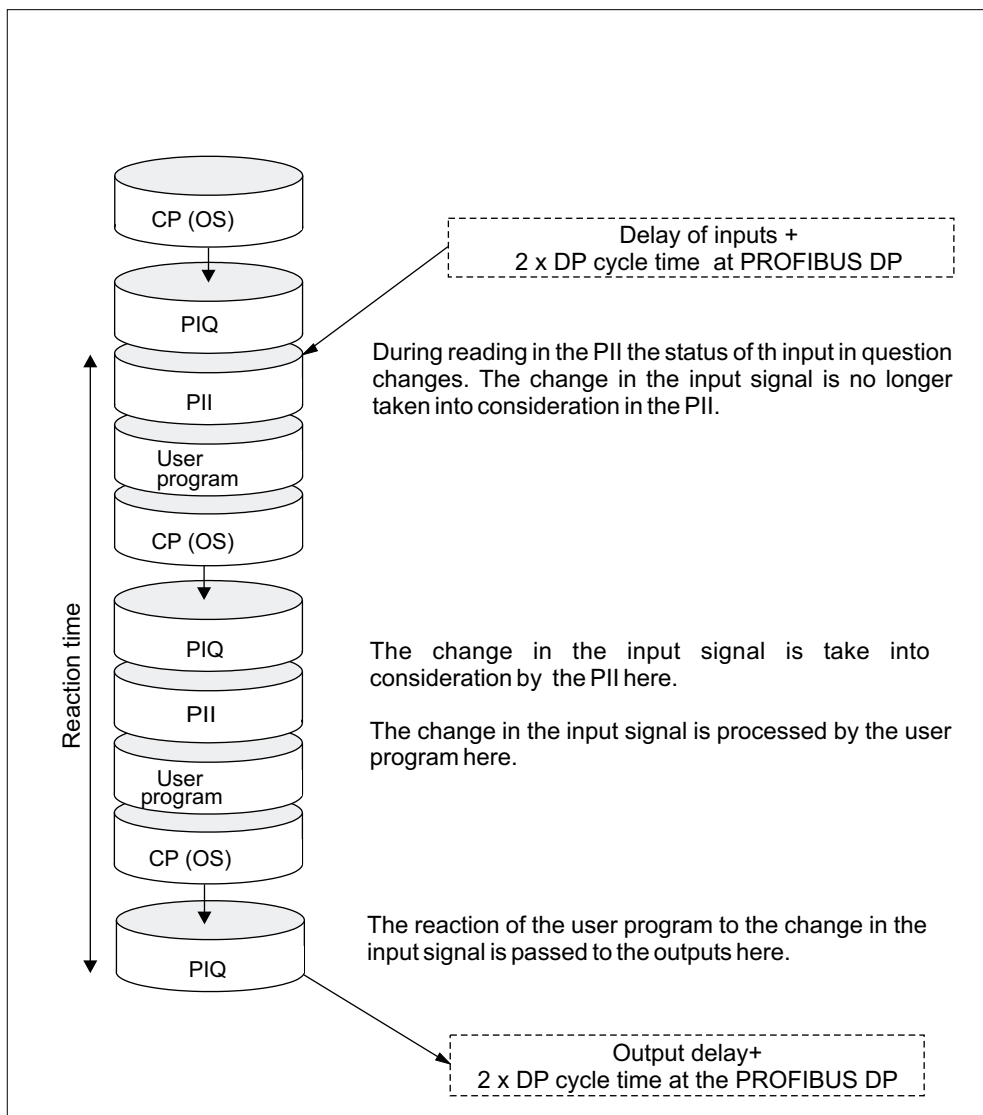
Figure 5-9   Longest response time

Calculation

The (longest) response time is the sum of:

- 2 x process image transfer time for the inputs +

- 2 x process image transfer time for the outputs +

- 2 x operating system processing time +

- 2 x program processing time +

- 4 x the runtime of DP Slave message frames (includes processing in the DP Master) +

- I/O delay

The result is equivalent to twice the cycle time + input and output delay + twice the bus runtime.

see also

Calculating method for calculating the cycle/response time *[→ Page 5-16]*

Reducing the response time with direct I/O access *[→ Page 5-15]*

5.3.4 Reducing the response time with direct I/O access

Reducing the response time

You can reach faster response times with direct access to the I/O in your user program, for example with

- L PIB or

- T PQW

you can partially avoid the response times described above.

Note

You can also achieve fast response times by using process interrupts. Refer to the following chapters.

5.4   Calculating method for calculating the cycle/response time

Introduction

This chapter gives you an overview of how to calculate the cycle/response time.

All tables are found in Chapter *Calculating the cycle time*.

Cycle time

1. Determine the user program runtime with the help of the *Instruction list*.

2. Multiply the calculated value by the CPU-specific factor from the table *Extension of user program processing time*.

3. Calculate and add the process image transfer time. Corresponding guide values are found in table *Data for calculating process image transfer time*.

4. Add the processing time at the scan cycle checkpoint. Corresponding guide values are found in the table *Operating system processing time at the scan cycle checkpoint*.

5. Include the extensions as a result of testing and commissioning functions in your calculation. These values can be found in the *Cycle time extension as a result of testing and commissioning functions* table.*The result is the*

6. **Cycle time***.*

Extension of the cycle time as a result of interrupts and communication load

$$\frac{100}{100 - \text{"projected Communication load in \%"}}$$

Figure 5-10 Formula for calculating communication load

7. Multiply the cycle time by the factor as in the formula above.

8. Calculate the runtime of interrupt-processing program sections with the help of the instruction list. Add the corresponding value from the *Calculating the Cycle Time* chapter, Table *Extended cycle time as a result of nested interrupts.*

9. Multiply both values by the CPU-specific extension factor of the user program processing time (see Table 5-3).

10. Add the value of the interrupt-processing program sequences to the theoretical cycle time, multiplied by the number of triggering (or expected) interrupt events within the cycle time.

The result is an approximation of the **physical cycle time**. Note the result.

Response time

Table 5-8   Calculating the response time

Shortest response time	Longest response time
-	Multiply the physical cycle time by factor 2.
Now add I/O delay.	Now add the I/O delay and the DP cycle times of the PROFIBUS-DP network.
The result is the shortest response time.	The result is the longest response time.

5.5   Interrupt response time

5.5.1 Overview

Definition of the interrupt response time

The interrupt response time is the time that expires between the first occurrence of an interrupt signal and the call of the first interrupt OB instruction. The following rule generally applies: High priority interrupts are executed first. This means that the interrupt response time is increased by the program processing time of the higher priority interrupt OBs and the interrupt OBs of equal priority which have not yet been executed (queued).

Calculation

The formula below show how you can calculate the minimum and maximum interrupt response times.

minimum interrupt response time of CPU + minimmum interrupt response time of signal modules + DP cycle time on PROFIBUS DP = **shortest interrupt response time**	maximum interrupt response time of CPU + maximum interrupt response time of the signal modules + 2 x DP cycle time on the PROFIBUS The maximum interrupt time extends when the communication functions are active. The time extension is calculated according to the following formula: $tv = 200 \,\mu s + 1000 \,\mu s \times n\%$ a clear extension is possible with n = Cycle time produced by communicaton

Figure 5-11 Formula for calculating the interrupt response time

Process/diagnostic interrupt response times of the CPUs

Table 5-9   Process and diagnostic interrupt response times

CPU	Process interrupt response times			Diagnostic interrupt response times	
	External min.	external max.	Integrated I/O max.	Min.	Max.
CPU 312	0.5 ms	0.8 ms	-	0.5 ms	1.0 ms
CPU 312C	0.5 ms	0.8 ms	0.6 ms	0.5 ms	1.0 ms
CPU 313C	0.4 ms	0.6 ms	0.5 ms	0.4 ms	1.0 ms
CPU 313C-2	0.4 ms	0.7 ms	0.5 ms	0.4 ms	1.0 ms
CPU 314	0.4 ms	0.7 ms	-	0.4 ms	1.0 ms
CPU 314C-2	0.4 ms	0.7 ms	0.5 ms	0.4 ms	1.0 ms
CPU 315-2 DP	0.4 ms	0.7 ms	-	0.4 ms	1.0 ms

Signal modules

The **Process interrupt response time** of signal modules is determined by following factors:

- Digital input modules

  Process interrupt response time = internal interrupt preparation time + input delay

  You will find these times in the data sheet for the respective digital input module.

- Analog input modules

  Process interrupt response time = internal interrupt preparation time + input delay

  The internal interrupt preparation time for analog input modules can be neglected. The conversion times can be found in the data sheet for the individual analog input modules.

The **Diagnostic interrupt response time** of signal modules is equivalent to the period that expires between the time a signal module detects a diagnostic event and the time this signal module triggers the diagnostic interrupt. This short time can be neglected.

Process interrupt processing

Process interrupt processing begins after process interrupt OB40 is called. Higher priority interrupts stop process interrupt processing. Direct I/O access is executed during runtime of the instruction. After process interrupt processing has terminated, cyclic program execution continues or further interrupt OBs of equal or lower priority are called and processed.

5.5.2 Reproducibility of delay interrupts and watchdog interrupts

Definition of reproducibility

Delay interrupt:

The period that expires between the call of the first instruction in the interrupt OB and the programmed time of interrupt.

Watchdog interrupt:

The fluctuation width of the interval between two successive calls, measured between the respective initial instructions of the interrupt OBs.

Reproducibility

The following table shows the reproducibility of delay/watchdog interrupts of the CPUs.

Table 5-10   Reproducibility of CPU delay and watchdog interrupts

CPU	Delay interrupt	Watchdog interrupt
CPU 312	+/- 200 µs	+/- 200 µs
CPU 312C	+/- 200 µs	+/- 200 µs
CPU 313C	+/- 200 µs	+/- 200 µs
CPU 313C-2	+/- 200 µs	+/- 200 µs
CPU 314	+/- 200 µs	+/- 200 µs
CPU 314C-2	+/- 200 µs	+/- 200 µs
CPU 315-2 DP	+/- 200 µs	+/- 200 µs

These times only apply if the interrupt can actually be executed at this time and not delayed, for example, by high priority interrupts or queued interrupts of equal priority.

5.6 Sample calculations

5.6.1 Example of cycle time calculation

Assembly

You have configured an S7300 and equipped it with following modules in rack "0":

- a CPU 314C-2
- 2 digital input modules SM 321; DI 32 x 24 VDC (4 bytes each in the PI)
- 2 digital output modules SM 322; DO 32 x 24 VDC/0.5 A (4 bytes each in the PI)

User program

According to the Instruction List, the user program runtime is 5 ms. There is no active communication.

Calculation of the cycle time

In this example, the cycle time is equivalent to the sum of following times:

- User program processing time:

  approx. 5 ms x CPU-specific factor 1.10 = approx. 5.5 ms

- Process image transfer time

  Process image of inputs: 100 µs + 8 bytes x 37 µs = approx. 0.4 ms

  Process image of outputs: 100 µs + 8 bytes x 37 µs = approx. 0.4 ms

- Operating system runtime at the scan cycle checkpoint:

  approx. 0.5 ms

Cycle time = 5.5 ms + 0.4 ms + 0.4 ms + 0.5 ms = 6.8 ms.

Calculating the physical cycle time

- There is no active communication.
- Interrupts are not processed.

Hence, **the physical cycle time** is 6 ms.

Calculating the longest response time

Longest response time

6.8 ms x 2 = 13.6 ms.

- I/O delay can be neglected.

- DP cycle times must not be taken into account, as all modules are inserted in rack 0.

- Interrupts are not processed.

5.6.2 Sample of response time calculation

Assembly

You have configured an S7300 and equipped it with following modules in two racks:

- a CPU 314C-2

  Configuration of cycle load as a result of communication: 40 %

- 4 digital input modules SM 321; DI 32 x 24 VDC (4 bytes each in the PI)

- 3 digital output modules SM 322; DO 16 x 24 VDC/0.5 A (2 bytes each in the PI)

- 2 analog input modules SM 331; AI 8 x 12-bit (not in the PI)

- 2 analog output modules SM 332; AO 4 x 12-bit (not in the PI)

User program

According to the instruction list, the user program runtime is 10.0 ms.

Calculating the cycle time

In this example, the cycle time is equivalent to the sum of following times:

- User program processing time:

  approx. 10 ms x CPUspecific factor 1.10 = approx. 11 ms

- Process image transfer time

  Process image of inputs: 100 µs + 16 bytes x 37 µs = approx. 0.7 ms

  Process image of outputs: 100 µs + 6 bytes x 37 µs = approx. 0.3 ms

- Operating system runtime at the scan cycle checkpoint:

  approx. 0.5 ms

The sum of the listed times is equivalent to the cycle time:

Cycle time = 11.0 ms + 0.7 ms + 0.3 ms + 0.5 ms = 12.5 ms.

Calculating the physical cycle time

Under consideration of communication load:

12.5 ms * 100 / (100-40) = 20.8 ms.

Thus, under consideration of time-sharing factors, the **actual cycle time** is **21 ms**.

Calculation of the longest response time

- Longest response time = 21 ms * 2 = 42 ms.

- I/O delay

  – The maximum delay of the input digital module SM 321; DI 32 x 24 VDC is **4.8 ms** per channel.

  – The output delay of the digital output module SM 322; DO 16 x 24 VDC/0.5 A **can be neglected**.

  – The analog input module SM 331; AI 8 x 12-bit was programmed to suppress interference frequencies of 50 Hz. This gives a conversion time of 22 ms per channel. Since 8 channels are active, the result is a cycle time of **176 ms** for the analog input module.

  – The analog output module SM 332; AO 4 x 12-bit was programmed for the measuring range of 0 ...10 Hz. This gives a conversion time of 0.8 ms per channel. Since 4 channels are active, the result is a cycle time of 3.2 ms. A settling time of 0.1 ms for a resistive load must be added to this value. The result is an analog output response time of **3.3 ms**.

- DP cycle times can be neglected, as all modules are inserted in the CPU rack.

- Response times plus I/O delay:

  – **Case 1:** An output channel of the digital output module is set when a signal is received at the digital input. The result is a a response time of:

    Response time = 42 ms + 4.8 ms = 46.8 ms.

  – **Case 2:** An analog value is fetched, and an analog value is output. The result is a response time of:

    Longest response time = 42 ms + 176 ms + 3.3 ms = 221.3 ms.

5.6.3 Example of interrupt response time calculation

Assembly

You have assembled an S7-300, consisting of one CPU 314C-2 and four digital modules in the CPU rack. One of the digital input modules is an SM 321; DI 16 x 24 VDC; with process/diagnostic interrupt function.

You have enabled only the process interrupt in your CPU and SM parameter configuration. You decided not to use time controlled processing, diagnostics or error handling. You have configured a 20% communication load on the cycle.

You have configured a delay of 0.5 ms for the inputs of the DI module.

No activities are required at the scan cycle checkpoint.

Calculation

In this example, the process interrupt response time is based on following time factors:

- Process interrupt response time of CPU 314C-2: approx. 0.7 ms

- Extension by communication load according to the formula:

  200 µs + 1000 µs x 20 % = 400 µs = 0.4 ms

- Process interrupt response time of SM 321; DI 16 x 24 VDC:

  – Internal interrupt preparation time: 0.25 ms

  – Input delay: 0.5 ms

- Since the signal modules are inserted in the CPU rack, DP cycle times on the PROFIBUS-DP are irrelevant.

The process interrupt response time is equivalent to the sum of the listed time factors:

Process interrupt response time = 0.7 ms + 0.4 ms + 0.25 ms + 0.5 ms = **1.85** ms.

This calculated process interrupt response time expires between the time a signal is received at the digital input and the call of the first instruction in OB40.

Technical Data

6

6.1 CPU 312

Technical Data

Table 6-1   Technical Data for CPU 312

Technical Data	
CPU and version	
MLFB	6ES7312-1AD10-0AB0
• Hardware version	01
• Firmware version	V2.0.0
• Associated programming package	STEP 7, V 5.1 + SP 4 or later
Memory	
RAM	
• Integrated	16 KB
• Expandable	No
Load memory	Plugged in with MMC (max. 4 MB)
Buffering	Guaranteed by MMC (maintenance-free)
Processing times	
Processing times for	
• Bit operations	Min. 0.2 µs
• Word instructions	Min. 0.4 µs
• Fixed-point arithmetic	Min. 5 µs
• Floating-point arithmetic	Min. 6 µs
Timers/counters and their retentivity	
S7 counters	128
• Retentive memory	Configurable
• Default	from C0 to C7
• Counting range	0 to 999
IEC Counters	Yes
• Type	SFB
• Number	unlimited (limited only by RAM size)
S7 timers	128

Technical Data	
• Retentive memory	Configurable
• Default	Not retentive
• Timer range	10 ms to 9990 s
IEC Timers	Yes
• Type	SFB
• Number	unlimited (limited only by RAM size)
Data areas and their retentivity	
Total retentive data area (includes flag bits; timers; counters)	all
flag bits	128 bytes
• Retentive memory	Yes
• Default retentivity	MB0 to MB15
Clock flag bits	8 (1 flag bit)
Data blocks	511 (DB 1 to DB 511)
• Size	16 KB
Local data per priority class	max. 256 bytes
Blocks	
Total	1024 (DBs, FCs, FBs)
Obs	See the Instruction List
• Size	max. 16 KB
Nesting depth	
• Per priority class	8
• Additional within an error OB	4
FBs	max. 512 (FB 0 to FB 511)
• Size	max. 16 KB
FCs	max. 512 (FC 0 to FC 511
• Size	max. 16 KB
Address areas (I/Os)	
Total I/O address area	1024 bytes /1024 bytes (can be freely addressed)
I/O process image	128 bytes/128 bytes
Digital channels	max. 256
of those local	max. 256
Analog channels	max. 64
of those local	max. 64
Assembly	
Racks	max. 1
Modules per rack	max. 8

Technical Data	
Number of DP masters	
• Integrated	None
• Via CP	1
Number of function modules and communication processors you can operate	
• FM	max. 8
• CP (PtP)	max. 8
• CP (LAN)	max. 4
Time-of-day	
Realtime clock	yes (SW clock)
• Buffered	No
• Accuracy	Deviation per day < 15 s
Operating hours counter	1
• Number	0
• Range of values	2^{31} (if SFC 101 is used)
• Granularity	1 hour
• Retentive	yes; must be manually restarted after every restart
Clock synchronization	Yes
• In the PLC	Master
• On MPI	Master/slave
S7 signaling functions	
Number of stations that can log in for signaling functions (e.g. OS)	6 (depends on the number of connections configured for PG / OP and S7 basic communication)
Process diagnostic messages	Yes
• Simultaneously enabled interrupt S blocks	max. 20
Testing and commissioning functions	
Status/controlling of variables	Yes
• Variable	Inputs, outputs, flags, DBs, timers, counters
• Number of variables	30
Of those as status variable	30
Of those as control variable	14
Forcing	Yes
• Variable	Inputs, outputs
• Number of variables	max. 10
Status block	Yes
Single-step	Yes
Breakpoints	2

Technical Data	
Diagnostic buffer	Yes
• Number of entries (not configurable)	max. 100
Communication functions	
PG/OP communication	Yes
Global data communication	Yes
• Number of GD circuits	4
• Number of GD packets	max. 4
Sending stations	max. 4
Receiving stations	max. 4
• Size of GD packets	max. 22 bytes
Consistent data	22 bytes
S7-based communication	Yes
• Rser data per job	max. 76 bytes
Consistent data	76 bytes (for X_SEND or X_RCV)
	64 bytes (for X_PUT or X_GET as the server)
S7 communication	
• As server	Yes
• User data per job	max. 180 bytes (with PUT/GET)
Consistent data	64 bytes
S5-compatible communication	Yes (via CP and loadable FCs)
Number of connections	max. 6
can be used for	
• PG communication	max. 5
Reserved (Default)	1
Configurable	from 1 to 5
• OP communication	max. 5
Reserved (Default)	1
Configurable	from 1 to 5
• S7-based communication	
Reserved (Default)	2
Configurable	0 to 2
Routing	No
Interfaces	
1st interface	
Type of interface	Integrated RS485 interface
Physics	RS485
Electrically isolated	No
Interface power supply (15 VDC to 30 VDC)	max. 200 mA

Technical Data	
Functionality	
• MPI	Yes
• PROFIBUS-DP	No
• PtP communication	No
MPI	
Number of connections	6
Services	
• PG/OP communication	Yes
• Routing	No
• Global data communication	Yes
• S7-based communication	Yes
• S7 communication	
As server	Yes
As Client	No
• Transmission rates	187.5 Kbps
Programming	
Programming language	LAD/FBD/STL
Available instructions	See the Instruction List
Nesting levels	8
System functions (SFCs)	See the Instruction List
System function blocks (SFBs)	See the Instruction List
user program security	Yes
Dimensions	
Mounting dimensions W x H x D (mm)	40 x 125 x 130
Weight	270 g
Voltages and currents	
Power supply (nominal value)	24 VDC
• Permitted range	20.4 V to 28.8 V
Current consumption (no-load operation)	normally 60 mA
Inrush current	normally 2.5 A
I^2t	0.5 A^2s
External fusing of power supply lines (recommended)	min. 2 A
Power loss	normally 2.5 W

6.2   CPU 312C

Technical Data

Table 6-2   Technical Data for CPU 312C

Technical Data	
CPU and version	
MLFB	6ES7 312-5BD01-0AB0
• Hardware version	01
• Firmware version	V2.0
• Associated programming package	STEP 7 V 5.2 or later
	(please use previous CPU for STEP 7 V 5.1 + SP 3 or later)
Memory	
RAM	
• Integrated	16 KB
• Expandable	No
Load memory	Plugged in with MMC (max. 4 MB)
Buffering	Guaranteed by MMC (maintenance-free)
Processing times	
Processing times for	
• Bit operations	Min. 0.2 µs
• Word instructions	Min. 0.4 µs
• Fixed-point arithmetic	Min. 5 µs
• Floating-point arithmetic	Min. 6 µs
Timers/counters and their retentivity	
S7 counters	128
• Retentive memory	Configurable
• Default	from C0 to C7
• Counting range	0 to 999
IEC Counters	Yes
• Type	SFB
• Number	unlimited (limited only by RAM size)
S7 timers	128
• Retentive memory	Configurable
• Default	Not retentive
• Timer range	10 ms to 9990 s
IEC Timers	Yes

Technical Data	
• Type	SFB
• Number	unlimited (limited only by RAM size)
Data areas and their retentivity	
Total retentive data area (includes flag bits; timers; counters)	All
Flag bits	128 bytes
• Retentive memory	Configurable
• Default retentivity	MB0 to MB15
Clock flag bits	8 (1 byte per flag bit)
Data blocks	max. 511 (DB 1 to DB 511)
• Size	max. 16 KB
Local data per priority class	max. 256 bytes
Blocks	
Total	1024 (DBs, FCs, FBs)
Obs	See the Instruction List
• Size	max. 16 KB
Nesting depth	
• Per priority class	8
• Additional within an error OB	4
FBs	max. 512 (FB 0 to FB 511)
• Size	max. 16 KB
FCs	max. 512 (FC 0 to FC 511)
• Size	max. 16 KB
Address areas (I/Os)	
Total I/O address area	max. 1024 bytes/1024 bytes (can be freely addressed)
I/O process image	128 bytes/128 bytes
Digital channels	max. 256
• Of those local	max. 256
• Integrated channels	10 DI / 6 DO
Analog channels	max. 64
• Of those local	max. 64
• Integrated channels	None
Assembly	
Racks	max. 1
Modules per rack	max. 8
Number of DP masters	
• Integrated	None

Technical Data	
• Via CP	max. 1
Number of function modules and communication processors you can operate	
• FM	max. 8
• CP (PtP)	max. 8
• CP (LAN)	max. 4
Time-of-day	
Realtime clock	yes (SW clock)
• Buffered	No
• Accuracy	Deviation per day < 10 s
Operating hours counter	1
• Number	0
• Range of values	2^{31} hours (if SFC 101 is used)
• Granularity	1 hour
• Retentive	yes; must be manually restarted after every restart
Clock synchronization	Yes
• In the PLC	Master
• On MPI	Master/slave
S7 signaling functions	
Number of stations that can log in for signaling functions (e.g. OS)	max. 6 (depends on the number of connections configured for PG / OP and S7 basic communication)
Process diagnostic messages	Yes
• Simultaneously enabled interrupt S blocks	max. 20
Testing and commissioning functions	
Status/controlling of variables	Yes
• Variable	Inputs, outputs, flags, DBs, timers, counters
• Number of variables	max. 30
Of those as status variable	max. 30
Of those as control variable	max. 14
Forcing	Yes
• Variable	Inputs, outputs
• Number of variables	max. 10
Status block	Yes
Single-step	Yes
Breakpoints	2
Diagnostic buffer	Yes
• Number of entries (not configurable)	max. 100

Technical Data	
Communication functions	
PG/OP communication	Yes
Global data communication	Yes
• Number of GD circuits	4
• Number of GD packets	max. 4
Sending stations	max. 4
Receiving stations	max. 4
• Size of GD packets	max. 22 bytes
Consistent data	22 bytes
S7-based communication	Yes
• User data per job	max. 76 bytes
Consistent data	76 bytes (for X_SEND or X_RCV)
	64 bytes (for X_PUT or X_GET as the server)
S7 communication	
• As server	Yes
• User data per job	max. 180 bytes (with PUT/GET)
Consistent data	64 bytes
S5-compatible communication	Yes (via CP and loadable FCs)
Number of connections	max. 6
can be used for	
• PG communication	max. 5
Reserved (Default)	1
Configurable	from 1 to 5
• OP communication	max. 5
Reserved (Default)	1
Configurable	from 1 to 5
• S7-based communication	max. 2
Reserved (Default)	2
Configurable	from 0 to 2
Routing	No
Interfaces	
1st interface	
Type of interface	integrated RS485 interface
Physics	RS485
Electrically isolated	No
Interface power supply (15 VDC to 30 VDC)	max. 200 mA
Functionality	
• MPI	Yes
• PROFIBUS-DP	No

Technical Data	
• PtP communication	No
MPI	
Number of connections	6
Services	
• PG/OP communication	Yes
• Routing	No
• Global data communication	Yes
• S7-based communication	Yes
• S7 communication	
As server	Yes
As Client	No
• Transmission rates	max. 187.5 kbps
Programming	
Programming language	LAD/FBD/STL
Available instructions	See the Instruction List
Nesting levels	8
System functions (SFCs)	See the Instruction List
System function blocks (SFBs)	See the Instruction List
User program security	Yes
Integrated I/O	
• Default addresses of the integrated	
Digital inputs	DI124.0 to DI125.1
Digital outputs	DO124.0 to DO124.5
Integrated functions	
Counters	2 Channels (see the Manual *Technological Functions*)
Frequency counters	2 channels, up to max. 10 kHz (see the Manual *Technological Functions*)
Pulse outputs	2 channels for pulse width modulation, up to max. 2.5 kHz (see the Manual *Technological Functions*)
Positioning control	No
Integrated "Controlling" SFB	No
Dimensions	
Mounting dimensions W x H x D (mm)	80 x 125 x 130
Weight	409 g
Voltages and currents	
Power supply (nominal value)	24 VDC
• Permitted range	20.4 V to 28.8 V
Current consumption (no-load operation)	typically 60 mA
Inrush current	typically 11 A

Technical Data	
Power consumption (nominal value)	500 mA
I^{2}t	0.7 A^{2}s
External fusing of power supply lines (recommended)	LS switch Type C min. 2 A, LS switch Type B min. 4 A
Power loss	typically 6 W

Cross-reference

In the *Technical data of the integrated I/O* chapter, you can find

- the technical data of integrated I/Os under *Digital inputs of CPUs 31xC* and *Digital outputs of CPUs 31xC*.

- the block diagrams of the integrated I/Os, under *Arrangement and usage of integrated I/Os*.

6.3   CPU 313C

Technical Data

Table 6-3   Technical Data for CPU 313C

Technical Data	
CPU and version	
MLFB	6ES7 313-5BE01-0AB0
• Hardware version	01
• Firmware version	V2.0.0
• Associated programming package	STEP 7 V 5.2 or later (please use previous CPU for STEP 7 V 5.1 + SP 3 or later)
Memory	
RAM	
• Integrated	32 KB
• Expandable	No
Load memory	Plugged in with MMC (max. 8 MB)
Buffering	Guaranteed by MMC (maintenance-free)
Processing times	
Processing times for	
• Bit operations	min. 0.1 µs
• Word instructions	Min. 0.2 µs
• Fixed-point arithmetic	Min. 2 µs

Technical Data	
• Floating-point arithmetic	Min. 6 µs
Timers/counters and their retentivity	
S7 counters	256
• Retentive memory	Configurable
• Default	from C0 to C7
• Counting range	0 to 999
IEC Counters	Yes
• Type	SFB
• Number	unlimited (limited only by RAM size)
S7 timers	256
• Retentive memory	Configurable
• Default	Not retentive
• Timer range	10 ms to 9990 s
IEC Timers	Yes
• Type	SFB
• Number	unlimited (limited only by RAM size)
Data areas and their retentivity	
Total retentive data area (includes flag bits; timers; counters)	All
Flag bits	256 bytes
• Retentive memory	Configurable
• Default retentivity	MB0 to MB15
Clock flag bits	8 (1 byte per flag bit)
Data blocks	max. 511 (DB 1 to DB 511)
• Size	max. 16 KB
Local data per priority class	max. 510 bytes
Blocks	
Total	1024 (DBs, FCs, FBs)
Obs	See the Instruction List
• Size	max. 16 KB
Nesting depth	
• Per priority class	8
• Additional within an error OB	4
FBs	max. 512 (FB 0 to FB 511)
• Size	max. 16 KB
FCs	max. 512 (FC 0 to FC 511)
• Size	max. 16 KB

Technical Data	
Address areas (I/Os)	
Total I/O address area	max. 1024 bytes/1024 bytes (can be freely addressed)
I/O process image	128 bytes/128 bytes
Digital channels	max. 1016
• Of those local	max. 992
• Integrated channels	24 DI / 16 DO
Analog channels	max. 253
• Of those local	max. 248
• Integrated channels	4 + 1 AI / 2 AO
Assembly	
Racks	max. 4
Modules per rack	max. 8; max. 7 in rack 3
Number of DP masters	
• Integrated	None
• Via CP	max. 2
Number of function modules and communication processors you can operate	
• FM	max. 8
• CP (PtP)	max. 8
• CP (LAN)	max. 6
Time-of-day	
Realtime clock	yes (HW clock)
• Buffered	Yes
• Buffered period	Typically 6 weeks (at an ambient temperature of 40 degC)
• Accuracy	Deviation per day < 10 s
Operating hours counter	1
• Number	0
• Range of values	2^{31} hours (if SFC 101 is used)
• Granularity	1 hour
• Retentive	yes; must be manually restarted after every restart
Clock synchronization	Yes
• In the PLC	Master
• On MPI	Master/slave
S7 signaling functions	
Number of stations that can log in for signaling functions (e.g. OS)	max. 8 (depends on the number of connections configured for PG / OP and S7 basic communication)

Technical Data	
Process diagnostic messages	Yes
• Simultaneously enabled interrupt S blocks	max. 20
Testing and commissioning functions	
Status/controlling of variables	Yes
• Variable	Inputs, outputs, flags, DBs, timers, counters
• Number of variables	max. 30
Of those as status variable	max. 30
Of those as control variable	max. 14
Forcing	Yes
• Variable	Inputs, outputs
• Number of variables	max. 10
Status block	Yes
Single-step	Yes
Breakpoints	2
Diagnostic buffer	Yes
• Number of entries (not configurable)	max. 100
Communication functions	
PG/OP communication	Yes
Global data communication	Yes
• Number of GD circuits	4
• Number of GD packets	max. 4
Sending stations	max. 4
Receiving stations	max. 4
• Size of GD packets	max. 22 bytes
Consistent data	22 bytes
S7-based communication	Yes
• User data per job	max. 76 bytes
Consistent data	76 bytes (for X_SEND or X_RCV)
	64 bytes (for X_PUT or X_GET as the server)
S7 communication	
• As server	Yes
• As Client	Yes (via CP and loadable FBs)
• User data per job	max. 180 bytes (with PUT/GET)
Consistent data	64 bytes
S5-compatible communication	Yes (via CP and loadable FCs)
Number of connections	max. 8
can be used for	
• PG communication	max. 7
Reserved (Default)	1

Technical Data	
Configurable	from 1 to 7
• OP communication	max. 7
Reserved (Default)	1
Configurable	from 1 to 7
• S7-based communication	max. 4
Reserved (Default)	4
Configurable	from 0 to 4
Routing	No
Interfaces	
1st interface	
Type of interface	Integrated RS485 interface
Physics	RS485
Electrically isolated	No
Interface power supply (15 VDC to 30 VDC)	max. 200 mA
Functionality	
• MPI	Yes
• PROFIBUS-DP	No
• PtP communication	No
MPI	
Number of connections	8
Services	
• PG/OP communication	Yes
• Routing	No
• Global data communication	Yes
• S7-based communication	Yes
• S7 communication	
As server	Yes
As Client	Yes (via CP and loadable FBs)
• Transmission rates	max. 187.5 kbps
Programming	
Programming language	LAD/FBD/STL
Available instructions	See the Instruction List
Nesting levels	8
System functions (SFCs)	See the Instruction List
System function blocks (SFBs)	See the Instruction List
User program security	Yes
Integrated I/O	
• Default addresses of the integrated	
Digital inputs	124.0 to 126.7
Digital outputs	124.0 to 125.7

Technical Data	
Analog inputs	752 to 761
Analog outputs	752 to 755
Integrated functions	
Counters	3 channels (see the Manual *Technological Functions*)
Frequency counters	3 channels, max. 30 kHz (see the Manual *Technological Functions*)
Pulse outputs	3 channels for pulse width modulation, up to max. 2.5 kHz (see the Manual *Technological Functions*)
Positioning control	No
Integrated "Controlling" SFB	PID controller (see the Manual *Technological Functions*)
Dimensions	
Mounting dimensions W x H x D (mm)	120 x 125 x 130
Weight	660 g
Voltages and currents	
Power supply (nominal value)	24 VDC
• Permitted range	20.4 V to 28.8 V
Current consumption (no-load operation)	typically 150 mA
Inrush current	typically 11 A
Power consumption (nominal value)	700 mA
I^2t	0.7 A^2s
External fusing of power supply lines (recommended)	LS switch Type C min. 2 A, LS switch Type B min. 4 A
Power loss	typically 14 W

Cross-reference

In the *Technical data of the integrated I/O* chapter, you can find

- the technical data of integrated I/O under *Digital inputs of CPUs 31xC*, *Digital outputs of CPUs 31xC, Analog inputs of CPUs 31xC* and *Analog outputs of CPUs 31xC*.

- the block diagrams of the integrated I/Os, under *Arrangement and usage of integrated I/Os*.

6.4   CPU 313C-2 PtP and CPU 313C-2 DP

Technical Data

Table 6-4   Technical data for CPU 313C-2 PtP/ CPU 313C-2 DP

Technical Data		
CPU and version	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
MLFB	6ES7 313-6BE01-0AB0	6ES7 313-6CE01-0AB0
• Hardware version	01	01
• Firmware version	V2.0.0	V2.0.0
Associated programming package	STEP 7 V 5.2 or later (please use previous CPU for STEP 7 V 5.1 + SP 3 or later)	STEP 7 V 5.2 or later (please use previous CPU for STEP 7 V 5.1 + SP 3 or later)
Memory	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
RAM		
• Integrated	32 KB	
• Expandable	No	
Load memory	Plugged in with MMC (max. 8 MB)	
Buffering	Guaranteed by MMC (maintenance-free)	
Processing times	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Processing times for		
• Bit operations	min. 0.1 µs	
• Word instructions	Min. 0.2 µs	
• Fixed-point arithmetic	Min. 2 µs	
• Floating-point arithmetic	Min. 6 µs	
Timers/counters and their retentivity	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
S7 counters	256	
• Retentive memory	Configurable	
• Default	from C0 to C7	
• Counting range	0 to 999	
IEC Counters	Yes	
• Type	SFB	
• Number	Unlimited (limited only by RAM size)	
S7 timers	256	
• Retentive memory	Configurable	
• Default	Not retentive	
• Timer range	10 ms to 9990 s	
IEC Timers	Yes	
• Type	SFB	
• Number	Unlimited (limited only by RAM size)	

Technical Data		
Data areas and their retentivity	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Total retentive data area (includes flag bits; timers; counters)	All	
Flag bits	256 bytes	
• Retentive memory	Configurable	
• Default retentivity	MB0 to MB15	
Clock flag bits	8 (1 byte per flag bit)	
Data blocks	max. 511 (DB 1 to DB 511)	
• Size	max. 16 KB	
Local data per priority class	max. 510 bytes	
Blocks	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Total	1024 (DBs, FCs, FBs)	
OBs	See the Instruction List	
• Size	max. 16 KB	
Nesting depth		
• Per priority class	8	
• Additional within an error OB	4	
FBs	max. 512 (FB 0 to FB 511)	
• Size	max. 16 KB	
FCs	max. 512 (FC 0 to FC 511)	
• Size	max. 16 KB	
Address areas (I/Os)	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Total I/O address area	max. 1024 bytes/1024 bytes (can be freely addressed)	max. 1024 bytes/1024 bytes (can be freely addressed)
• Distributed	None	max. 1008 bytes
I/O process image	128 bytes/128 bytes	128 bytes/128 bytes
Digital channels	max. 1008	max. 8192
• Of those local	max. 992	max. 992
• Integrated channels	16 DI / 16 DO	16 DI / 16 DO
Analog channels	max. 248	max. 512
• Of those local	max. 248	max. 248
• Integrated channels	None	None
Assembly	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Racks	max. 4	
Modules per rack	max. 8; max. 7 in rack 3	
Number of DP masters		
• Integrated	No	1
• Via CP	max. 1	max. 1

Technical Data		
Number of function modules and communication processors you can operate		
• FM	max. 8	
• CP (PtP)	max. 8	
• CP (LAN)	max. 6	
Time-of-day	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Realtime clock	yes (HW clock)	
• Buffered	Yes	
• Buffered period	Typically 6 weeks (at an ambient temperature of 40 degC)	
• Accuracy	Deviation per day < 10 s	
Operating hours counter	1	
• Number	0	
• Range of values	2^{31} hours (if SFC 101 is used)	
• Granularity	1 hour	
• Retentive	yes; must be manually restarted after every restart	
Clock synchronization	Yes	
• In the PLC	Master	
• On MPI	Master/slave	
S7 signaling functions	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Number of stations that can log in for signaling functions (e.g. OS)	max. 8 (depends on the number of connections configured for PG / OP and S7 basic communication)	
Process diagnostic messages	Yes	
• Simultaneously enabled interrupt S blocks	max. 20	
Testing and commissioning functions	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Status/controlling of variables	Yes	
• Variable	Inputs, outputs, flags, DBs, timers, counters	
• Number of variables	max. 30	
Of those as status variable	max. 30	
Of those as control variable	max. 14	
Forcing	Yes	
• Variable	Inputs, outputs	
• Number of variables	max. 10	
Status block	Yes	
Single-step	Yes	
Breakpoints	2	
Diagnostic buffer	Yes	
• Number of entries (not	max. 100	

Technical Data		
configurable)		
Communication functions	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
PG/OP communication	Yes	
Global data communication	Yes	
• Number of GD circuits	4	
• Number of GD packets	max. 4	
Sending stations	max. 4	
Receiving stations	max. 4	
• Size of GD packets	max. 22 bytes	
Consistent data	22 bytes	
S7-based communication	Yes (server)	
• User data per job	max. 76 bytes	
Consistent data	76 bytes (for X_SEND or X_RCV)	
	64 bytes (for X_PUT or X_GET as the server)	
S7 communication		
• As server	Yes	
• As Client	Yes (via CP and loadable FBs)	
• User data per job	max. 180 bytes (with PUT/GET)	
Consistent data	64 bytes	
S5-compatible communication	Yes (via CP and loadable FCs)	
Number of connections	max. 8	
can be used for		
• PG communication	max. 7	
Reserved (Default)	1	
Configurable	from 1 to 7	
• OP communication	max. 7	
Reserved (Default)	1	
Configurable	from 1 to 7	
• S7-based communication	max. 4	
Reserved (Default)	4	
Configurable	from 0 to 4	
Routing	No	max. 4
Interfaces	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
1st interface		
Type of interface	Integrated RS485 interface	
Physics	RS485	
Electrically isolated	No	
Interface power supply (15 VDC to 30 VDC)	max. 200 mA	
Functionality		
• MPI	Yes	

Technical Data		
• PROFIBUS-DP	No	
• PtP communication	No	
MPI		
Number of connections	8	
Services		
• PG/OP communication	Yes	
• Routing	No	Yes
• Global data communication	Yes	
• S7-based communication	Yes	
• S7 communication		
As server	Yes	
As Client	Yes (via CP and loadable FBs)	
• Transmission rates	max. 187.5 kbps	
2nd interface	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Type of interface	Integrated RS422/RS485 interface	integrated RS485 interface
Physics	RS 422/485	RS485
Electrically isolated	Yes	Yes
Interface power supply (15 VDC to 30 VDC)	No	max. 200 mA
Number of connections	None	8
Functionality		
• MPI	No	No
• PROFIBUS-DP	No	Yes
• PtP communication	Yes	No
DP master		
Number of connections	–	8
Services		
• PG/OP communication	–	Yes
• Routing	–	Yes
• Global data communication	–	No
• S7-based communication	–	No
• S7 communication	–	No
• Equidistance	–	Yes
• SYNC/FREEZE	–	Yes
• Enable/disable DP slaves	–	Yes
• DPV1	–	Yes
• Transmission rates	–	Up to 12 Mbps
• Number of DP slaves per station	–	max. 32;
• Address area	–	max. 1 KB I / 1 KB O

Technical Data		
• User data per DP slave	–	max. 244 bytes I / 244 bytes O
DP Slave		
Number of connections	–	8
Services		
• PG/OP communication	–	Yes
• Routing	–	Yes (only if interface is active)
• Global data communication	–	No
• S7-based communication	–	No
• S7 communication	–	No
• Direct data exchange	–	Yes
• Transmission rates	–	Up to 12 Mbps
• Automatic baud rate search	–	Yes (only if interface is passive)
• Transfer memory	–	244 bytes I / 244 bytes O
• Address areas	–	max. 32 with max. 32 bytes each
• DPV1	–	No
GSD file	–	The latest GSD file is available at: http://www.ad.siemens.de/support in the Product Support area
Point-to-Point communication		
• Transmission rates	38.4 kbps half duplex 19.2 kbps full duplex	–
• Cable length	max. 1200 m	–
• The user program can control the interface	Yes	–
• The interface can trigger a break or an interrupt in the user program	Yes (message with break ID)	–
• Protocol driver	3964(R); ASCII	–
Programming	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Programming language	LAD/FBD/STL	
Available instructions	See the Instruction List	
Nesting levels	8	
System functions (SFCs)	See the Instruction List	
System function blocks (SFBs)	See the Instruction List	
User program security	Yes	
Integrated I/O	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
• Default addresses of the integrated		
Digital inputs	124.0 to 125.7	
Digital outputs	124.0 to 125.7	

Technical Data		
Integrated functions		
Counters	3 channels (see the Manual *Technological Functions*)	
Frequency counters	3 channels, max. 30 kHz (see the Manual *Technological Functions*)	
Pulse outputs	3 channels for pulse width modulation, up to max. 2.5 kHz (see the Manual *Technological Functions*)	
Positioning control	No	
Integrated "Controlling" SFB	PID controller (see the Manual *Technological Functions*)	
Dimensions	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Mounting dimensions W x H x D (mm)	120 x 125 x 130	
Weight	Approx. 566 g	
Voltages and currents	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
Power supply (nominal value)	24 VDC	
• Permitted range	20.4 V to 28.8 V	
Current consumption (no-load operation)	Typically 100 mA	
Inrush current	Typically 11 A	
Power consumption (nominal value)	700 mA	900 mA
I^2t	0.7 A^2s	
External fusing of power supply lines (recommended)	LS switch Type C min. 2 A, type B min. 4 A	
Power loss	Typically 10 W	
Standards and Approvals	**CPU 313C-2 PtP**	**CPU 313C-2 DP**
PNO certificate		
• DP Master	–	
• DP Slave	–	

Cross-reference

In the *Technical data of the integrated I/O* chapter, you can find

- the technical data of integrated I/Os under *Digital inputs of CPUs 31xC* and *Digital outputs of CPUs 31xC*.

- the block diagrams of the integrated I/Os, under *Arrangement and usage of integrated I/Os*.

6.5   CPU 314

Technical data for the CPU 314

Table 6-5   Technical data for the CPU 314

Technical Data	
CPU and version	
MLFB	6ES7314-1AF10-0AB0
• Hardware version	01
• Firmware version	V 2.0.0
• Associated programming package	STEP 7 as of V 5.1 + SP 4
Memory	
RAM	
• Integrated	48 KB
• Expandable	No
Load memory	Plugged in with MMC (max. 8 MB)
Buffering	Guaranteed by MMC (maintenance-free)
Processing times	
Processing times for	
• Bit operations	min. 0.1 μs
• Word instructions	Min. 0.2 μs
• Fixed-point arithmetic	Min. 2.0 μs
• Floating-point arithmetic	Min. 6 μs
Timers/counters and their retentivity	
S7 counters	256
• Retentive memory	Configurable
• Default	from C0 to C7
• Counting range	0 to 999
IEC Counters	Yes
• Type	SFB
• Number	unlimited (limited only by RAM size)
S7 timers	256
• Retentive memory	Configurable
• Default	Not retentive
• Timer range	10 ms to 9990 s
IEC Timers	Yes
• Type	SFB
• Number	unlimited (limited only by RAM size)
Data areas and their retentivity	
Total retentive data area (includes flag bits; timers; counters)	All

Technical Data	
flag bits	256 bytes
• Retentive memory	Yes
• Default retentivity	MB0 to MB15
Clock flag bits	8 (1 byte per flag bit)
Data blocks	
• Number	511 (DB 1 to DB 511)
• Size	16 KB
Local data per priority class	max. 512
Blocks	
Total	1024 (DBs, FCs, FBs)
Obs	See the Instruction List
• Size	16 KB
Nesting depth	
• Per priority class	8
• Additional within an error OB	4
FBs	See the Instruction List
• Number	512 (FB 0 to FB 511)
• Size	16 KB
FCs	See the Instruction List
• Number	512 (FC 0 to FC 511)
• Size	16 KB
Address areas (I/Os)	
Total I/O address area	max. 1024 bytes/1024 bytes (can be freely addressed)
I/O process image	128 bytes/128 bytes
Digital channels	max. 1024
of those local	max. 1024
Analog channels	max. 256
of those local	max. 256
Assembly	
Racks	max. 4
Modules per rack	8
Number of DP masters	
• Integrated	None
• Via CP	max. 1
Number of function modules and communication processors you can operate	
• FM	max. 8

Technical Data	
• CP (PtP)	max. 8
• CP (LAN)	max. 10
Time-of-day	
Realtime clock	yes (HW clock)
• Buffered	Yes
• Buffered period	normally 6 weeks (at an ambient temperature of 40 degC)
• Accuracy	Deviation per day: < 10 s
Operating hours counter	1
• Number	0
• Range of values	2^{31} hours (if SFC 101 is used)
• Granularity	1 hour
• Retentive	yes; must be manually restarted after every restart
Clock synchronization	Yes
• In the PLC	Master/slave
• On MPI	Slave
S7 signaling functions	
Number of stations that can log in for signaling functions (e.g. OS)	12 (depends on the number of connections configured for PG / OP and S7 basic communication)
Process diagnostic messages	Yes
• Simultaneously enabled interrupt S blocks	max. 40
Testing and commissioning functions	
Status/controlling of variables	Yes
• Variable	Inputs, outputs, flags, DBs, timers, counters
• Number of variables	30
Of those as status variable	30
Of those as control variable	14
Forcing	Yes
• Variable	Inputs / Outputs
• Number of variables	max. 10
Status block	Yes
Single-step	Yes
Breakpoints	
Diagnostic buffer	Yes
• Number of entries (not configurable)	max. 100
Communication functions	

Technical Data	
PG/OP communication	Yes
Global data communication	Yes
• Number of GD circuits	4
• Number of GD packets	max. 4
Sending stations	max. 4
Receiving stations	max. 4
• Size of GD packets	max. 22 bytes
Consistent data	22 bytes
S7-based communication	Yes
• User data per job	max. 76 bytes
Consistent data	76 bytes (for X_SEND or X_RCV)
	64 bytes (for X_PUT or X_GET as the server)
S7 communication	Yes
• As server	Yes
• As Client	Yes (via CP and loadable FBs)
• User data per job	max. 180 (for PUT/GET)
Consistent data	64 bytes
S5-compatible communication	Yes (via CP and loadable FCs)
Number of connections	12
can be used for	
• PG communication	
Reserved (Default)	1
Configurable	1 to 11
• OP communication	
Reserved (Default)	1
Configurable	1 to 11
• S7-based communication	
Reserved (Default)	8
Configurable	0 to 8
Routing	No
Interfaces	
1st interface	
Type of interface	Integrated RS485 interface
Physics	RS485
Electrically isolated	No
Interface power supply (15 VDC to 30 VDC)	max. 200 mA
Functionality	
• MPI	Yes
• PROFIBUS-DP	No

Technical Data	
• PtP communication	No
MPI	
Number of connections	12
Services	
• PG/OP communication	Yes
• Routing	No
• Global data communication	Yes
• S7-based communication	Yes
• S7 communication	Yes
As server	Yes
As Client	Yes (via CP and loadable FBs)
• Transmission rates	187.5 Kbps
Programming	
Programming language	LAD/FBD/STL
Available instructions	See the Instruction List
Nesting levels	8
System functions (SFCs)	See the Instruction List
System function blocks (SFBs)	See the Instruction List
User program security	Yes
Dimensions	
Mounting dimensions W x H x D (mm)	40 x 125 x 130
Weight	280 g
Voltages and currents	
Power supply (nominal value)	24 VDC
• Permitted range	20.4 V to 28.8 V
Current consumption (no-load operation)	normally 60 mA
Inrush current	normally 2.5 A
I^2t	0.5 A^2s
External fusing of power supply lines (recommended)	min. 2 A
Power loss	typically 2.5 W

6.6 CPU 314C-2 PtP and CPU 314C-2 DP

Technical Data

Table 6-6   Technical data for the CPU 314C-2 PtP and CPU 314C-2 DP

Technical Data		
CPU and version	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
MLFB	6ES7 314-6BF01-0AB0	6ES7 314-6CF01-0AB0
• Hardware version	01	01
• Firmware version	V2.0.0	V2.0.0
Associated programming package	STEP 7 V 5.2 or later (please use previous CPU for STEP 7 V 5.1 + SP 3 or later)	STEP 7 V 5.2 or later (please use previous CPU for STEP 7 V 5.1 + SP 3 or later)
Memory	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
RAM		
• Integrated	48 KB	
• Expandable	No	
Load memory	Plugged in with MMC (max. 4 MB)	
Buffering	Guaranteed by MMC (maintenance-free)	
Processing times	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Processing times for		
• Bit operations	min. 0.1 μs	
• Word instructions	Min. 0.2 μs	
• Fixed-point arithmetic	Min. 2 μs	
• Floating-point arithmetic	Min. 6 μs	
Timers/counters and their retentivity	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
S7 counters	256	
• Retentive memory	Configurable	
• Default	from C0 to C7	
• Counting range	0 to 999	
IEC Counters	Yes	
• Type	SFB	
• Number	Unlimited (limited only by RAM size)	
S7 timers	256	
• Retentive memory	Configurable	
• Default	Not retentive	
• Timer range	10 ms to 9990 s	
IEC Timers	Yes	
• Type	SFB	
• Number	Unlimited (limited only by RAM size)	

Technical Data		
Data areas and their retentivity	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Total retentive data area (includes flag bits; timers; counters)	All	
Flag bits	256 bytes	
• Retentive memory	Configurable	
• Default retentivity	MB0 to MB15	
Clock flag bits	8 (1 byte per flag bit)	
Data blocks	max. 511 (DB 1 to DB 511)	
• Size	max. 16 KB	
Local data per priority class	max. 512 bytes	
Blocks	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Total	1024 (DBs, FCs, FBs)	
OBs	See the Instruction List	
• Size	max. 16 KB	
Nesting depth		
• Per priority class	8	
• Additional within an error OB	4	
FBs	max. 512 (FB 0 to FB 511)	
• Size	max. 16 KB	
FCs	max. 512 (FC 0 to FC 511)	
• Size	max. 16 KB	
Address areas (I/Os)	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Total I/O address area	max. 1024 bytes/1024 bytes (can be freely addressed)	max. 1024 bytes/1024 bytes (can be freely addressed)
• Distributed	None	max. 1,000 bytes
I/O process image	128 bytes/128 bytes	128 bytes/128 bytes
Digital channels	max. 1016	max. 8192
• Of those local	max. 992	max. 992
• Integrated channels	24 DI / 16 DO	24 DI / 16 DO
Analog channels	max. 253	max. 512
• Of those local	max. 248	max. 248
• Integrated channels	4 + 1 AI / 2 AO	4 + 1 AI / 2 AO
Assembly	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Racks	max. 4	
Modules per rack	max. 8; max. 7 in rack 3	
Number of DP masters		
• Integrated	No	1

Technical Data		
• Via CP	max. 1	max. 1
Number of function modules and communication processors you can operate		
• FM	max. 8	
• CP (PtP)	max. 8	
• CP (LAN)	max. 10	
Time-of-day	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Realtime clock	yes (HW clock)	
• Buffered	Yes	
• Buffered period	Typically 6 weeks (at an ambient temperature of 40 degC)	
• Accuracy	Deviation per day < 10 s	
Operating hours counter	1	
• Number	0	
• Range of values	2^{31} hours (if SFC 101 is used)	
• Granularity	1 hour	
• Retentive	yes; must be manually restarted after every restart	
Clock synchronization	Yes	
• In the PLC	Master	
• On MPI	Master/slave	
S7 signaling functions	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Number of stations that can log in for signaling functions (e.g. OS)	max. 12 (depends on the number of connections configured for PG / OP and S7 basic communication)	
Process diagnostic messages	Yes	
• Simultaneously enabled interrupt S blocks	max. 40	
Testing and commissioning functions	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Status/controlling of variables	Yes	
• Variable	Inputs, outputs, flags, DBs, timers, counters	
• Number of variables	max. 30	
Of those as status variable	max. 30	
Of those as control variable	max. 14	
Forcing	Yes	
• Variable	Inputs, outputs	
• Number of variables	max. 10	
Status block	Yes	
Single-step	Yes	
Breakpoints	2	

Technical Data		
Diagnostic buffer	Yes	
• Number of entries (not configurable)	max. 100	
Communication functions	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
PG/OP communication	Yes	
Global data communication	Yes	
• Number of GD circuits	4	
• Number of GD packets	max. 4	
Sending stations	max. 4	
Receiving stations	max. 4	
• Size of GD packets	max. 22 bytes	
Consistent data	22 bytes	
S7-based communication	Yes	
• User data per job	max. 76 bytes	
Consistent data	76 bytes (for X_SEND or X_RCV) 64 bytes (for X_PUT or X_GET as the server)	
S7 communication		
• As server	Yes	
• As Client	Yes (via CP and loadable FBs)	
• User data per job	max. 180 bytes (with PUT/GET)	
Consistent data	64 bytes	
S5-compatible communication	Yes (via CP and loadable FCs)	
Number of connections	max. 12	
can be used for		
• PG communication	max. 11	
Reserved (Default)	1	
Configurable	from 1 to 11	
• OP communication	max. 11	
Reserved (Default)	1	
Configurable	from 1 to 11	
• S7-based communication	max. 8	
Reserved (Default)	8	
Configurable	from 0 to 8	
Routing	No	max. 4
Interfaces	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
1st interface		
Type of interface	Integrated RS485 interface	
Physics	RS485	
Electrically isolated	No	
Interface power supply (15 VDC to 30 VDC)	max. 200 mA	

Technical Data		
Functionality		
• MPI	Yes	
• PROFIBUS-DP	No	
• PtP communication	No	
MPI		
Number of connections	12	
Services		
• PG/OP communication	Yes	
• Routing	No	Yes
• Global data communication	Yes	
• S7-based communication	Yes	
• S7 communication		
As server	Yes	
As Client	Yes (via CP and loadable FBs)	
• Transmission rates	max. 187.5 kbps	
2nd interface	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Type of interface	Integrated RS422/RS485 interface	integrated RS485 interface
Physics	RS 422/485	RS485
Electrically isolated	Yes	Yes
Interface power supply (15 VDC to 30 VDC)	No	max. 200 mA
Number of connections	None	12
Functionality		
• MPI	No	No
• PROFIBUS-DP	No	Yes
• PtP communication	Yes	No
DP master		
Number of connections	–	12
Services		
• PG/OP communication	–	Yes
• Routing	–	Yes
• Global data communication	–	No
• S7-based communication	–	No
• S7 communication	–	No
• Equidistance	–	Yes
• SYNC/FREEZE	–	Yes
• Enable/disable DP slaves	–	Yes
• DPV1	–	Yes
• Transmission rates	–	Up to 12 Mbps
• Number of DP slaves per	–	max. 32;

Technical Data		
station		
• Address area	–	max. 1 KB I / 1 KB O
• User data per DP slave	–	max. 244 bytes I / 244 bytes O
DP Slave		
Number of connections	–	12
Services		
• PG/OP communication	–	Yes
• Routing	–	Yes (only if interface is active)
• Global data communication	–	No
• S7-based communication	–	No
• S7 communication	–	No
• Direct data exchange	–	Yes
• Transmission rates	–	Up to 12 Mbps
• Transfer memory	–	244 bytes I / 244 bytes O
• Automatic baud rate search	–	Yes (only if interface is passive)
• Address areas		max. 32 with max. 32 bytes each
• DPV1	–	No
GSD file	–	The latest GSD file is available at: http://www.ad.siemens.de/support in the Product Support area
Point-to-Point communication		
• Transmission rates	38.4 kbps half duplex 19.2 kbps full duplex	–
• Cable length	max. 1200 m	–
• The user program can control the interface	Yes	–
• The interface can trigger a break or an interrupt in the user program	Yes (message with break ID)	–
• Protocol driver	3964 (R); ASCII and RK512	–
Programming	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Programming language	LAD/FBD/STL	
Available instructions	See the Instruction List	
Nesting levels	8	
System functions (SFCs)	See the Instruction List	
System function blocks (SFBs)	See the Instruction List	
User program security	Yes	
Integrated I/O	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
• Default addresses of the integrated		
Digital inputs	124.0 to 126.7	

Technical Data		
Digital outputs	124.0 to 125.7	
Analog inputs	752 to 761	
Analog outputs	752 to 755	
Integrated functions		
Counters	4 channels (see the Manual *Technological Functions*)	
Frequency counters	4 channels, up to max. 60 kHz (see the Manual *Technological Functions*)	
Pulse outputs	4 channels for pulse width modulation, up to max. 2.5 kHz (see the Manual *Technological Functions*)	
Positioning control	1 channel (see the Manual *Technological Functions*)	
Integrated "Controlling" SFB	PID controller (see the Manual *Technological Functions*)	
Dimensions	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Mounting dimensions W x H x D (mm)	120 x 125 x 130	
Weight	Approx. 676 g	
Voltages and currents	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
Power supply (nominal value)	24 VDC	
• Permitted range	20.4 V to 28.8 V	
Current consumption (no-load operation)	Typically 150 mA	
Inrush current	Normally 11A	
Power consumption (nominal value)	800 mA	1000 mA
I^2t	0.7 A^2s	
External fusing of power supply lines (recommended)	LS switch Type C min. 2 A, LS switch Type B min. 4 A	
Power loss	Normally 14 W	
Standards and Approvals	**CPU 314C-2 PtP**	**CPU 314C-2 DP**
PNO certificate		
• DP Master	–	
• DP Slave	–	

Cross-reference

In the *Technical data of the integrated I/O* chapter, you can find

- the technical data of integrated I/O under *Digital inputs of CPUs 31xC*, *Digital outputs of CPUs 31xC, Analog inputs of CPUs 31xC* and *Analog outputs of CPUs 31xC*.

- the block diagrams of the integrated I/Os, under *Arrangement and usage of integrated I/Os*.

6.7   CPU 315-2 DP

Technical Data

Table 6-7   Technical Data for CPU 315-2 DP

Technical Data	
CPU and version	
MLFB	6ES7315-2AG10-0AB0
• Hardware version	01
• Firmware version	V 2.0.0
• Associated programming package	STEP 7 as of V 5.1 + SP 4
Memory	
RAM	
• Integrated	128 KB
• Expandable	No
Load memory	Plugged in with MMC (max. 8 MB)
Buffering	Guaranteed by MMC (maintenance-free)
Processing times	
Processing times for	
• Bit operations	min. 0.1 µs
• Word instructions	Min. 0.2 µs
• Fixed-point arithmetic	Min. 2.0 µs
• Floating-point arithmetic	Min. 6 µs
Timers/counters and their retentivity	
S7 counters	256
• Retentive memory	Configurable
• Default	from C0 to C7
• Counting range	0 to 999
IEC Counters	Yes
• Type	SFB
• Number	unlimited (limited only by RAM size)
S7 timers	256
• Retentive memory	Configurable
• Default	Not retentive
• Timer range	10 ms to 9990 s
IEC Timers	Yes
• Type	SFB
• Number	unlimited (limited only by RAM size)
Data areas and their retentivity	
Total retentive data area (includes flag bits; timers; counters)	all

Technical Data	
Flag bits	2048 bytes
• Retentive memory	Yes
• Default retentivity	MB0 to MB15
Clock flag bits	8 (1 byte per flag bit)
Data blocks	
• Number	1023 (DB 1 to DB 1023)
• Size	16 KB
Local data per priority class	max. 1024
Blocks	
Total	1024 (DBs, FCs, FBs)
Obs	See the Instruction List
• Size	16 KB
Nesting depth	
• Per priority class	8
• Additional within an error OB	4
FBs	See the Instruction List
• Number	2048 (FB 0 to FB 2047)
• Size	16 KB
FCs	See the Instruction List
• Number	2048 (FC 0 to FC 2047)
• Size	16 KB
Address areas (I/Os)	
Total I/O address area	max. 2048 bytes/2048 bytes (can be freely addressed)
Distributed	max. 2000
I/O process image	128/128
Digital channels	max. 16384
Of those local	max. 1024
Analog channels	max. 1024
Of those local	max. 256
Assembly	
Racks	max. 4
Modules per rack	8
Number of DP masters	
• Integrated	1
• Via CP	1
Number of function modules and communication processors you can operate	

Technical Data	
• FM	max. 8
• CP (PtP)	max. 8
• CP (LAN)	max. 10
Time-of-day	
Realtime clock	yes (HW clock)
• Buffered	Yes
• Buffered period	normally 6 weeks (at an ambient temperature of 40 degC)
• Accuracy	Deviation per day: < 10 s
Operating hours counter	1
• Number	0
• Range of values	2^{31} hours (if SFC 101 is used)
• Granularity	1 hour
• Retentive	yes; must be manually restarted after every restart
Clock synchronization	Yes
• In the PLC	Master
• On MPI	Master/slave
S7 signaling functions	
Number of stations that can log in for signaling functions (e.g. OS)	16 (depends on the number of connections configured for PG / OP and S7 basic communication)
Process diagnostic messages	Yes
• Simultaneously enabled interrupt S blocks	40
Testing and commissioning functions	
Status/controlling of variables	Yes
• Variable	Inputs, outputs, flags, DBs, timers, counters
• Number of variables	30
Of those as status variable	30
Of those as control variable	14
Forcing	
• Variable	Inputs / Outputs
• Number of variables	max. 10
Status block	Yes
Single-step	Yes
Breakpoints	2
Diagnostic buffer	Yes
• Number of entries (not configurable)	max. 100

Technical Data	
Communication functions	
PG/OP communication	Yes
Global data communication	Yes
• Number of GD circuits	8
• Number of GD packets	max. 8
Sending stations	max. 8
Receiving stations	max. 8
• Size of GD packets	max. 22 bytes
Consistent data	22 bytes
S7-based communication	Yes
• User data per job	max. 76 bytes
Consistent data	76 bytes (for X_SEND or X_RCV) 64 bytes (for X_PUT or X_GET as the server)
S7 communication	Yes
• As server	Yes
• As Client	Yes (via CP and loadable FBs)
• User data per job	max. 180 bytes (with PUT/GET)
Consistent data	64 byte (as the server)
S5-compatible communication	Yes (via CP and loadable FCs)
Number of connections	16
can be used for	
• PG communication	
Reserved (Default)	1
Configurable	1 to 15
• OP communication	
Reserved (Default)	1
Configurable	1 to 15
• S7-based communication	Yes
Reserved (Default)	12
Configurable	0 to 12
Routing	Yes
Interfaces	
1st interface	
Type of interface	Integrated RS485 interface
Physics	RS485
Electrically isolated	No
Interface power supply (15 VDC to 30 VDC)	max. 200 mA
Functionality	
• MPI	Yes

Technical Data	
• PROFIBUS-DP	No
• PtP communication	No
MPI	
Number of connections	16
Services	
• PG/OP communication	Yes
• Routing	Yes
• Global data communication	Yes
• S7-based communication	Yes
• S7 communication	Yes
As server	Yes
As Client	Yes (via CP and loadable FBs)
• Transmission rates	187.5 Kbps
2nd interface	
Type of interface	Integrated RS485 interface
Physics	RS485
Electrically isolated	Yes
Type of interface	Integrated RS485 interface
Interface power supply (15 VDC to 30 VDC)	max. 200 mA
Number of connections	16
Functionality	
MPI	No
PROFIBUS-DP	Yes
PtP communication	No
DP master	
Number of connections	16
Services	
• PG/OP communication	Yes
• Routing	Yes
• Global data communication	No
• S7-based communication	No
• S7 communication	No
• Equidistance	Yes
• SYNC/FREEZE	Yes
• DPV1	Yes
Transmission speed	Up to 12 Mbps
Number of DP slaves per station	125
Address area	max. 244 bytes
DP Slave	
Number of connections	16

Technical Data	
Services	
• PG/OP communication	Yes
• Routing	Yes (only if interface is active)
• Global data communication	No
• S7-based communication	No
• S7 communication	No
• Direct data exchange	Yes
• Transmission rates	Up to 12 Mbps
• Automatic baud rate search	Yes (only if interface is passive)
• Transfer memory	244 bytes I / 244 bytes O
• Address areas	max. 32 with max. 32 bytes each
• DPV1	No
GSD file	New lines in the technical data for DP slave for DP CPUs provide cross-reference to our home page: The latest GSD file is available at: http://www.ad.siemens.de/support in the Product Support area
Programming	
Programming language	LAD/FBD/STL
Available instructions	See the Instruction List
Nesting levels	8
System functions (SFCs)	See the Instruction List
System function blocks (SFBs)	See the Instruction List
User program security	Yes
Dimensions	
Mounting dimensions W x H x D (mm)	40 x 125 x 130
Weight	290 g
Voltages and currents	
Power supply (nominal value)	24 VDC
• Permitted range	20.4 V to 28.8 V
Current consumption (no-load operation)	normally 60 mA
Inrush current	normally 2.5 A
I^2t	0.5 A^2s
External fusing of power supply lines (recommended)	min. 2 A
Power loss	normally 2.5 W

Technical data for integrated I/Os (CPU 31xC only)

7

7.1 Arrangement and usage of integrated I/Os

Introduction

The integrated I/O of 31xC CPUs can be used for technological functions or as standard I/O.

The figures below illustrate possible usage of I/Os integrated in the CPUs.

Further information on integrated I/O is found in the Manual "Technical Functions"

CPU 312C

Standard	Interrupt input	Count		X1
			1 ⌀	
DI	X	C0 (A)	2 ⌀	DI+0.0
DI	X	C0 (B)	3 ⌀	DI+0.1
DI	X	C0 (Hw gate)	4 ⌀	DI+0.2
DI	X	C1 (A)	5 ⌀	DI+0.3
DI	X	C1 (B)	6 ⌀	DI+0.4
DI	X	C1 (HW gate)	7 ⌀	DI+0.5
DI	X	Latch 0	8 ⌀	DI+0.6
DI	X	Latch 1	9 ⌀	DI+0.7
DI	X		10 ⌀	DI+1.0
DI	X		11 ⌀	DI+1.1
			12 ⌀	2 M
			13 ⌀	1L+
DO		V0	14 ⌀	DO+0.0
DO		V1	15 ⌀	DO+0.1
DO			16 ⌀	DO+0.2
DO			17 ⌀	DO+0.3
DO			18 ⌀	DO+0.4
DO			19 ⌀	DO+0.5
			20 ⌀	1 M

Cn	Counter n
A, B	Sensor signals
Cn	Comparator n
X	Pin usable if not occupied be technological functions
HW Gate	Gate control
Latch	Counting status

Figure 7-1 CPU 312C: Pin-out of the integrated DI/DO (Connector X1)
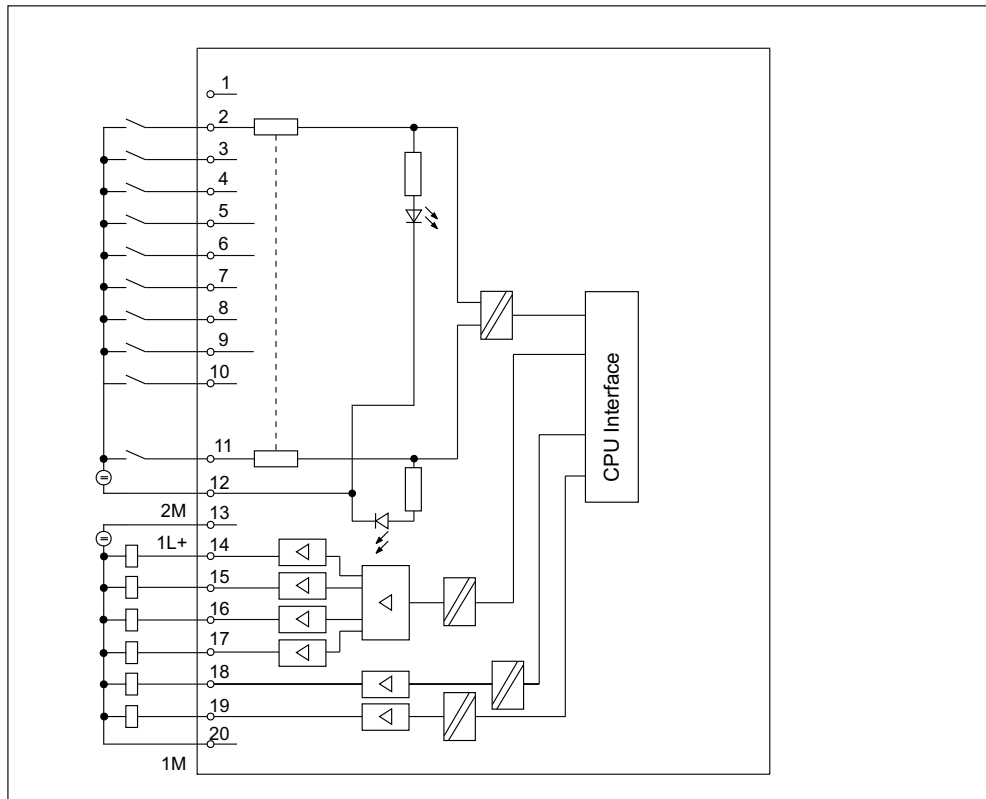
Figure 7-2   Block diagram of the integrated digital I/Os of the CPU 312C

CPU 313C, CPU 313C-2 DP/PtP, CPU 314C-2 DP/PtP

Standard DI	Interrupt input	Count	Posi- tioning 1)		X1 of CPU 313C-2 PtP/DP / X2 of CPU 314C-2 PtP/DP			Positioning 1)		Count	Standard DO
				1 ⌀	1L+	2L+	⌀ 21	digital	analog		
X	X	C0 (A)	A 0	2 ⌀	DI+0.0	DO+0.0	⌀ 22			V0	X
X	X	C0 (B)	B 0	3 ⌀	DI+0.1	DO+0.1	⌀ 23			V1	X
X	X	C0 (Hwgate)	N 0	4 ⌀	DI+0.2	DO+0.2	⌀ 24			V2	X
X	X	C1 (A)	Touch 0	5 ⌀	DI+0.3	DO+0.3	⌀ 25			V3 1)	X
X	X	C1 (B)	Bero 0	6 ⌀	DI+0.4	DO+0.4	⌀ 26				X
X	X	C1 (Hwgate)		7 ⌀	DI+0.5	DO+0.5	⌀ 27				X
X	X	C2 (A)		8 ⌀	DI+0.6	DO+0.6	⌀ 28		CONV_EN		X
X	X	C2 (B)		9 ⌀	DI+0.7	DO+0.7	⌀ 29		CONV_DIR		X
				10 ⌀		2M	⌀ 30				
				11 ⌀		3L+	⌀ 31				
X	X	C2 (Hwgate)		12 ⌀	DI+1.0	DO+1.0	⌀ 32	R+			X
X	X	C3 (A)		13 ⌀	DI+1.1	DO+1.1	⌀ 33	R-			X
X	X	C3 (B)	⎫1)	14 ⌀	DI+1.2	DO+1.2	⌀ 34	Rapid			X
X	X	C3 (Hwgate)	⎬	15 ⌀	DI+1.3	DO+1.3	⌀ 35	Creep			X
X	X	C0 (Latch)		16 ⌀	DI+1.4	DO+1.4	⌀ 36				X
X	X	C1 (Latch)		17 ⌀	DI+1.5	DO+1.5	⌀ 37				X
X	X	C2 (Latch)		18 ⌀	DI+1.6	DO+1.6	⌀ 38				X
X	X	C3 (Latch)	1)	19 ⌀	DI+1.7	DO+1.7	⌀ 39				X
				20 ⌀	1M	3M	⌀ 40				

Cn — Counter n
A, B — Sensor signals
HW Gate — Gate control
Latch — Save counter status
Cn — Comparator n
Touch 0 — Touch probe 0
Bero 0 — Reference-point switch 0
R+, R- — Directional signal
Rapid — Rapid traverse
Creep — Creep speed
CONV_EN — Enable power section
CONV_DIR — Directional signal (only for control mode "Voltage 0 up to10 V or current from 0 to 20 mA and direction signall")
X — Pin usable if not occupied by technological functions

1) only CPU 314C-2

Figure 7-3   CPU 313C/313C-2/314C-2: Pin-out of the integrated DI/DO (Connector X1 and X2)

Details are found in the *Manual "Technical Functions, in the "Counting", "Frequency Measurement" and "Pulse Width Modulation" chapters*
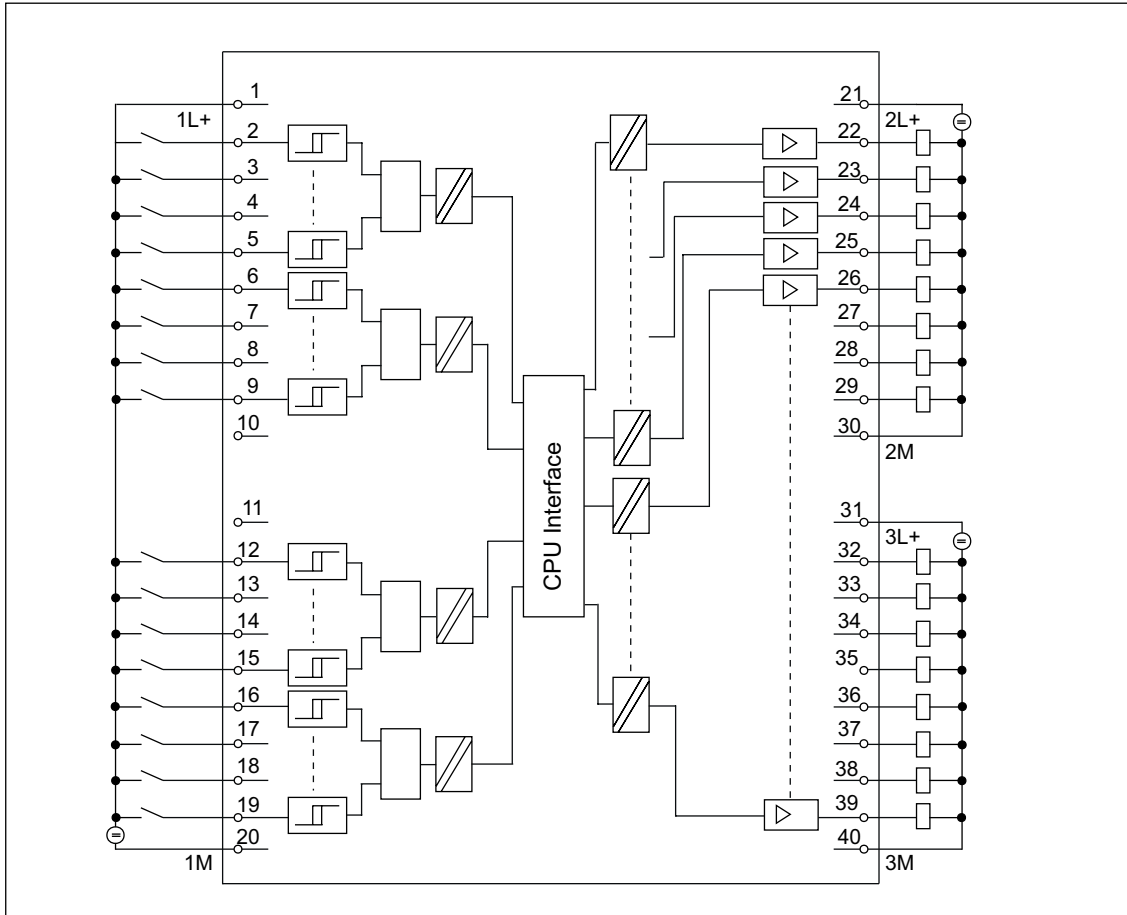
Figure 7-4   Block diagram of integrated digital I/O of CPUs 313C/313C-2/314C-2

Standard		Positioning	1) X1				Standard DI	Input Interrupt
			1 ⊘			⊘ 21		
	V		2 ⊘		DI+2.0	⊘ 22	X	X
AI (Ch0)	I		3 ⊘	PEW x+0	DI+2.1	⊘ 23	X	X
	C		4 ⊘		DI+2.2	⊘ 24	X	X
	V		5 ⊘		DI+2.3	⊘ 25	X	X
AI (Ch1)	I		6 ⊘	PEW x+2	DI+2.4	⊘ 26	X	X
	C		7 ⊘		DI+2.5	⊘ 27	X	X
	V		8 ⊘		DI+2.6	⊘ 28	X	X
AI (Ch2)	I		9 ⊘	PEW x+4	DI+2.7	⊘ 29	X	X
	C		10 ⊘		4M	⊘ 30		
	V		11 ⊘			⊘ 31		
AI (Ch3)	I		12 ⊘	PEW x+6		⊘ 32		
	C		13 ⊘			⊘ 33		
PT 100 (Ch4)			14 ⊘	PEW x+8		⊘ 34		
			15 ⊘			⊘ 35		
AO (Ch0)	V	Manipulated value 0	16 ⊘	PAW x+0		⊘ 36		
	A		17 ⊘			⊘ 37		
AO (Ch1)	V		18 ⊘	PAW x+2		⊘ 38		
	A		19 ⊘			⊘ 39		
			20 ⊘	M$_{ANA}$		⊘ 40		

1) only CPU 314C-2

Figure 7-5   CPUs 313C/314C-2: Pin-out of the integrated AI/AO and DI (Connector X1)
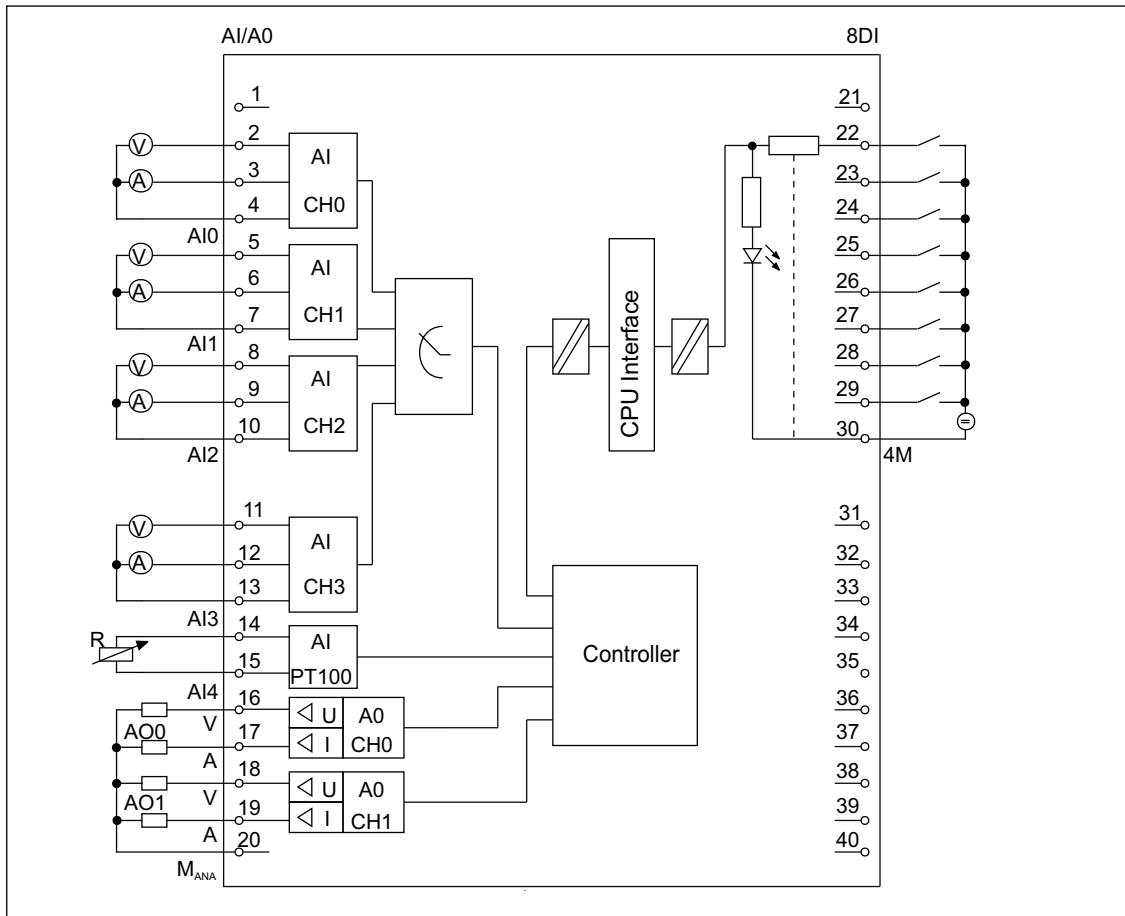
Figure 7-6   Block diagram of integrated digital/analog I/O of CPUs 313C/314C-2

Simultaneous use of technological functions and standard I/O

Technological functions and standard I/O can be used simultaneously with appropriate hardware. For example, you can use all digital inputs not in use by counting functions as standard DI.

Read access to inputs used by technological functions is possible. Write access to outputs used by technological functions is not possible.

Possible effects on CPU performance are described in Chapter *Cycle/Response Times*.

7.2 Analog I/O

Wiring of the current/voltage inputs

The figure below shows the wiring diagram of the current/voltage inputs operated with 2-/4-wire measuring transducers.
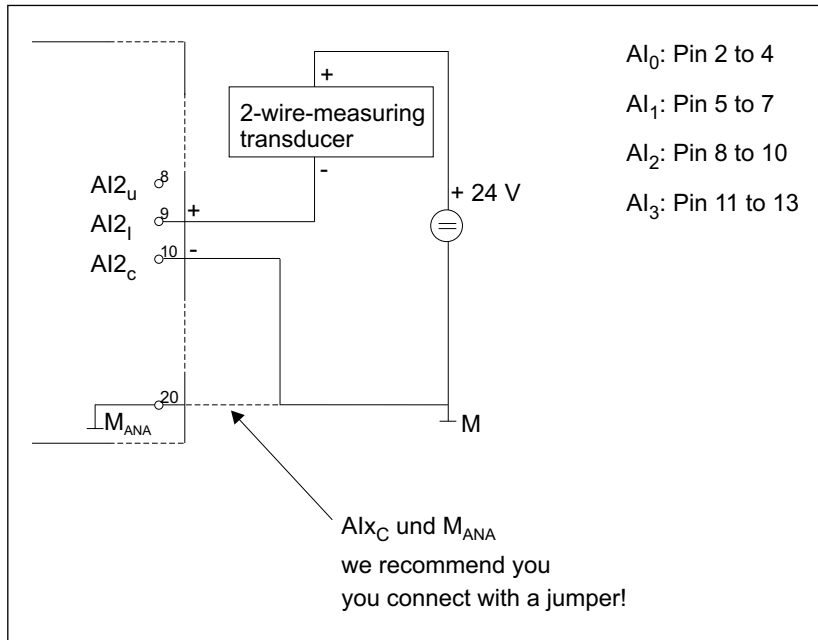
Figure 7-7   Connection of a 2-wire measuring transducer to an analog current/voltage input of CPU 313C/314C-2
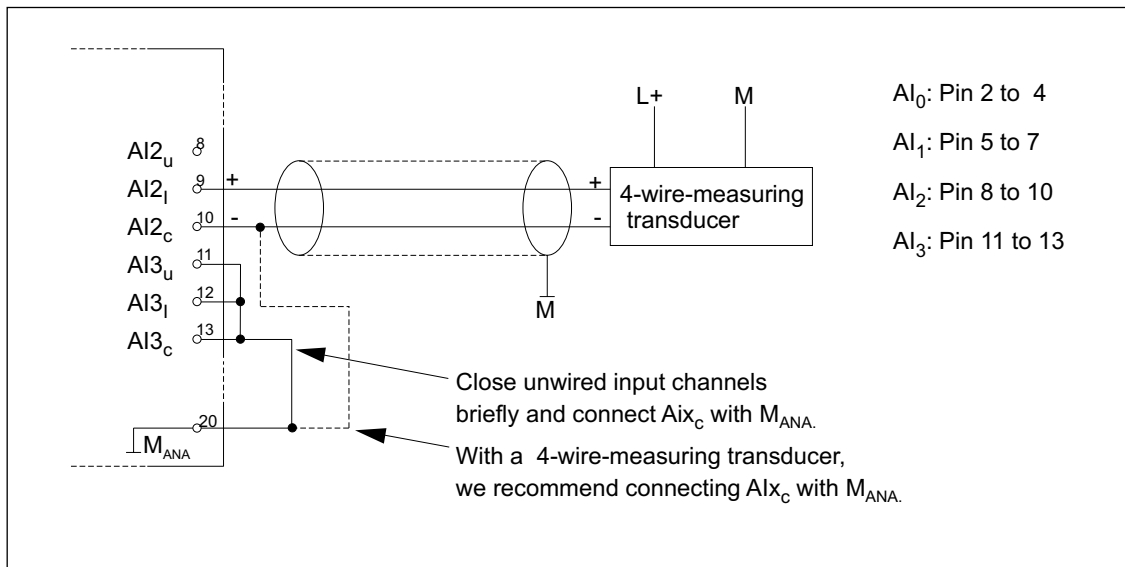
Figure 7-8   Connection of a 4-wire measuring transducer to an analog current/voltage input of
CPU 313C/314C-2

Measurement principle

31xC CPUs use the measurement principle of actual value encoding. Here, they operate with a sampling rate of 1 kHz. That is, a new value is available at the peripheral input word register once every millisecond. This value can then be read via user program (e.g. L PEW). The "old" value is read again if access times are shorter than 1 ms.

Integrated hardware low-pass filter

An integrated low-pass filter attenuates analog input signals of channel 0 to 3. They are attenuated according to the trend in the figure below.
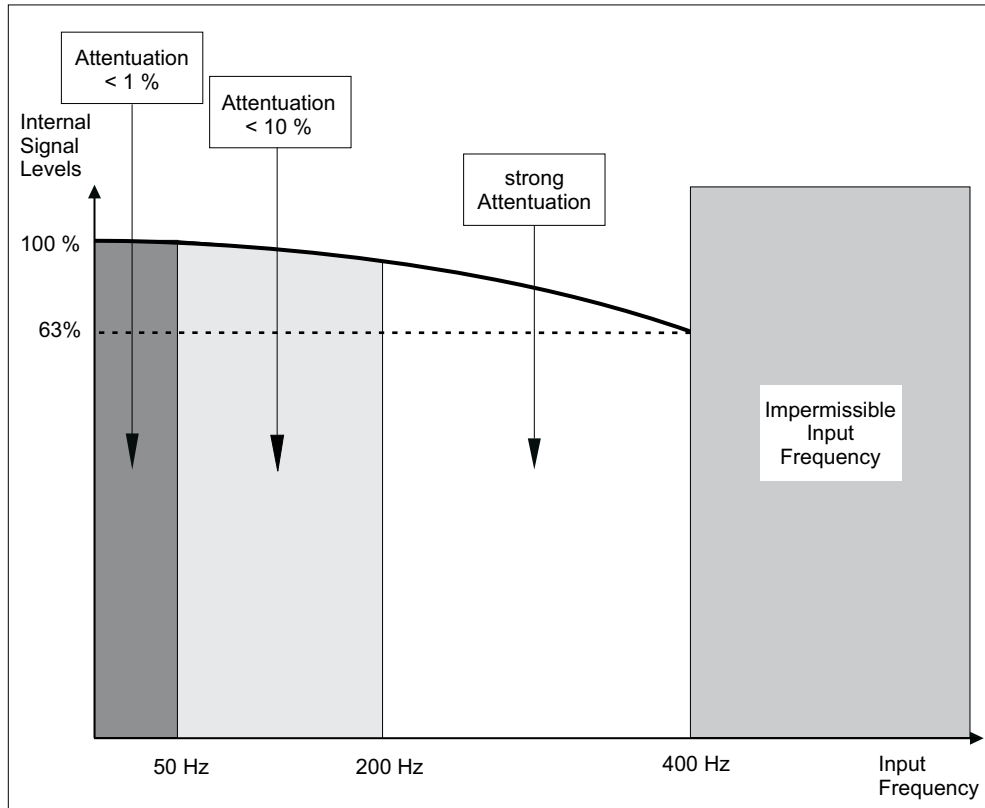
Figure 7-9   Low-pass characteristics of the integrated filter

Note

The maximum frequency of the input signal is 400 Hz.

Input filters (Software filter)

The current / voltage inputs have a software filter for the input signals that can be programmed with STEP 7. It filters the configured interference frequency (50/60 Hz) and multiples thereof.

The selected interference suppression also determines the integration time. At an interference suppression of 50 Hz the software filter forms the average based on the last 20 measurements and saves the result as measurement value.

You can suppress interference frequencies (50 Hz or 60 Hz) according to the parameters set in STEP 7. A setting of 400 Hz will not suppress interference.

An integrated low-pass filter attenuates analog input signals of channel 0 to 3.
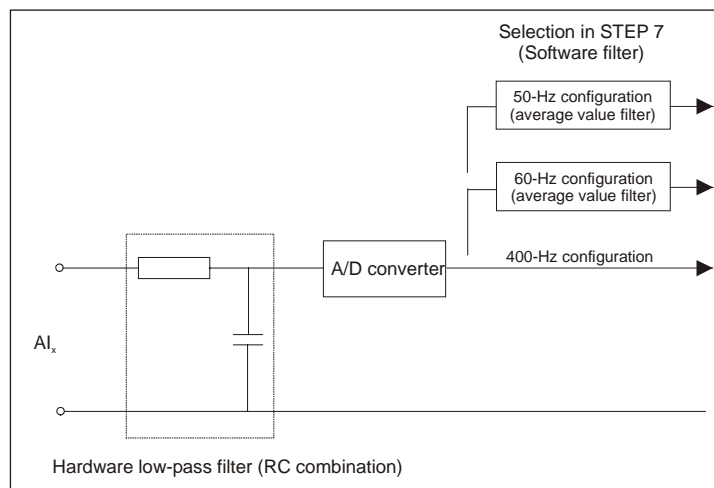
Figure 7-10 Principle of interference suppression with STEP 7

In the two graphics below we illustrate how the 50 Hz and 60 Hz interference suppression work
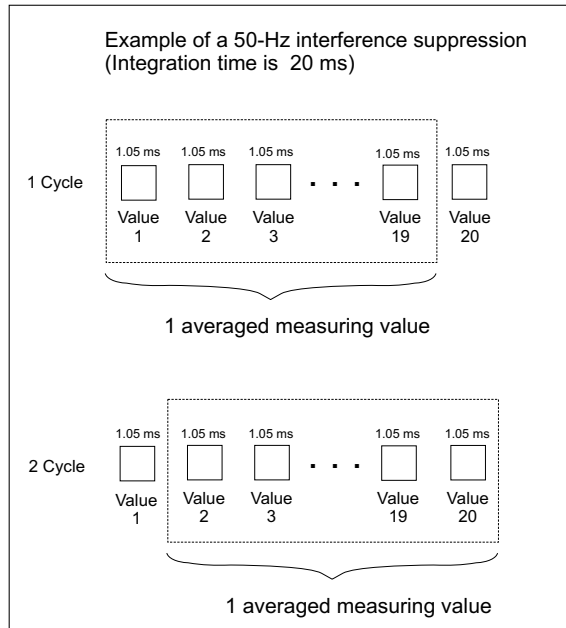
Figure 7-11 50 Hz interference suppression
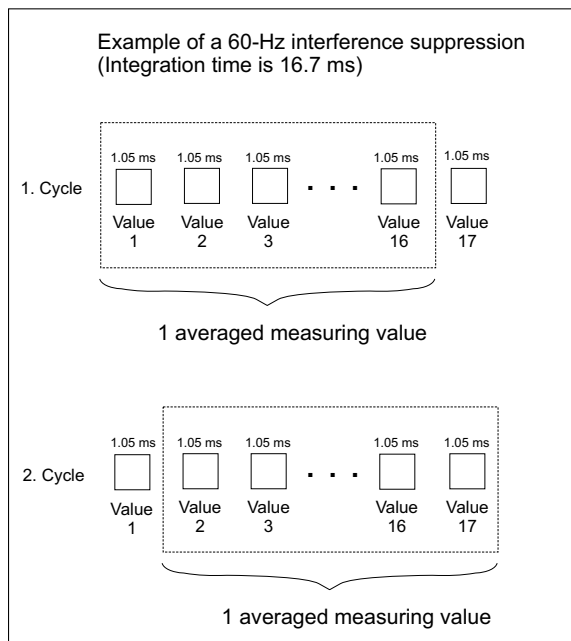
Figure 7-12 60 Hz interference suppression

Note

If the interference frequency is not 50/60 Hz or a multiple thereof, the input signal must be filtered externally,
in which case, 400 Hz must be set as the interference suppression for the affected input. This is equivalent to "disabling" the software filter.

Inputs which are not connected

The three inputs of a current/voltage analog output channel that is not connected should be shorted and connected to M_{ANA} (Pin 20 of the front connector). This ensures maximum interference resistance for these analog inputs.

Outputs not connected

In order to take unused analog outputs off power, you must disable and leave them open when you assign parameters in *STEP 7*.

Cross-reference

Details (e.g. display and processing of analog values) are found in Chapter 4 of the Reference Manual *Module Data*.

7.3 Configuration

Introduction

Configure the integrated I/O of CPUs 31xC in *STEP 7*. You must always configure them when the CPU is in STOP mode. The generated parameters are downloaded from the PG to the S7-300 and written to CPU memory .

You can also choose to change the parameters via SFC55 in the user program (see the Reference Manual *System and Standard Functions*). Refer to the structure of record 1 for the respective parameters.

Parameters of standard DI

The table below gives you an overview of the parameters for standard digital inputs.

Table 7-1   Parameters for the standard DI

Parameters	Range of values	Default	Range of efficiency
Input delay (ms)	0.1/0.5/3/15	3	Channel group

The table below gives you an overview of parameters for operating digital inputs as interrupt inputs .

Table 7-2   Parameters for the interrupt inputs

Parameters	Range of values	Default	Range of efficiency
Interrupt input	Disabled / positive edge	disabled	digital input
Interrupt input	Disabled / negative edge	disabled	digital input

Parameters	Range of values	Default	Range of efficiency

Byte 0

7   0   Bit No.

Input Interrupt DI +0.0
Input Interrupt DI +0.1
Input Interrupt DI +0.7

Byte 1

7   0   Bit No.

Input Interrupt DI +1.0
Input Interrupt DI +1.1
Input Interrupt DI +1.7

Byte 2

7   0   Bit No.

Input Interrupt DI +2.0
Input Interrupt DI +2.1
Input Interrupt DI +2.7

0:     deactivated
1:     positive Transition
Default setting: 0

Byte 3: reserved

Byte 4

7   0   Bit No

Input Interrupt DI +0.0
Input Interrupt DI +0.1
Input Interrupt DI +0.7

Byte 5

7   0   Bit No.

Input Interrupt DI +1.0
Input Interrupt DI +1.1
Input Interrupt DI +1.7

Byte 6

7   0   Bit No.

Input Interrupt DI +2.0
Input Interrupt DI +2.1
Input Interrupt DI +2.7

0:     deactivated
1:     negative Transition
Default setting: 0

Byte 7: reserved

Byte 8

7   0   Bit No.

Input delay DI +0.0 to DI +0.3
Input delay DI +0.4 to DI +0.7
Input delay DI +1.0 to DI +1.3
Input delay DI +1.4 toDI +1.7

Byte 9

7   0   Bit No.

Input delay DI +2.0 to DI +2.3
Input delay DI +2.4 to DI +2.7
reserved

00_B: 3   ms
01_B: 0,1 ms
10_B: 0,5 ms
11_B: 15   ms
Default setting: 00_B

Figure 7-13 Structure of record 1 for standard DI and interrupt inputs (length of 10 bytes)

Parameters of standard DO

There are no parameters for standard digital outputs.

Parameters of standard AI

The following table gives you an overview of the parameters for standard analog inputs (see also Chapter 4.3 in the Reference Manual *Module Data*).

Table 7-3   Parameters for the standard AI

Parameters	Range of values	Default	Range of efficiency
Integration time (ms) Interference suppression (Hz) (channel 0 to 3)	2.5/16.6/20 400/60/50	20 50	Channel Channel
Measurement range (channel 0 to 3)	disabled / +/- 20 mA/ 0 ... 20 mA/ 4 ... 20 mA/ +/- 10 V/ 0 ... 10 V	+/- 10 V	Channel
Type of measurement (channel 0 to 3)	Disabled/ U voltage/ I current	U voltage	Channel
Unit of measurement (channel 4)	Celsius/Fahrenheit/ Kelvin	Celsius	Channel
measurement range (Pt 100 input; channel 4)	Disabled/ Pt 100/600 Ω	600 Ω	Channel
Type of measurement (Pt 100 input; channel 4)	disabled / resistance/ thermal resistance	Resistance	Channel

Parameters of standard AO

The table below gives you an overview of standard analog output parameters (see also Chapter 4.3 in the Reference Manual *Module Data*).

Table 7-4   Parameters for the standard AO

Parameters	Range of values	Default	Range of efficiency
Output range (channel 0 to 1)	disabled / +/- 20 mA/ 0 ... 20 mA/ 4 ... 20 mA/ +/- 10 V/ 0 ... 10 V	+/- 10 V	Channel
Type of output (channel 0 to 1)	Disabled/ U voltage/ I current	U voltage	Channel

Byte 0

7   0   Bit No.

reserved

Maßeinheit
00_B: Celsius
01_B: Fahrenheit
10_B: Kelvin
Default setting: 00_B

reserved

Byte 1

7   0   Bit No.

Integration time Interference frequency suppression channel AI 0
Integration time Interference frequency suppression channel AI 1
Integration time Interference frequency suppression channel AI 2
Integration time Interference frequency suppression channel AI 3
00_B: 2,5 ms, 400 Hz
01_B: 16,6 ms, 60 Hz
10_B: 20   ms, 50 Hz
Default setting: 10_B

Byte 2: reserved

Byte 3

7   0   Bit No.

Measuring range channel AI 0 (settings see Byte 6)
Measuring method channel AI 0 (settings see Byte 6)

Byte 4

7   0   Bit No.

Measuring range channel AI 1 (settings see Byte 6)
Measuring method channel AI 1 (settings see Byte 6)

Byte 5

7   0   Bit No.

Measuring range channel AI 2 (settings see Byte 6)
Measuring method channel AI 2 (settings see Byte 6)

Byte 6

7   0   Bit No.

Measuring range channel AI 3
0_H: deactivated
2_H: 0 … 20 mA
3_H: 4 … 20 mA
4_H: +/- 20 mA
8_H: 0 … 10 V
9_H: +/- 10V
Default setting: 9_H

Measuring method AI 3
0_H: deactivated
1_H: U Voltage
3_H: 2 DMU Strom
Default setting: 1_H

Byte 7

7   0   Bit No.

Measuring range channel AI 4I
0_H: deactivated
2_H: 600 Ohm
6_H: Pt 100
Default setting: 2_H

Measuring method channel AI 4
0_H: deactivated
6_H: resistance
15_H: bulb resistor
Default setting: 6_H

Byte 8 to10: reserved

Figure 7-14 Structure of record 1 for standard AI/AO (length of 13 bytes)

Parameters for technological functions

The parameters for the respective function are found in the *Technological Functions* manual.

7.4   Interrupts

Interrupt inputs

All digital inputs of the on-board I/O of CPUs 31xC can be used as interrupt inputs.

You can specify the interrupt behavior for each individual input in your parameter declaration. Options are:

- no interrupt
- interrupt at the positive edge
- interrupt at the negative edge
- interrupt at the positive and negative edge

Note

Every channel will hold one event if the rate of incoming interrupts exceeds the handling capacity of OB40. Further events (interrupts) will be lost, without diagnostics or explicit message.

Start information for OB40

The table below shows the relevant temporary variables (TEMP) of OB40 for the interrupt inputs of 31xC CPUs. A description of process interrupt OB40 is found in the Reference Manual *System and Standard Functions*.

Table 7-5   Starting information for OB40 relating to the interrupt inputs of the integrated I/Os

Byte	Variable	Data type		Description
6/7	OB40_MDL_ADDR	WORD	B#16#7C	Address of the interrupt-triggering module (Here: Default addresses of the digital inputs)
8 on	OB40_POINT_ADDR	DWORD	see the figure below	Displaying the interrupt triggering integrated inputs
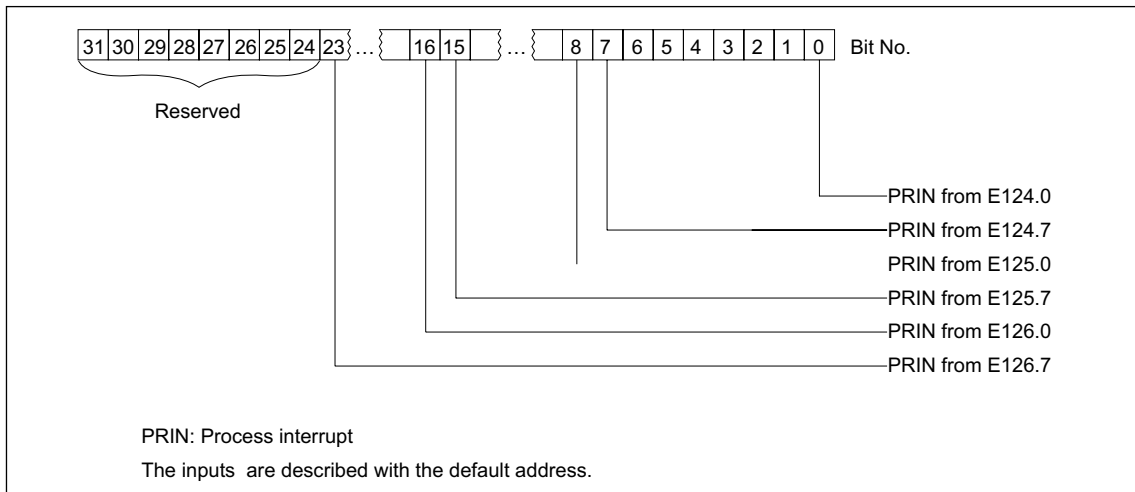
Figure 7-15 Displaying the statuses of CPU 31xC interrupt inputs

7.5 Diagnostics

Standard I/O

Diagnostic data is not available for integrated I/O which is operated as standard I/O (see also the Reference Manual *Module Data*).

Technological functions

Diagnostics options for the respective technological function are found in the *Technological Functions* manual.

7.6   Digital inputs

Introduction

This chapter contains the technical data for the digital inputs of 31xC CPUs.

The table includes the following CPUs:

- under CPU 313C-2, the CPU 313C-2 DP and CPU 313C-2 PtP
- under CPU 314C-2, the CPU 314C-2 DP and CPU 314C-2 PtP

Technical data

Technical Data				
Modulespecific data	**CPU 312C**	**CPU 313C**	**CPU 313C-2**	**CPU 314C-2**
Number of inputs	10	24	16	24
• number of these inputs which can be used for technological functions	8	12	12	16
Cable length				
• Unshielded	For standard DIs: max. 600 m			
	For technological functions: no			
• Shielded	For standard DIs: max. 1000 m			
	For technological function at max. counting frequency			
	100 m	100 m	100 m	50 m
Voltage, currents, potentials	**CPU 312C**	**CPU 313C**	**CPU 313C-2**	**CPU 314C-2**
Rated load voltage L+	24 VDC			
• Polarity reversal protection	Yes			
Number of inputs which can be controlled simultaneously				
• horizontal assembly				
up to 40 degC	10	24	16	24
up to 60 degC	5	12	8	12
• vertical assembly				
up to 40 degC	5	12	8	12
electrical isolation				
• between the channels and the backplane bus	Yes			
• between the channels	No			
permitted potential difference				
• between different circuits	75 VDC / 60 VAC			
Insulation test voltage	500 VDC			
Current consumption				

Technical Data				
• on load voltage L+ (no-load)	–	max. 70 mA	max. 70 mA	max. 70 mA
Status, interrupts, diagnostics	**CPU 312C**	**CPU 313C**	**CPU 313C-2**	**CPU 314C-2**
Status display	one green LED per channel			
Interrupts	• yes, if the corresponding channel is configured as interrupt input • when using technological functions, please refer to the *Technological Functions* manual.			
Diagnostic functions	• no diagnostics when operated as standard I/O • when using technological functions, please refer to the *Technological Functions* manual.			
Data for the selection of an encoder for standard DI	**CPU 312C**	**CPU 313C**	**CPU 313C-2**	**CPU 314C-2**
Input voltage				
• Rated value	24 VDC			
• For signal "1"	15 V to 30 V			
• For signal "0"	-3 V to 5 V			
Input current				
• For signal "1"	typically 9 mA			
Delay of standard inputs				
• Configurable	yes (0.1 / 0.5 / 3 / 15 ms)			
• Rated value	3 ms			
Input delay for count and position feedback inputs when using technological functions. "Minimum pulse width/ minimum pause between pulses at maximum counting frequency"	48 µs	16 µs	16 µs	8 µs
Input characteristics curve	to IEC 1131, type 1			
Connection of 2wire BEROs	Possible			
• permitted quiescent current	max. 1.5 mA			

7.7   Digital outputs

Introduction

This chapter contains the technical data for the digital outputs of 31xC CPUs.

The table includes the following CPUs:

- under CPU 313C-2, the CPU 313C-2 DP and CPU 313C-2 PtP
- under CPU 314C-2, the CPU 314C-2 DP and CPU 314C-2 PtP

Fast Digital Outputs

Technological functions use fast digital outputs.

Technical data

Technical Data				
Modulespecific data	**CPU 312C**	**CPU 313C**	**CPU 313C-2**	**CPU 314C-2**
Number of outputs	6	16	16	16
• of those are fast outputs	2	4	4	4
Cable length				
• Unshielded	max. 600 m			
• Shielded	max. 1000 m			
Voltage, currents, potentials	**CPU 312C**	**CPU 313C**	**CPU 313C-2**	**CPU 314C-2**
Rated load voltage L+	24 VDC			
• Polarity reversal protection	Yes			
Total current of outputs (per group)				
• horizontal assembly				
up to 40 degC	max. 2.0 A	max. 3.0 A	max. 3.0 A	max. 3.0 A
up to 60 degC	max. 1.5 A	max. 2.0 A	max. 2.0 A	max. 2.0 A
• vertical assembly				
up to 40 degC	max. 1.5 A	max. 2.0 A	max. 2.0 A	max. 2.0 A
electrical isolation				
• between the channels and the backplane bus	Yes			
• between the channels	No	Yes	Yes	Yes
in groups of	–	8	8	8
permitted potential difference				
• between different circuits	75 VDC / 60 VAC			
Insulation test voltage	500 VDC			
Current consumption				
• with load voltage L+	max. 50 mA	max. 100 mA	max. 100 mA	max. 100 mA

Technical Data				
Status, interrupts, diagnostics	**CPU 312C**	**CPU 313C**	**CPU 313C-2**	**CPU 314C-2**
Status display	one green LED per channel			
Interrupts	• no interrupts when operated as standard I/O • when using technological functions, please refer to the *Technological Functions* manual.			
Diagnostic functions	• no diagnostics when operated as standard I/O • when using technological functions, please refer to the *Technological Functions* manual.			
Data for the selection of an actuator for standard DI	**CPU 312C**	**CPU 313C**	**CPU 313C-2**	**CPU 314C-2**
Output voltage				
• For signal "1"	min. L+ (-0.8 V)			
Output current				
• For signal "1"				
Rated value	0.5 A			
Permitted range	5 mA to 600 mA			
• For signal "0" (residual current)	max. 0.5 mA			
Load impedance range	48 Ω to 4 kΩ			
Lamp load	max. 5 W			
Parallel connection of 2 outputs				
• for redundant load control	Possible			
• for performance increase	Not possible			
Controlling of digital inputs	Possible			
Switching frequency				
• under resistive load	max. 100 Hz			
• For inductive load to IEC 947-5, DC13	max. 0.5 Hz			
• under lamp load	max. 100 Hz			
• fast outputs under resistive load	max. 2.5 kHz			
Inductive breaking voltage limited internally to	typically (L+) - 48 V			
Short-circuit protection of the output	yes, electronic			
• Response threshold	typically 1 A			

7.8 Analog inputs

Introduction

This chapter contains the technical data for analog outputs of CPUs 31xC.

The table includes the following CPUs:

- under CPU 314C-2, the CPU 314C-2 DP and CPU 314C-2 PtP

Technical Data

Technical Data		
Module specific data	**CPU 313C**	**CPU 314C-2**
Number of inputs	4 channels with current/voltage input	
	1 channel with resistance input	
Cable length		
• Shielded	max. 100 m	
Voltage, currents, potentials	**CPU 313C**	**CPU 314C-2**
Resistance input		
• No load voltage	typically 2.5 V	
• Measurement current	typically 1.8 mA to 3.3 mA	
Electrical isolation		
• Between the channels and the backplane bus	Yes	
• Between the channels	No	
Permitted potential difference		
• Between the inputs and M_{ANA} (U_{CM})	8.0 VDC	
• Between M_{ANA} and $M_{internal}$ (U_{ISO})	75 VDC / 60 VAC	
Insulation test voltage	600 VDC	
Analog value generation	**CPU 313C**	**CPU 314C-2**
Measurement principle	Actual value encoding (successive approximation)	
Integration time/conversion time/resolution (per channel)		
• Configurable	Yes	
• Integration time in ms	2.5 / 16.6 / 20	
• Permitted input frequency	max. 400 Hz	
• Resolution (including overdrive)	11 bits + signed bit	
• Suppression of interference frequency f1	400 / 60 / 50 Hz	
Time constant of the input filter	0.38 ms	
Basic processing time	1 ms	
Interference suppression, error limits	**CPU 313C**	**CPU 314C-2**
Interference voltage suppression for f = nx (f1 $\pm$ 1 %), (f1 = interference frequency), n = 1, 2		
• Commonmode interference ($_{UCM}$< 1.0 V)	> 40 dB	

Technical Data		
• Feedback interference (peak value of the interference < rated value of the input range)	> 30 dB	
Crosstalk between the inputs	> 60 dB	
Operational error limits (across the temperature range, in relation to input range)		
• Voltage/current	< 1 %	
• Resistance	< 5%	
Basic error limit (operational limit at 25 degC, in relation to input range)		
• Voltage/current	< 0.7 %	
• Resistance	< 3%	
Temperature error (in relation to input range)	±0.006%/K	
Linearity error (referred to input range)	±0.06%	
Repeat accuracy (in transient state at 25 degC, in relation to input range)	±0.06%	
Status, interrupts, diagnostics	**CPU 313C**	**CPU 314C-2**
Interrupts	• no interrupts when operated as standard I/O	
Diagnostic functions	• no diagnostics when operated as standard I/O • when using technological functions, please refer to the *Technological Functions* Manual.	
Encoder selection data	**CPU 313C**	**CPU 314C-2**
Input ranges (rated value)/input resistance		
• Voltage	±10 V/100 kΩ 0 V to 10 V/100 kΩ	
• Current	±20 mA/50 Ω 0 mA to 20 mA/50 Ω 4 mA to 20 mA/50 Ω	
• Resistance	0 Ω to 600 Ω/10 MΩ	
• Resistance thermometer	Pt 100/10 MΩ	
Permitted continuous input voltage (destruction limit)		
• for voltage inputs	max. 30 V;	
• for current inputs	max. " 2.5 V;	
Permitted continuous input current (destruction limit)		
• for voltage inputs	max. " 0.5 mA;	
• for current inputs	max. 50 mA;	
Connection of signal generators		
• for voltage measurement	Possible	
• for current measurement		
as 2-wire measuring transducer	possible, with external power supply	
as 4-wire measuring transducer	Possible	

Technical Data	
• for measuring resistance	
with 2-wire connection	possible, without cable resistance compensation
with 3-wire connection	Not possible
with 4-wire connection	Not possible
Linearization of the characteristics trend	by software
• for resistance thermometers	Pt 100
Temperature compensation	No
Technical unit for temperature measurement	Degrees Celsius/Fahrenheit/Kelvin

7.9 Analog outputs

Introduction

This chapter contains the technical data for digital outputs of CPUs 31xC.

The table includes the following CPUs:

- under CPU 314C-2, the CPU 314C-2 DP and CPU 314C-2 PtP

Technical Data

Technical Data		
Module specific data	**CPU 313C**	**CPU 314C-2**
Number of outputs	2	
Cable length		
• Shielded	max. 200 m	
Voltage, currents, potentials	**CPU 313C**	**CPU 314C-2**
Rated load voltage L+	24 VDC	
• Polarity reversal protection	Yes	
Electrical isolation		
• Between the channels and the backplane bus	Yes	
• Between the channels	No	
Permitted potential difference		
• Between outputs and M_{ANA} (U_{CM})	8.0 VDC	
• Between M_{ANA} and $M_{internal}$ (U_{ISO})	75 VDC / 60 VAC	
Insulation test voltage	600 VDC	
Analog value generation	**CPU 313C**	**CPU 314C-2**
Resolution (including overdrive)	11 bits + signed bit	
Conversion time (per channel)	1 ms	
Settling time		

Technical Data		
• with resistive load	0.6 ms	
• with capacitive load	1.0 ms	
• with inductive load	0.5 ms	
Interference suppression, error limits	**CPU 313C**	**CPU 314C-2**
Crosstalk between the outputs	> 60 dB	
Operational error limits (across the temperature range, in relation to output range)		
• Voltage/current	± 1 %	
Basic error limit (operational limit at 25C, in relation to output range)		
• Voltage/current	±0.7%	
Temperature error (in relation to output range)	±0.01%/K	
Linearity error (in relation to output range)	±0.15%	
Repeat accuracy (in transient state at 25 degC, in relation to output range)	±0.06%	
Output ripple; bandwidth 0 to 50 kHz (in relation to output range)	±0.1%	
Status, interrupts, diagnostics	**CPU 313C**	**CPU 314C-2**
Interrupts	• no interrupts when operated as standard I/O • when using technological functions, please refer to the *Technological Functions* manual.	
Diagnostic functions	• no diagnostics when operated as standard I/O • when using technological functions, please refer to the *Technological Functions* manual.	
Actuator selection data	**CPU 313C**	**CPU 314C-2**
Output range (rated values)		
• Voltage	±10 V 0 V to 10 V	
• Current	±20 mA/ 0 mA to 20 mA 4 mA to 20 mA	
Load resistance (within output rating)		
• For voltage outputs	min. 1 kΩ	
Capacitive load	max. 0.1 µF	
• For current outputs	max. 300 Ω	
Inductive load	0.1 mH	
Voltage output		
• Short-circuit protection	Yes	
• Short-circuit current	typically 55 mA	
Current output		

Technical Data	
• No load voltage	typically 17 V
Destruction limit for externally applied voltages/currents	
• Voltage measured between the outputs and M_{ANA}	max. 16 V, continuous;
• Current	max. 50 mA;
Connection of actuators	
• For voltage outputs	
2-wire connection	possible, without cable resistance compensation
4-wire connection (measuring line)	not possible
• For current outputs	
2-wire connection	possible

Information about upgrading to a CPU 31xC, 312, 314, 315-2 DP

<div style="text-align: right; font-size: 2em; font-weight: bold;">8</div>

Who should read this chapter?

You are already using a CPU from the SIEMENS S7-300 series and now want to upgrade to a new device.

Please note that problems may occur while downloading your user program to the "new" CPU.

If you have used one of the following CPUs in the past ...

CPU	Order No.	As of version	
		Firmware	Hardware
CPU 312 IFM	6ES7 312-5AC02-0AB0	1.0.0	01
	6ES7 312-5AC82-0AB0		
CPU 313	6ES7 313-1AD03-0AB0	1.0.0	01
CPU 314	6ES7 314-1AE04-0AB0	1.0.0	01
	6ES7 314-1AE84-0AB0		
CPU 314 IFM	6ES7 314-5AE03-0AB0	1.0.0	01
CPU 314 IFM	6ES7 314-5AE83-0AB0	1.0.0	01
CPU 315	6ES7 315-1AF03-0AB0	1.0.0	01
CPU 315-2 DP	6ES7 315-2AF03-0AB0	1.0.0	01
	6ES7 315-2AF83-0AB0		
CPU 316-2 DP	6ES7 316-2AG00-0AB0	1.0.0	01
CPU 318-2DP	6ES7 318-2AJ00-0AB0	V3.0.0	03

... then please note if you upgrade to one of these

CPU	Order No.	As of version		Hereafter called
		Firmware	**Hardware**	
CPU 312	6ES7312-1AD10-0AB0	V2.0.0	01	CPU 31xC/31x
CPU 312C	6ES7312-5BD01-0AB0	V2.0.0	01	
CPU 313C	6ES7313-5BE01-0AB0	V2.0.0	01	
CPU 313C-2 PtP	6ES7313-6BE01-0AB0	V2.0.0	01	
CPU 313C-2 DP	6ES7313-6CE01-0AB0	V2.0.0	01	
CPU 314	6ES7314-1AF10-0AB0	V2.0.0	01	
CPU 314C-2 PtP	6ES7314-6BF01-0AB0	V2.0.0	01	
CPU 314C-2 DP	6ES7314-6CF01-0AB0	V2.0.0	01	
CPU 315-2 DP	6ES7315-2AG10-0AB0	V2.0.0	01	

SFC 56, SFC 57 and SFC 13 which work asynchronously

Some of the SFCs that work asynchronously, when used on CPUs 312IFM - 318-2 DP, were always, or under certain conditions, processed after the first call ("quasi-synchronous").

On the 31xC/31x CPUs these SFCs actually run asynchronously. Asynchronous processing may cover multiple OB1 cycles. As a result, a wait loop may turn into an endless loop within an OB.

The following SFCs are affected:

- SFC 56 "WR_DPARM"; SFC 57 "PARM_MOD"

  On CPUs 312 IFM to 318-2 DP, these SFCs always work "quasi-synchronously" during communication with centralized I/O modules and always work synchronously during communication with decentralized I/O modules.

Note

If you are using SFC 56 "WR_DPARM" or SFC 57 "PARM_MOD", you should always evaluate the SFC's BUSY bit.

- SFC 13 "DPNRM_DG"

  On CPUs 312 IFM to 318-2 DP, this SFC always works "quasi synchronously" when it is called in OB82. On CPUs 31xC/31x it generally works asynchronously.

Note

In the user program, the job should merely be started in OB 82. The data should be evaluated in the cyclical program, taking account of the BUSY bits and the value returned in RET_VAL.

Tip:

If you are using a CPU 31xC/31x, we recommend that you use SFB 54, rather than SFC 13 "DPNRM_DG".

SFC 20 "BLKMOV"

In the past, this SFC could be used with CPUs 312 IFM to 318-2 DP to copy data from a non runtime-related DB.

SFC 20 no longer has this functionality with CPUs 31xC/31x. SFC83 "READ_DBL" is now used instead.

SFC 54 "RD_DPARM"

This SFC is no longer available on CPUs 31xC/31x. Instead you should use SFC 102 "RD_DPARA", which works asynchronously.

SFCs that may return other results

You can ignore the following points if you only use logical addressing in your user program.

If you use address conversion in your user program (SFC 5 "GADR_LGC", SFC 49 "LGC_GADR"), you must check the assignment of the slot and logical start address for your DP slaves.

- In the past, the diagnostic address of a DP slave was assigned to the slave's virtual slot 2. Since DPV1 was standardized, this diagnostic address has been assigned to virtual slot 0 (station proxy) for CPUs 31xC/31x.

- If the slave has modeled a separate slot for the interface module (e.g. CPU31x-2 DP as an intelligent slave or IM 153), then its address is assigned to slot 2.

Activating / deactivating DP slaves via SFC 12

With CPUs 31xC/31x, slaves that were deactivated via SFC 12 are no longer automatically activated at the RUN to STOP transition. Now, they are not activated until they are restarted (STOP to RUN transition).

Interrupt events from decentralized I/Os while the CPU status is STOP

With the new DPV1 functionality (IEC 61158/ EN 50170, volume 2, PROFIBUS), the handling of incoming interrupt events from the distributed I/Os while the CPU status is STOP has also changed.

Previous response by the CPU with STOP status:

With CPUs 312IFM – 318-2 DP, initially an interrupt event was noticed while the CPU was in STOP mode. When the CPU status subsequently returned to RUN, the interrupt was then fetched by an appropriate OB (e.g. OB 82).

New response by the CPU:

With CPUs 31xC/31x, an interrupt event (process or diagnostic interrupt, new DPV1 interrupts) is acknowledged by the decentralized I/O while the CPU is still in STOP status, and is entered in the diagnostic buffer if necessary (diagnostic interrupts only). When the CPU status subsequently returns to RUN, the interrupt is no longer fetched by the OB. Possible slave faults can be read using suitable SZL queries (e.g. read SZL 0x692 via SFC51).

Runtimes that change while the program is running

If you have created a user program that has been fine-tuned in relation to certain processing times, please note the following points if you are using a CPU 31xC/31x:

- the program will run much faster on the CPU 31xC/31x.

- Functions that require MMC access (e.g. system start-up time, program download in RUN, return of DP station, etc), may sometimes run slower on the CPU 31xC/31x.

Converting the diagnostic addresses of DP slaves

If you are using a CPU 31xC/31x with DP interface as the master, please note that you may have to reassign the diagnostic addresses for the slaves since the changes to the DPV1 standard sometimes require two diagnostic addresses per slave.

- The virtual slot 0 has its own address (diagnostic address of the station proxy). The module status data for this slot (read SZL 0xD91 with SFC 51 "RDSYSST") contains IDs that concern the entire slave/station, e.g. the station error ID. Failure and restoration of the station are also signaled in OB86 on the master via the diagnostic address of the virtual slot 0.

- With some slaves, the interface module is also modeled as a separate virtual slot (e.g. CPU as an intelligent slave or IM153), and a suitable separate address is assigned to virtual slot 2.
  The change of operating status is signaled in the master's diagnostic interrupt OB 82 via this address for CPU 31xC-2DP acting as an intelligent slave.

Note

Reading diagnostics with SFC 13 "DPNRM_DG":
The originally assigned diagnostic address still works. Internally, *STEP 7* assigns this address to slot 0.

If you use SFC51 "RDSYSST", for example, to read module status information or rack/station status information, you must also consider the changed significance of the slots, as well as the additional slot 0.

Reusing existing hardware configurations

If you reuse the configuration of a CPU 312 IFM to 318-2 DP for a CPU 31xC/31x, the CPU 31xC/31x may not run correctly.

If this is the case, you will have to replace the CPU in the STEP 7 hardware configuration editor. When you replace the CPU, STEP7 will automatically accept all the settings (if appropriate and possible).

Replacing a CPU 31xC/31x

When supplied, the CPU 31xC/31x adds a connecting plug to the power supply connector.

If you replace the CPU 31xC/31x, you no longer have to detach the cables on the CPU: Simply insert a screwdriver with a 3.5 mm blade to the right of the connecting plug. Use this to release the latch and then pull the connecting plug away from the CPU. Once you have replaced the CPU, simply plug the connecting plug back into the power supply connector.

Using consistent data areas in the process image for DP slaves

See also the Consistent data section of the Addressing chapter in the Installation Manual.

Load memory concept for the CPU 31xC/31x

On CPUs 312 IFM to 318-2 DP, the load memory is integrated into the CPU and may be extended with a memory card,

The load memory of the CPU 31xC/31x is located on the micro memory card (MMC), and is retentive. When blocks are downloaded to the CPU, they are stored on the MMC and cannot be lost even in the event of a power failure or memory reset.

Cross-reference

See also the *Memory concept* chapter in the *CPU Data 31xC and 31x manual.*

Note

The user program can only be downloaded and thus the CPU can only be used if the MMC is inserted.

PG/OP functions

With CPUs 315-2 DP (6ES7315-2AFx3-0AB0), 316-2DP and 318-2 DP, PG/OP functions at the DP interface were only possible if the interface was set to active. With CPUs 31xC/31x, these functions are possible at both active and passive interfaces. The performance of the passive interface is much lower, however.

Routing for the CPU 31xC/31x as an intelligent slave

If you use the CPU 31xC/31x as an intelligent slave, the routing function can only be used with an actively-configured DP interface.

In the properties of the DP interface in STEP 7, tick the Commissioning / Test mode check box.

Glossary

9

Accumulator

The --> CPU uses the accumulator registers as intermediate memory for load, transfer, comparison, calculation and conversion operations.

Address

An address represents the ID for a specific address or address range. Example: Input I12.1; Memory bit word MW25; Data block DB3.

Analog Module

Analog modules convert process values (e.g. temperature) into digital values, so that they can be processed by the central processing unit, or convert digital values into analog manipulated variables.

Automation system

An automation system in the context of SIMATIC S7 --> is a programmable logic controller.

Back-up Memory

The back-up memory provides a back-up of memory areas for the --> CPU without a back-up battery. It backs up a configurable number of timers, counters, memory bits, data bytes and retentive timers, counters, memory bits and data bytes).

Backplane Bus

The serial backplane data bus supplies the power required by the modules. It is also used by the modules for communication. The connection between the modules is established by bus connectors.

Bus

A bus is a communication medium connecting several nodes. Data can be transferred via serial or parallel circuits, that is, via electrical conductors or optic waveguides.

Bus segment

A bus segment is a self-contained section of a serial bus system. Bus segments are interconnected using repeaters.

Chassis ground

Chassis ground is the totality of all the interconnected inactive parts of a piece of equipment on which a hazardous touch voltage cannot build up even in the event of a fault.

Clock memory bits

Memories that can be used for clocking purposes in the user program (1 memory byte).

Note

Note in the case of S7300 CPUs that the clock memory byte is not overwritten in the user program.

Code Block

A SIMATIC S7 code block contains part of the **STEP 7** user program. (In contrast: a --> Data Block (DB) only contains data.)

Communication processor

Communication processors are modules for point-to-point and bus communication.

Compress

The programming device online function "Compress" is used to align all valid blocks contiguously in the RAM of the CPU at the start of the user memory. This eliminates all gaps which arose when blocks were deleted or modified.

Configuration

Assignment of modules to racks/slots and (e.g. for signal modules) addresses.

Consistent data

Data whose contents are related and which should not be separated are known as consistent data.

For example, the values of analog modules must always be handled consistently, that is the value of an analog module must not be corrupted by reading it out at two different times.

Counter

Counters are part of CPU --> system memory. The content of "Counter cells" can be modified by **STEP 7** instructions (e.g. up/down count).

CP

--> Communication Processor

CPU

Central processing unit of the S7 programmable controller with open and closed-loop control systems, memory, operating system and interface for programming device.

CPU operating system

The operating system of the CPU organizes all functions and processes of the CPU which are not associated with a special control task.

Cycle Time

The term cycle time describes the time required by a --> CPU to run through a --> user program once.

Data Block

Data blocks (DB) are data areas in the user program which contain user data. Global data blocks can be accessed by all code blocks while instance data blocks are assigned to a specific FB call.

Data, static

Static data is data which can only be used within a function block. The data is saved in an instance data block belonging to the function block. The data stored in the instance data block is retained until the next function block call.

Data, temporary

Temporary data is local data of a block that is stored in the L stack during block execution and no longer available after execution.

Delay Interrupt

--> Interrupt, Delay

Diagnostic buffer

The diagnostic buffer is a buffered memory area in the CPU in which diagnostic events are stored in the order of their occurrence.

Diagnostic Interrupt

Modules capable of diagnostics operations report detected system errors to the --> CPU via diagnostic interrupts.

Diagnostics

--> System Diagnostics

DP master

A --> master which behaves in accordance with EN 50170, Part 3 is known as a DP master.

DP slave

A --> slave operated on PROFIBUS with PROFIBUSDP protocol and in accordance with EN 50170, Part 3 is referred to as DP slave.

DPV1

The designation DPV1 means the extended functions of the acyclical services (to include new interrupts, for example) provided by the DP protocol. The DPV1 functionality has been incorporated into IEC 61158/EN 50170, volume 2, PROFIBUS.

Electrically isolated

The reference potential of the control and on-load power circuits for isolated I/Os is electrically isolated; e.g. by optocouplers, relay contact or transformer. I/O circuits can be connected to a common potential.

Equipotential bonding

Electrical connection (equipotential bonding conductor) which gives the bodies of electrical equipment and external conducting bodies the same or approximately the same potential, in order to prevent disturbing or dangerous voltages from being generated between these bodies.

External power supply

Power supply for the signal and function modules and the I/O connected to them.

Error Display

One of the possible responses of the operating system to a --> runtime error is to display the error. The other possible responses are: --> error response in the user program, CPU STOP.

Error handling via OB

When the operating system detects a specific error (e.g. access error with **STEP 7**), it calls a dedicated organization block (Error OB) that determines subsequent CPU response.

Error Response

Response to a --> runtime error. The operating system can respond in the following ways: transition of the PLC to STOP mode, call of an organization block in which the user can program an error response or display.

FB

--> Function Block

FC

--> Function

Flash EPROM

FEPROMs are the same as electrically erasable EEPROMS in that they can retain data in the event of a power failure, but they can be erased much more quickly (FEPROM = Flash Erasable Programmable Read Only Memory). They are used on --> Memory Cards.

Floating potential

Having no electrical connection to ground

FORCE

The Force function is used to assign fixed values to certain variables from a user program or CPU (including I/Os).

In this context, please note the limitations listed in the *Overview of the test functions* section in the chapter entitled *Test functions, diagnostics and troubleshooting* in the *S7-300 Installation* manual

Function

According to IEC 1131-3 a function is a --> code block that contains no --> static data. A function allows parameters to be passed in the user program. Functions are therefore suitable for programming complex functions, e.g. calculations, which are repeated frequently.

Function block

According to IEC 1131-3, a function block is a --> code block that contains --> static data. An FB allows parameters to be passed in the user program. Function blocks are therefore suitable for programming complex functions, e.g. closed-loop controls, mode selections, which are repeated frequently.

Functional Grounding

Grounding which has the sole purpose of safeguarding the intended function of the electrical equipment. With functional grounding you short-circuit interference voltage which would otherwise have an unacceptable impact on equipment.

GD circuit

A GD circle encompasses a number of CPUs which exchange data by means of global data communication and which are used as follows:

- One CPU broadcasts a GD packet to the other CPUs.
- One CPU sends and receives a GD packet from another CPU.

GD packet

A GD packet can consist of one or more GD objects which are transmitted together in a frame.

GD Element

A GD element is generated by assigning shared --> global data. It is identified by a unique global data ID in the global data table.

Ground

> The conducting earth whose electrical potential can be set equal to zero at any point.
>
> In the vicinity of grounding electrodes, the earth can have a potential different to zero. The term "reference ground" is frequently used to describe this situation.

Ground (to)

> To ground means to connect an electrically conducting component to the grounding electrode (one or more conducting components which have a very good contact with the earth) across a grounding system.

Global data

> Shared data can be addressed from any --> code block (FC, FB, OB). In detail, this refers to memories M, inputs I, outputs Q, timers, counters and data blocks DB. Absolute or symbolic access can be made to shared data.

Global data communication

> Global data communication is a procedure used to transfer --> global data between CPUs (without CFBs).

GSD file (device master file)

> The device master file (GSD file) stores all slave specific properties. The GSD file format is specified in EN 50170,Volume 2, PROFIBUS.

Instance data block

> A DB is automatically generated and assigned to every function block in the **STEP 7** user program. The values of the input, output and in/out parameters are stored in the instance data block, together with local block data.

Interface, multipoint

> --> MPI

Interrupt

> The CPU's --> operating system knows 10 different priority classes for controlling user program execution. These priority classes include interrupts, such as process interrupts. When an interrupt is triggered, the operating system automatically calls an assigned OB. In this OB the user can program the desired response (for example in an FB).

Interrupt, Delay

The delay interrupt belongs to one of the priority classes when processing programs in SIMATIC S7. It is started on expiration of a time generated in the user program. A corresponding organization block is then executed.

Interrupt, diagnostic

--> Diagnostic interrupt

Interrupt, Process

--> Process Interrupt

Interrupt, status

A status interrupt can be generated by a DPV1 slave and causes OB 55 to be called on the DPV1 master. For detailed information on OB 55, see the *Reference Manual "System software for S7-300/400: System and Standard Functions*"

Interrupt, time-of-day

The time-of-day interrupt belongs to one of the priority classes when processing programs in SIMATIC S7. It is generated depending on a specific date (or daily) and time-of-day (e.g. 9:50 or hourly, or every minute). A corresponding organization block is then executed.

Interrupt, update

An update interrupt can be generated by a DPV1 slave and causes OB 56 to be called on the DPV1 master. For detailed information on OB 56, see the *Reference Manual "System software for S7-300/400: System and Standard Functions*"

Interrupt, vendor-specific

A vendor-specific interrupt can be generated by a DPV1 slave. It causes OB 57 to be called on the DPV1 master.

Detailed information on OB 57 can be found in the *Reference Manual "System Software for S7-300/400: System and Standard Functions"*

Interrupt, watchdog

A watchdog interrupt is generated periodically by the CPU in configurable time intervals. A corresponding --> organization block is then executed.

Local data

--> Data, temporary

Load Memory

Load memory is part of the CPU. It contains objects generated by the programming device. It is implemented either as a plug-in memory card or a permanently integrated memory.

Main Memory

Working memory is a RAM memory in the --> CPU accessed by the processor during user program execution.

Master

Masters in possession of the --> Token can send/request data to/from other nodes (= active node).

Memory bits

Memory bits are part of the CPU's --> system memory. They store the intermediate results of calculations. They can be accessed in bit, byte, word or double word units.

Micro Memory Card (MMC)

Micro Memory Cards are memory media for CPUs and CPs. Its smaller dimensions form the only difference compared to the --> Memory Card.

Module Parameters

Module parameters are values which can be used to control the response of the module. A distinction is made between static and dynamic module parameters.

MPI

This interface is capable of multipoint communication (MPI). It forms part of the SIMATIC S7 PG interface. it also offers optional multiple node operation (PGs, text displays, operator panels) on one or several PLCs. Each node is identified by a unique address (MPI address).

MPI address

--> MPI

Nesting depth

One block can be called from another by means of a block call. Nesting depth is defined as the number of simultaneously called --> code blocks.

Non-isolated

The reference potential of the control and on-load power circuits for non-isolated I/Os is electrically interconnected.

OB

--> Organization Blocks

OB priority

The CPU --> operating system distinguishes between different priority classes, e.g. cyclic program execution, program execution controlled by process interrupt. Each priority class is assigned --> organization blocks (OBs) in which the S7 user can program a response. The OBs have different standard priorities which determine the order in which they are executed or interrupted in the event that they are activated simultaneously.

Operating mode

SIMATIC S7 PLC operating modes are: STOP, --> START-UP, RUN.

Organization Blocks

Organization blocks (OBs) represent the interface between the operating system of the CPU and the user program. The processing sequence of the user program is defined in the organization blocks.

Parameters

1. Variable of a **STEP 7** code block
2. Variable for declaring module response (one or several per module). All modules have a suitable basic factory setting which can be customized in **STEP 7**.
There are --> static parameters and --> dynamic parameters

Parameters, dynamic

Unlike static parameters, dynamic parameters of modules can be changed during operation by calling an SFC in the user program, for example limit values of an analog signal input module.

Parameters, static

Unlike dynamic parameters, static parameters of modules cannot be changed by the user program, but rather by changing the configuration in **STEP 7**, for example the input delay on a digital signal input module.

PG

--> Programming Device

PLC

--> Programmable controller

Priority class

memory markers, timers and counters is reset following a power failure and a transition from the STOP mode to the RUN mode.

The following can be made retentive:

- Bit memories
- S7 timers
- S7 counters
- Data areas

Process Image

The process image is part of CPU --> system memory. At the start of cyclic program execution, the status of the signal module inputs is written to the input process image. At the end of cyclic program execution, the signal status of the output process image is transferred to the output modules.

Process interrupt

A process interrupt is triggered by interrupt-triggering modules as a result of a specific event in the process. The process interrupt is reported to the CPU. The assigned --> organization block is then processed, according to interrupt priority.

Product version

The product version differentiates between products which have the same order number. The product version is increased with each upwardly compatible function extension, production-related modification (use of new components) or bug-fix.

The S7 CPU operating system provides up to 26 priority classes (or "Program execution levels"). Specific OBs are assigned to these classes. The priority classes determine which OBs interrupt other OBs. If a priority class includes several OBs, they do not interrupt each other, but are executed sequentially.

PROFIBUS DP

The PLC distributes controls for digital, analog and intelligent modules and to a wide range of field devices to EN 50170, part 3, such as drives or valve blocks, to processes at external locations - even across distances exceeding 23 km.

The modules and field devices are connected to the programmable controller via the PROFIBUSDP field bus and are addressed in the same way as centralized I/Os.

Programmable controller

Programmable controllers (PLCs) are electronic controllers whose function is saved as a program in the control unit. The configuration and wiring of the unit are therefore independent of the function of the control system. The PLC has a computer structure; it consists of the --> CPU (Central Processing Unit) with memories, I/O modules and internal bus system. The I/Os and the programming language are oriented to control engineering needs.

Programming device

Programming devices are essentially personal computers which are compact, portable and suitable for industrial applications. They are equipped with special hardware and software for SIMATIC PLCs.

RAM

RAM (Random Access Memory) is a semiconductor read/write memory.

Reduction factor

The reduction rate determines the send/receive frequency for --> GD packets on the basis of the CPU cycle.

Reference potential

Potential with reference to which the voltages of participating circuits are observed and/or measured.

Restart

When a central processing unit is started up (e.g. by switching the mode selector from STOP to RUN or by switching the power on), organization block OB 100 (complete restart) is executed before cyclic program execution commences (OB 1). On restart, the input process image is read in and the **STEP 7** user program is executed, starting at the first instruction in OB 1.

Retentivity

A memory area is retentive if its contents are retained even after a power failure and a change from STOP to RUN. The nonretentive area of Reference ground

--> Ground

Runtime Error

Errors occurred in the PLC (that is, not in the process itself) during user program execution.

Segment

--> Bus Segment

SFB

--> System function block

SFC

--> System function

Signal module

Signal modules (SM) form the interface between the process and the PLC. There are digital and analog I/O modules (input/output module, digital or analog). analog I/O modules (input/output module)

Slave

A slave can only exchange data on --> Master request.

START-UP

RESTART mode is activated on a transition from STOP mode to RUN mode. Can be triggered by the --> mode selector switch or after power on, or by an operator action on the programming device. An S7–300 performs --> a restart.

STEP 7

Programming language for developing user programs for SIMATIC S7 PLCs.

Substitute Value

Substitute values are configurable values which output modules transfer to the process when the CPU switches to STOP mode.

In the event of an input access error, a substitute value can be written to the accumulator instead of the input value which could not be read (SFC 44).

System diagnostics

System diagnostics is the term used to describe the detection, evaluation and signaling of errors which occur within the programmable controller. Examples of such errors are program errors or module failures. System errors can be displayed with LED indicators or in **STEP 7**.

System function

A system function (SFC) is a -->function integrated in the operating system of the CPU that can be called, as required, in the STEP 7 user program.

System function block

A System Function Block (SFB) is a --> function block integrated in the CPU operating system. If required, it can be called in the STEP 7 user program.

System Memory

The system memory (RAM) is integrated on the central processing unit. System memory contains the operand areas (e.g. timers, counters, memory bits) and the data areas required internally by the --> operating system (e.g. buffers for communication).

System status list

The system status list contains data describing the current status of an S7300. You can use it to gain an overview of the following at any time:

- The S7300 configuration

- The current CPU configuration and the configurable signal modules

- Current status and processes in the CPU and configurable signal modules.

Timer

--> Timer

Timers

Timers are part of CPU --> system memory. The contents of the "timer cells" are updated automatically by the operating system asynchronously to the user program. **STEP 7** instructions are used to define the exact function of the timer cells (for example on-delay) and initiate their execution (e.g. start).

Time-of-day interrupt

--> Interrupt, Time-of-day

Token

Access right on bus

Transmission rate

Rate of data transfer (bps)

Terminating resistor

The terminating resistor is used to avoid reflections on data links.

User memory

User memory contains --> code and --> data blocks of the user program. The user memory can be integrated in the CPU or can be provided on plug-in memory cards or memory modules. However, user programs are always executed from --> CPU main memory.

A GD circuit is identified by a GD circuit number.

User Program

The SIMATIC system distinguishes between the --> CPU operating system and user programs. The latter are created with -->**STEP 7** programming software, using optional programming languages (LAD and STL). User programs are stored in code blocks. data is stored in data blocks.

Varistor

Voltage-independent resistor

Watchdog Interrupt

➔ Interrupt, Watchdog

Index